Errata

Title & Document Type: HP5501B Laser Head Operating & Service Manual

Manual Part Number: 05501-90035

Serial Prefixes: 2632

Revision Date: September 1986

HP References in this Manual

This manual may contain references to HP or Hewlett-Packard. Please note that Hewlett-Packard's former test and measurement, semiconductor products and chemical analysis businesses are now part of Agilent Technologies.

Changes to this Manual

No changes have been made to this manual, with the exception of correcting the odd spelling and grammatical errors. In some places original photographs may be replaced or augmented with modern digital photographs. (it's weird looking at an old BW HP manual and seeing a color photograph... still gets me)

About this Manual

This manual is reproduced from high-resolution scans of an original document, which was then converted to Word format using custom designed OCR software for my personal use.

This means that what you see here is not a scan of a scan/copy.

OCR errors may exist and as such the user of this document should take care and use common sense when referencing this documentation.

Copyright Notice

This documentation is © Copyright 1980 Hewlett Packard and © Copyright 2006, Jack Hudler, hpdocs@hudler.org.

Permission to use and redistribute this documentation for non-commercial and internal corporate purposes is hereby granted, free of charge.

Any redistribution of this documentation or its derivates must include this copyright notice.

You may not sell this documentation or its derivations without written consent.

You may modify this documentation as necessary, but you may not sell derivative works based on it.

You may include this documentation with the equipment/hardware on which it is used for the purposes of selling the equipment/hardware. If you advertise that a copy of this documentation is included in the sale, you must state that is for "Free".

Meaning if you want to gratuitously toss in a copy of the manual on an eBay sale, it's ok with me as long as you state it's for free. No you can't sell a digital archive of manuals and say it includes a free copy of this documentation. You must give it away with equipment.

I think you get the spirit of the copyright; it takes a lot of hours to scan and replicate a manual. I just want this used in the spirit in which is it given.

Agilent if you have questions or wish to include this in your archive email me.

5501B Laser Head







OPERATING AND SERVICE MANUAL

HP5501B LASER HEAD

SERIAL NUMBER PREFIX: 2632A

This manual applies directly to **HP5501B** Laser Heads with serial numbers prefixed 2632A. Lower number serial prefixes are covered in Section 7 while higher number serial prefixes are documented with "Manual Changes" Supplements described in Section 7.

© HEWLETT-PACKARD COMPANY 1986 5301 Stevens Creek Blvd., Santa Clara, CA 95051-7299 Portions © by Jack Hudler 2006 hpdocs@hudler.org

Printed: SEPTEMBER 1986

ELECTRICAL SAFETY CONSIDERATIONS

GENERAL

The product and related documentation must be reviewed for familiarization with safety markings and instructions before operation.

This product is a Safety Class I instrument (provided with a protective earth terminal).

BEFORE APPLYING POWER

Verify that the product is set to match the available line voltage and the correct fuse is installed. Refer to Section 2, Installation.

SAFETY EARTH GROUND

An uninterruptible safety earth ground must be provided from the main power source to the product input wiring terminals, power cord, or supplied power cord set.

SAFETY SYMBOLS



Instruction manual symbol: the product will be marked with this symbol when it is necessary for the user to refer to the instruction manual.



Indicates hazardous voltages.



Indicates earth (ground) terminal.



The WARNING sign denotes a hazard. It calls attention to a procedure, practice, or the like, which, if not correctly performed or adhered to, could result in personal injury. Do not proceed beyond a WARNING sign until the indicated conditions are fully understood and met.



The **CAUTION** sign denotes a hazard. It calls attention to an operating procedure, practice, or the like, which, if not correctly performed or adhered to, could result in damage to or destruction of part or the entire product. Do not continue beyond a CAUTION sign until the indicated conditions are fully understood and met.

WARNING

Any interruption of the protective (grounding) conductor (inside or outside the instrument) or disconnecting the protective earth terminal will cause a potential shock hazard that could result in personal Injury. (Grounding one conductor of a two conductor outlet is not sufficient protection).

Whenever it is likely that the protection has been impaired, the instrument must be made inoperative and be secured against any unintended operation.

If this instrument is to be energized via an autotransformer (for voltage reduction) you must make sure the common terminal is connected to the neutral (earthed pole) of the power source. Servicing instructions are for use by service-trained personnel only. To avoid dangerous electric shock, do not perform any servicing unless qualified to do so.

Adjustments described in the manual are performed with power supplied to the instrument while protective covers are removed. Energy available at many points may, if contacted, result in personal injury.

Capacitors inside the instrument may still be charged even if the instrument has been disconnected from its source of supply.

For continued protection against the fire hazard, replace the line fuse(s) only with 125V fuse(s) of the same current rating and type (for example, normal blow, time delay, etc.). Do not use repaired fuses or short circuited fuse holders.

From 1.2 kilovolts to 12 kilovolts dc is present on the anode of the laser tube in the 5501B. Exercise extreme caution when working inside the instrument. The high voltage could cause serious personal injury if contacted. Any adjustments performed should be by service trained personnel only.

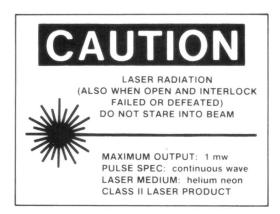
LASER HEAD SAFETY CONSIDERATIONS

CAUTION

LASER RADIATION IS EMITTED FROM THE APERTURE ON THE 5501B LASER HEAD AS ILLUSTRATED ON THE FOLLOWING PAGE. DO NOT STARE INTO BEAM. THIS PRODUCT IS A CLASS II LASER PRODUCT CONFORMING TO U.S. NATIONAL CENTER FOR DEVICES AND RADIOLOGICAL HEALTH REGULATIONS 21 CFR 1040.10 AND 1040.11. THE MAXIMUM RADIANT POWER OUTPUT IS 1 MILLIWATT, THE PULSE SPECIFICATION IS CONTINUOUS WAVE, THE LASER MEDIUM IS HELIUM-NEON, AND THE WAVELENGTH IS 632.991 NANOMETRES. LASER RADIATION IS ACCESSIBLE WHEN THE 5501B COVERS ARE REMOVED AND THE TEST-NORM SWITCH, A1S2, IS IN THE TEST POSITION.

USE OF CONTROLS OR ADJUSTMENTS OR PERFORMANCE OF PROCEDURES OTHER THAN THOSE SPECIFIED HEREIN MAY RESULT IN HAZARDOUS RADIATION EXPOSURE.

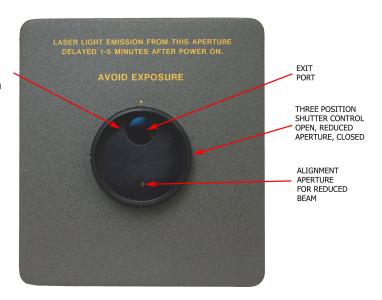
LASER HEAD SAFETY LABELS





CAUTION

Laser radiation present when exit port open and interlock failed or defeated DO NOT STARE INTO BEAM



END PRODUCT LASER SAFETY CONSIDERATIONS

The 5501B Laser Head complies with U.S. National Center for Devices and Radiological Health regulations 21 CFR 1040.10 and 1040.11.

These regulations may also apply to the end product into which the 5501B will be designed. Care must be taken to insure that the end product complies with all applicable national and local laser safety regulations.

Table of Contents

1	GENER	RAL INFORMATION	
	1-1.	Introduction	1-2
	1-4.	Equipment Description	1-2
	1-8.	Manual Organization	
	1-10.	Instruments covered by this manual	1-3
	1-14.	Safety Considerations	1-4
	1-16.	Equipment Supplied	1-4
	1-18.	Available Accessories	1-4
	1-20.	Specifications	1-5
	1-22.	Recommended Test Equipment	1-6
	1-24.	Warranty	1-6
2	INSTAL	LATION	2-1
	2-1.	Introduction	2-1
	2-3.	Unpacking, Inspection, and Reshipment	2-1
	2-5.	Unpacking and Inspection	2-1
	2-7.	Warranty Claims	2-1
	2-9.	Laser Tube Shipment	2-1
	2-11.	Tagging for Service	
	2-13.	Packaging for Reshipment	
	2-14.	Installation	
	2-16.	System Cabling	2-2
	2-19.	Power and Signal Connections	
	2-21.	Cable Fabrication	
	2-23.	Grounding Considerations	
	2-25.	Power Supply Requirements	
	2-27.	Power Dissipation	
	2-29.	Fusing	
	2-31.	Dimensions	
	2-33.	Mounting and Fixturing	
3	OPER/	ATION	
	3-1.	Introduction	
	3-4.	Power Application	
	3-6.	HP5501B Laser Head Front Panel Controls	
	3-8.	HP5501B LASER HEAD REAR PANEL INDICATORS AND CONNECTORS	
	3-10.	OPERATING MODES	
	3-12.	Warmup Time Operating Notes	
	3-13.	HP 10740A Coupler Based Systems - Manual Monitoring	
	3-14.	Systems with HP10745A or HP10746A Cards - Automatic Monitoring	
	3-16.	HP10740A Coupler - Error Signal Information	
	3-17.	HP10746A Error Signal Processing	
	3-18.	HP 10745A Background Information	
	3-19.	Program Modifications	
4		PRMÄNCE TESTS	
	4-1.	Introduction	
	4-3.	RECOMMENDED TEST EQUIPMENT	
	4-5.	TEST RECORD.	
	4-7.	HP5501B PERFORMANCE TEST	
	4-9.	Input Voltage Check	
	4-11.	Laser Power Output Test	
	4-13.	Procedure	

Table of Contents

5	ADJUS	TMENTS	5-1
	5-1.	Introduction	5-1
	5-3.	Safety Considerations	5-1
	5-5.	Recommended test equipment	5-1
	5-7.	Factory Selected Components	
	5-9.	Adjustment Procedures	
	5-11.	Reference Temperature Adjustments	
	5-14.	Preliminary Procedure	
	5-17.	Laser Tube Current Adjustment	
6		CEABLE PARTS	
٠	6-1.	Introduction	
	6-4.	Exchange Assemblies	
	6-6.	ABBREVIATIONS AND REFERENCE DESIGNATIONS	
		ORDERING INFORMATION	
	6-8.		
	6-11.	DIRECT MAIL ORDER SYSTEM	
	6-14.	Exploded View	
7		AL CHANGES	
	7-1.	Introduction	
	7-3.	Newer Instruments	
8		DE	
	8-1.	Introduction	
	8-3.	Theory of Operation	
	8-5.	Recommended Test Equipment	8-1
	8-7.	Service Aids	8-1
	8-9.	Schematic Diagram Symbols and Reference Designations	8-1
	8-12.	Safety Considerations	8-3
	8-14.	Safety Symbols	
	8-16.	Before and After Service Product Safety Checks	
	8-18.	LASER HEAD BLOCK DIAGRAM DESCRIPTION	8-5
	8-26.	Laser Tuning	
	8-29.	Warmup Mode Tuning	
	8-34.	Optical Mode Tuning	
	8-40.	Laser Assembly Optics	
	8-42.	Reference Receiver	
	8-44.	Shutter Mechanism	
	8-46.	ASSEMBLY/SCHEMATIC LOCATIONS OF HP5501B BLOCK DIAGRAM ELEMENTS	
	8-47.	REAR PANEL LED INDICATORS	
		ASSEMBLY REMOVAL INSTRUCTIONS	
	8-52.		
	8-62.	TROUBLE ISOLATION	
	8-63.	Quick Tuning Checkout Procedure	
	8-67.	Testing the Liquid Crystal Switch	
	8-70.	HP5501B Trouble Isolation Procedures	
	8-72.	Procedure	
	8-73.	A1 CONNECTOR BOARD CIRCUIT THEORY	
	8-76.	High Voltage Power Supply Switch (A1Q3 and A1Q4)	
	8-79.	Power Distribution	
	8-83.	A1 CONNECTOR BOARD TROUBLESHOOTING	
	8-85.	Rear Panel LED Operational Check	.8-27
	8-87.	A2 HIGH VOLTAGE POWER SUPPLY CIRCUIT THEORY	.8-29
	8-89.	HIGH VOLTAGE POWER SUPPLY TROUBLESHOOTING	.8-29
	8-91.	A3 CONTROLLER/REFERENCE BOARD AND A4 SAMPLER BOARD CIRCUIT THEORY	.8-32
	8-92.	Introduction	
	8-95.	Clock (A)	.8-32

Table of Contents

	8-97.	Dividers B	8-32
	8-99.	State Machine 🕞	8-33
	8-105.	Liquid Crystal D	8-34
	8-109.	Photodiode and Amplifier ©	8-34
	8-111.	Warmup Error Amplifier and Comparator ①	8-34
	8-114.	Subtracting Sample and Hold (H)	8-34
	8-118.	A1/A3 Power Amplifier ①	8-35
	8-121.	Reference Receiver ①	8-36
	8-125.	Line Driver (S	8-36
	8-127.	Power-On Reset (POR)	8-36
	8-129.	Laser Head Power ©	8-36
	8-131.	A4 Sampler Board	
	8-133.	A3 CONTROLLER/REFERENCE BOARD TROUBLESHOOTING	
	8-135.	Standard Troubleshooting Procedures	
	8-137.	Digital Troubleshooting	
	8-140.	Photodiode and Amplifier Troubleshooting	
	8-142.	Liquid Crystal Troubleshooting	8-42
	8-144.	Subtracting Sample and Hold Troubleshooting	8-42
	8-146.	Power Amplifier Troubleshooting	8-44
	8-148.	Warm-Up Error Amplifier Troubleshooting	8-46
	8-150.	Power Supply Troubleshooting	8-46
	8-152.	Reference Receiver Troubleshooting	8-47
9	SERVIO	CE NOTES	9-1
	9-1.	Service Note 5501-02A July 2001	9-1

List of Figures

Figure 1-1 HP5501B Laser Head	1-1
Figure 2-1. HP 107788 Power Cable	2-3
Figure 2-2. HP 107798 Reference Cable	2-4
Figure 2-3. Typical Transducer System Interconnections	
Figure 2-4. Interconnecting Plug Details	2-5
Figure 2-5. HP 5501B Laser Head Interconnect Wire Fabrication	2-6
Figure 2-6. Mounting Details and Physical Characteristics	
Figure 3-1. HP5501B Front Panel Controls	
Figure 3-2. HP5501B Rear Panel Connectors and Indicators	3-11
Figure 3-2. HP5501B Rear Panel Connectors and Indicators (Continued)	
Figure 4-1. HP5501B Power Connection	4-2
Figure 5-1. A 1 Connector Board, TEST-NORM Switch and Adjustment Locations	5-2
Figure 5-2. A3 Controller/Ref Board, Jumpers, Test Points, and Adjustment Locations	
Figure 5-3. 55018 High Voltage Areas and Anode Lead	5-5
Figure 6-1. HP5501B Laser Head Exploded View	6-11
Figure 8-1. Schematic Diagram Notes	8-2
Figure 8-2.HP5501B Laser Head Block Diagram	
Figure 8-3. Flow Diagram for State Machine	8-7
Figure 8-4. Feedback Loop during Warmup Mode	8-8
Figure 8-5. Warmup Mode Timing Diagram	8-9
Figure 8-6. Feedback Loop During Optical Mode	8-9
Figure 8-7. A6 Sampler Assembly, Exploded View	8-10
Figure 8-8. Liquid Crystal Timing Diagram (Optical Mode)	
Figure 8-9. Logic Clip Monitoring of Test IC U9	8-14
Figure 8-10. HP5501B Front Panel and Side Cover Removal	8-16
Figure 8-11. Factory-adjusted Sampler Mount (MP1)	8-18
Figure 8-12. Laser Tube Tuning Characteristics	8-19
Figure 8-13. Quick Tuning Check Test Setup	8-20
Figure 8-14. Quick Tuning Check Waveform Display	8-21
Figure 8-15. Liquid Crystal Removal	8-21
Figure 8-16. Liquid Crystal Test Setup	8-22
Figure 8-17. HP5501B TEST-NORM Switch A1S2	8-23
Figure 8-18. High Voltage Power Supply, Schematic Diagram	8-31
Figure 8-19. State Machine Timing Diagram	8-33
Figure 8-20. Test Point 11 Waveform (HEATER SENSE)	8-44
Figure 8-21. E-REF [U20 (Pin 9)]	
Figure 8-22. REFerence Signal Waveforms	
Figure 8-23. A1 Connector Board Component Locator	
Figure 8-23. A1 Connector Board Component Schematic Diagram	
Figure 8-23. A1 ↔ A3 Connector Pin Table	8-52
Figure 8-24. A3 Controller/Reference Board (05501-60027) and A4 Sampler Board (05501-60029)	
Schematic Diagram (Sheet 1 of 2)	8-55
Figure 8-24. A3 Controller/Reference Board (05501-60027) and A4 Sampler Board (05501-60029)	
Schematic Diagram (Sheet 2 of 2)	8-56
Figure 8-24 A3 Controller/Reference Board and A4 Sampler Board Photos & Data	57

List of Tables

Table 1-1. HP5501B Laser Head Specifications and Performance Characteristics	1-5
Table 1-2. Recommended Test Equipment	1-6
Table 2-1. Laser Head System Signal Chart	2-6
Table 2-2. HP 5501B Power Supply Requirements	2-7
Table 3-1. Proper 55018 Rear Panel LED Power-up Sequence	3-13
Table 3-1. Program Modifications for Table 4-12 in the HP5501A System Manual	3-16
Table 3-2. Program Modifications for Table 4-13 in the HP5501A System Manual	3-17
Table 3-3. Modified HP10745A HP-IB Interface Program	3-18
Table 3-4 Modified HP10746A Binary Interface Program	3-19
Table 4-1. Input Voltage	
Table 6-1. Exchange Assemblies	6-1
Table 6-2. Reference Designations and Abbreviations	6-3
Table 6-3. HP5501B Board Assemblies Replaceable Parts	6-4
Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)	6-5
Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)	6-6
Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)	6-7
Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)	6-8
Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)	6-9
Table 6-3. HP5501B Miscellaneous Chassis Parts (Continued)	6-10
Table 6-4. Manufacturer's Code List	6-12
Table 8-1. A3 U9 Test IC Signal Summary	8-13
Table 8-2. DC Unbalanced Failures	
Table 8-3. IC A3U4 and A3U6 Divider Check	8-39
Table 8-4. Signature Table	8-41
Table 8-5. Voltage Testpoints and Limits	8-46
Table 8-6. A3U17 Reference Receiver Test Voltages	8-48



Figure 1-1 HP5501B Laser Head

1 GENERAL INFORMATION

1-1. Introduction

- 1-2. This Operating and Service Manual contains information required to install, operate, test, adjust, and service the Hewlett-Packard Model 5501B Laser Head. The information in this manual is specific to the HP5501B and supplements other publications available for Hewlett-Packard Laser Transducer products. Also available is the HP5501A Laser Transducer System Manual (HP Part Number 05501-90028) that describes how to setup, align, and use the laser system to make interferometer measurements.
- 1-3. The **HP** part number of this manual is listed on the title page. Also listed is a microfiche part number for ordering 4 X 6" microfilm transparencies of this manual. The microfiche package also includes the latest "Manual Changes" supplement and any pertinent Service Notes.

1-4. Equipment Description

- 1-5. The **HP5501B** Laser Head consists of a thermally-tuned laser tube, control circuits, a reference receiver, and a high-voltage power supply. The laser head requires ±15 Volt supplies, each with a minimum capacity of 1 Amp. The **HP5501B** produces a frequency stabilized laser beam, a balanced reference output (see paragraph 16), a +15 Volt fused output, and a +5 Volt output. Diagnostic LED's, mounted on the 5501B's rear panel, provide status information on power supply input (±15 Volts), fuses, laser output and tuning, and the reference frequency output.
- 1-6. The 5501B laser beam consists of two linearly polarized and mutually perpendicular (orthogonal) components separated in frequency by approximately 1.8 MHz. The two components have light frequencies of F1 and F2. The higher frequency component (F2) is oriented parallel to the laser base, while the lower frequency component (F1) is perpendicular to the laser base. An optical receiver inside the HP5501B detects the 1.8 MHz frequency difference and places it at the rear panel REFERENCE SIGNAL connector as a balanced output (called the REFerence Frequency). The reference output is one signal used by the external electronics to measure distance traveled.
- During a typical measurement application, the laser beam travels through external optics where 1-7. the horizontal and vertical components of the beam are separated. One component travels along a fixed path and returns to an external optical receiver. The other component travels along the path (axis) to be measured and then returns to the external receiver. The external receiver detects the frequency difference between the two components and outputs a signal called the MEASure Frequency. The MEASure Frequency from the external receiver and the REFerence Frequency from the laser head are compared by external, customer selected electronics. If the distance between the external optics is fixed, the MEASure and REFerence frequencies are equal. As the relative distance between the external optics changes, the MEASure Frequency changes due to a Doppler frequency shift. This relative change between the MEASure and REFerence Frequencies is used by the system electronics to compute distance traveled. The laser transducer system can be configured for computer control of open- and closed-loop positioning and measuring applications, having single or multiple axes. For more detailed information, refer to the HP5501A Laser Transducer System manual (HP Part Number 05501-90028).

1-8. Manual Organization

- 1-9. This Service Manual is organized as follows:
- **SECTION 1, GENERAL INFORMATION**: covers Equipment Description, Manual Organization, Instruments Covered by this Manual, Safety Considerations, Equipment Supplied, Available Accessories, Specifications, Recommended Test Equipment, and Warranty Information.
- **SECTION 2, INSTALLATION**: covers Grounding Considerations, Power Requirements, Interconnecting Cabling, Operating and Storage Environments, Storage and Shipment, and Packaging.
- **SECTION 3, OPERATION**: provides operating information and covers Equipment Front and Rear Panel Features, Warm-up Time Considerations, and Program Notes.
- **SECTION 4, PERFORMANCE TESTS:** provides Safety Considerations, Performance Tests, and a Test Record.
- **SECTION 5, ADJUSTMENTS:** covers Safety Considerations, Test Equipment Required, Adjustment Procedures, and an Adjustment Record.
- **SECTION 6, REPLACEABLE PARTS:** includes Tables of Replaceable Parts including illustrated parts breakdowns of chassis and mechanical assemblies, Abbreviations, Ordering Information, and the HP Direct Mail Order System.
- **SECTION 7, MANUAL CHANGES:** describes how to update or backdate the manual for prefixes other than those listed on the title page.
- **SECTION 8, SERVICE:** contains Safety Considerations, Theory and Block Diagram Descriptions, Trouble Isolation, Troubleshooting, Schematics, and Component Locations.

1-10. Instruments covered by this manual

- 1-11. Attached to each instrument is a serial plate. The serial number is in the form: OOOOAOOOOO. It is in two parts; the first four digits and the letter are the serial number prefix and the last five digits are the suffix. The prefix is the same for all identical instruments; it changes only when a change is made to the instrument. The suffix is assigned sequentially and is unique to the individual instrument. This manual applies to instruments with the serial number prefix listed on the title page of this manual.
- 1-12. An instrument manufactured after the printing of this manual may have a serial number prefix that is not listed on the title page. This unlisted serial number prefix indicates the instrument is different from those described in this manual. The manual for this newer instrument is accompanied by a yellow "Manual Changes" supplement. This supplement contains updating information that explains how to change the manual to be applicable to newer instruments.
- 1-13. In addition to the new serial number prefix change information, the supplement may contain information for correcting errors in the manual (errata). To keep this manual as current and as accurate as possible, Hewlett-Packard recommends that you periodically request the latest "Manual Changes" supplement. The supplement for this manual is identified with the manual print date and part number, both of which appear on the manual title page. Complementary copies of the supplement are available.

1-14. Safety Considerations

1-15. The **HP5501B** Laser Head is designed to receive its power from a Safety Class 1 product. It is designed and tested in accordance with international safety standard IEC* 348. It is also a Class 1/ Laser product certified as conforming to U. S. National Center for Devices and Radiological Health Regulations 21 CFR ** 1040.10 and 1040.11. The instrument and the manual should be inspected and reviewed for safety markings and instructions before operation. A safety summary is included on the page following the title page.

1-16. Equipment Supplied

1-17. The **HP5501B** Laser Head is supplied with a test polarizer and two 4-pin connectors for use in fabricating the power and reference cables. The HP Part Numbers for the three items are:

Test Polarizer 1000-0616 Reference Signal Connector (P1) 1251-3450 Power Connector (P2) 1251-3447

1-18. Available Accessories

1-19. The HP 10778B and HP 10779B cables may be ordered from Hewlett-Packard. Figures <u>2-1</u> and 2-2 show photos of the cables, identify the connector markings, and give the pin numbers and corresponding wire color codes.

^{*}IEC, International Electrotechnical Commission

^{**}CFR, Code of Federal Regulations (U.S.A.)

1-20. Specifications

1-21. Table 1-1 lists the specifications and performance characteristics for the **HP5501B** Laser Head.

Table 1-1. HP5501B Laser Head Specifications and Performance Characteristics

Description: The **HP5501B** Laser Head contains an automatically tuned

Helium-Neon laser, circuits to control the laser, and a reference optical receiver. The laser generates a coherent, collimated, two

frequency beam of light. This is a Class II Laser Product

conforming to U.S. National Center for Devices and Radiological

Health Regulations 21 CFR 1040.10 and 1040.11.

Environmental Conditions:

Temperature (Operating): 0 to 40°C (32 to 104°F)

Temperature (Non Operating): Can be stored or shipped in environments within the range of -

40 to +75°C.

NOTE

This unit should also be protected from temperature extremes that could cause condensation within the instrument.

Relative Humidity (Operating): 0 to 95% Non-condensing **Vacuum Wavelength (Nominal):** 632.991372 nanometers

Vacuum Wavelength Accuracy: 1 X 10-7

Vacuum Wavelength Stability:2 X 10-8, typicalBeam Diameter:6 mm typicalMaximum Beam Power Output:1 milliwattMinimum Beam Power Output:120 microwattsWarm-Up Time:less than 10 minutes

Power Requirements: The **HP5501B** requires the following power inputs:

 \pm 15 Volts \pm 0.3 Volts at 0.8 Amperes maximum \pm 15 Volts \pm 0.3 Volts at 0.7 Amperes maximum

NOTE

Internal laser head 1.5 amp fuses permit power distribution to other laser equipment.

Safety Features: Front shutter to block Laser Beam.

A safety switch disables high voltage when cover is removed.

Outputs:

Reference signal: Differential square wave at approximately 1.8 MHz. Levels

compatible with all Laser Transducer System inputs.

Enclosure: NEMA Type 12
Dimensions: 32.5 X 13.2 X 12.7 cm

Weight:: 3.4 Kg (7.5 lbs)

1-22. Recommended Test Equipment

1-23. The equipment required to maintain the **HP5501B** Laser Head is listed in Table 1-2. Other equipment may be substituted if it meets or exceeds the critical specifications listed in the table.

Table 1-2. Recommended Test Equipment

INSTRUMENT	USE*	CRITICAL SPECIFICATIONS	RECOMMENDED EQUIPMENT (Equipment Having Equivalent Characteristics May Be Substituted)			
Signature Multimeter	Т	Detect TTL level signals	HP 5005A/B			
Oscilloscope	Т	100 MHz Bandwidth	HP 1740A (if available)			
Laser Power T		Range: 1 microwatt to 1 milliwatt Accuracy: ±10%	United Detector Technology Model 351L			
Clip-on Milliammeter		10 ma range accuracy ±0.1 ma	HP 428B			
Logic Pulser T		TTL level	HP 546A			
Current Tracer		Sensitivity: 1 ma to 1 amp	HP 547A			
Logic Clip	Т	TTL Compatible 16-pin IC. mounting	HP 548A			
Logic Probe	Т	TTL/CMOS Capability with Pulse	HP 545A			
Digital Voltmeter	Т	DC Volts: Floating Inputs Input Resistance: >10 MΩ Range: 1, 10, 20 Volts DC Accuracy: 0.1%	HP 3435A			
*P = Performance Test; C = Calibration; A = Adjustments; T = Troubleshooting; S = Shortened						

^{*}P = Performance Test; C = Calibration; A = Adjustments; T = Troubleshooting; S = Shortenec Performance Test

1-24. Warranty

1-25. The warranty statement for the instrument including the laser tube is located on the inside cover of this manual.

2 INSTALLATION

2-1. Introduction

2-2. This section provides installation instructions for the **HP5501B** Laser Head including unpacking, inspection and reshipment, installation, operating environment, and storage. Installation includes information on grounding considerations, power supply requirements, power dissipation, fusing, dimensions, and mounting and fixturing.

2-3. Unpacking, Inspection, and Reshipment

2-4. The following paragraphs contain information for unpacking and inspection, warranty claims, laser tube shipment, tagging for service, and packaging for reshipment.



TO AVOID HAZARDOUS ELECTRIC SHOCK, DO NOT PERFORM ELECTRICAL TESTS WHEN THERE ARE SIGNS OF SHIPPING DAMAGE TO ANY PORTION OF THE OUTER ENCLOSURE (COVERS, PANELS, CONNECTORS, LEOS, ETC.).

2-5. Unpacking and Inspection

2-6. Inspect the shipping container for damage. If the shipping container or cushioning material is damaged, it should be kept until the contents of the shipment have been checked for completeness and the instrument has been checked mechanically and electrically. Procedures for checking electrical performance are given in Section 4. If the contents are incomplete, if there is mechanical damage or defect, or if the instrument or some component fails the performance tests, notify the nearest Hewlett-Packard office. If the shipping container is damaged, or the cushioning material shows signs of stress, notify the carrier as well as the Hewlett-Packard office. Keep the shipping materials for the carrier's inspection. The HP office will arrange for repair or replacement at HP's option without waiting for a claim settlement.

2-7. Warranty Claims

2-8. Contact the nearest HP Sales and Support Office (see list at the end of this manual) for information relative to warranty claims.

2-9. Laser Tube Shipment

NOTE

The laser tube assembly MUST be shipped in an approved HP container.

2-10. The laser tube assembly (HP Part Number 05501-60102) should only be shipped in an HP container designed for that purpose. In addition, the container must indicate that the laser tube contains magnetic material. If it is necessary to ship a laser tube, contact your nearest HP Sales and Support Office for an approved container.

2-11. Tagging for Service

2-12. If the instrument is being returned to Hewlett-Packard for service, please complete one of the blue repair tags (HP Part Number 9320-3896) located at the end of this manual and attaches it to the instrument.

2-13. Packaging for Reshipment

1. Original Packaging

- a. The same containers and materials used in factory packaging can be obtained through Hewlett-Packard Sales and Support Offices listed at the rear of this manual.
- b. In any correspondence refer to the equipment by model number.

2. Other Packaging Methods

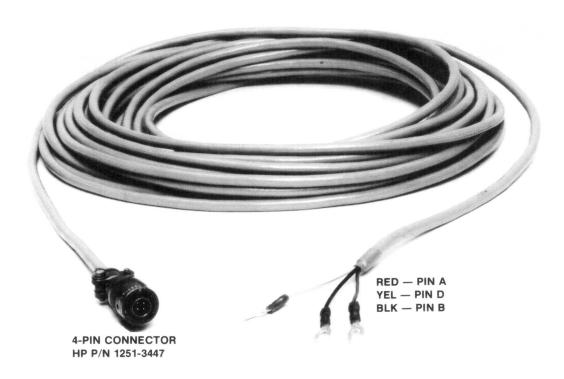
- a. If it becomes necessary to reship equipment, good commercial packing should be used.
- Contract packaging companies can provide dependable custom packaging on short notice. The following general instructions should be followed when repackaging with commercially available materials.
- c. If shipping to a Hewlett-Packard Support Office or Center, attach a blue tag indicating the type of service required, return address, and model number.
- d. Wrap the equipment in heavy paper or plastic.
- e. Use a strong shipping container. A double-wall carton made of 350 pound test material is adequate.
- f. Use enough shock-absorbing material (three to four inch layer) around all sides of the equipment to provide a firm cushion and prevent movement inside the container.
- g. Seal the shipping container securely.
- h. Mark the shipping container FRAGILE to assure careful handling.

2-14. Installation

2-15. The following paragraphs provide installation information for the **HP5501B** Laser Head including system cabling, grounding considerations, power supply requirements, power dissipation, fusing, and mounting and fixturing.

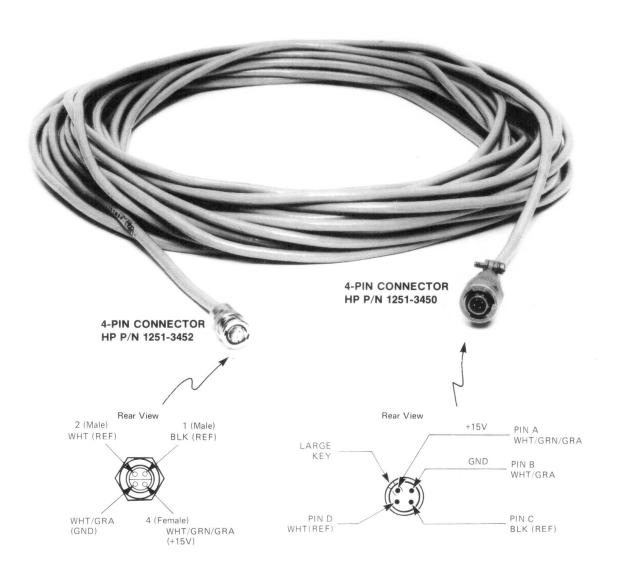
2-16. System Cabling

- 2-17. The HP5501B Laser Head is designed for use with the HP5501A Laser Transducer System and is a direct replacement for the HP5501A Laser Head. The HP10778B Power and HP10779B Reference cables (Figures 2-1 and 2-2 respectively), are available for connecting the laser head to the laser transducer system.
- 2-18. The **HP10778B** and **HP10779B** cables are both 10 Meters (32.8 ft) in length.



10778B LENGTH 10 METRES (32.8 FT)

Figure 2-1. HP 10778B Power Cable



10779B LENGTH 10 METRES (32.8 FT)

Figure 2-2. HP 10779B Reference Cable

2-19. Power and Signal Connections

2-20. The laser head rear panel contains two multi-pin connectors used for connecting **HP5501B** power and signal lines to other laser transducer system components. (Refer to Figure 2-3 for an interconnection diagram of a typical system.) Table 2-2 lists all power and signal lines that are available at the rear-panel connectors. The laser transducer system manual gives additional system wiring information.

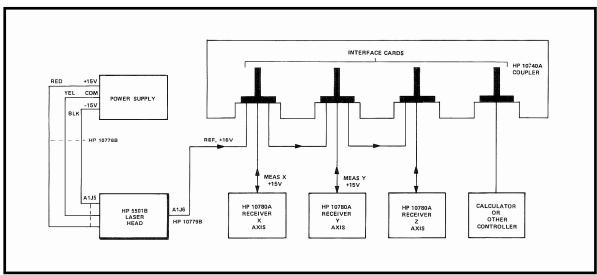


Figure 2-3. Typical Transducer System Interconnections

2-21. Cable Fabrication

2-22. Power and signal interconnecting cables of suitable length may be fabricated using the two plugs included with the laser head. Figures 2-4 and 2-5 illustrate the physical details of the two plugs supplied and give part numbers for both the plugs and the recommended cables. Refer to Table 2-1 for rear-panel connector pin numbers of all available power and signal lines.

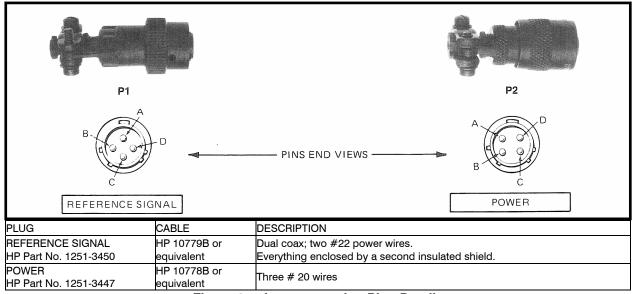


Figure 2-4. Interconnecting Plug Details

Input	Output	Signal Name	Function	Source	Destination
	A1J6-A	Fused +15V	Accessory +15V Operating Power		Accessory Equipment
	A1J6-B	Fused +15V RET	Accessory +15V Return		Accessory Equipment
	A1J6-C A1J6-D	REF -REF	System REFerence signal, equal to the difference in frequency between laser beam components F1 and F2.		Accessory Equipment
A1J5-A		+15V	External +15V Power Input	Ext. Pwr. Sup.	
A1J5-B		-15V	External -15V Power Input	Ext. Pwr. Sup	
	A1J5-C	+5V	+5V power test point		Accessory Equipment (test use only)
A1J5-D		GND	Power Ground	Ext. Pwr. Sup	

REF AND -REF OUTPUTS ARE CAPABLE OF DRIVING ONLY ONE UNIT



THE RUBBER COLLAR WHICH GOES OVER THE CABLES IS A VERY TIGHT FIT. USE SILICON GREASE TO FACILITATE INSTAILATION ON CABLE.

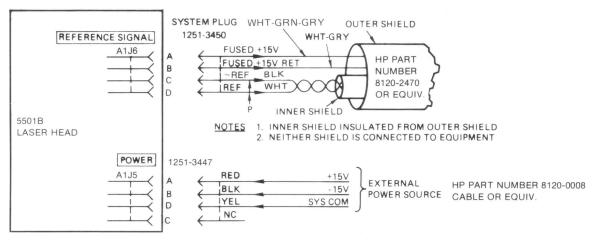


Figure 2-5. HP 5501B Laser Head Interconnect Wire Fabrication



Observe the current and grounding requirements described below.

2-23. Grounding Considerations

2-24. In order to avoid ground loops, the laser head base should be the only connection to earth ground. To accomplish this, the outputs of the ±15 Volt power supplies used to power the laser head should be floating. The +5 Volt power supply output required for either the **HP10740A** based electronics or **HP10781A** Pulse Converters, should also be floating. Alternatively, any other single point earth ground connection can be used to satisfy grounding requirements.

2-25. Power Supply Requirements

2-26. Table 2-2 lists the supply voltages, currents, and tolerances required by the **HP5501B** Laser Head. Note that other components of the system also use ±15 Volts. Add these to the laser head current requirements to obtain the overall system requirements.

Table 2-2. HP 5501B Power Supply Requirements

Supply Voltage	Tolerance	Current Requirement				
+15 Volts	±0.3 Volts	0.8 Amperes				
		3.5 Amperes peak surge for approximately 2 milliseconds at power-up				
-15 Volts	±0.3 Volts	0.7 Amperes				
	Other Power Supply Requirements					
Line I	Regulation	0.01%				
Load	Regulation	0.01%				
Rippl	e + Noise	60 millivolts peak-to-peak				
Isolat	ed Output					
Over	Voltage Protection					
(Recommended)						
Unde	r Voltage Protection					
(curre	ent limited)					
(Reco	ommended)					

2-27. Power Dissipation

2-28. The **HP5501B** dissipates approximately 21 watts during operation.

2-29. Fusing

2-30. The **HP5501B** has two internal 1.5 Ampere fuses to protect the ±15V lines. Both fuses are located on the A1 Connector Board and are accessible by removing the left and right covers of the laser head.

2-31. Dimensions

2-32. Figure 2-6 shows the **HP5501B** Laser Head dimensions.

DIMENSIONS IN MILLIMETERS

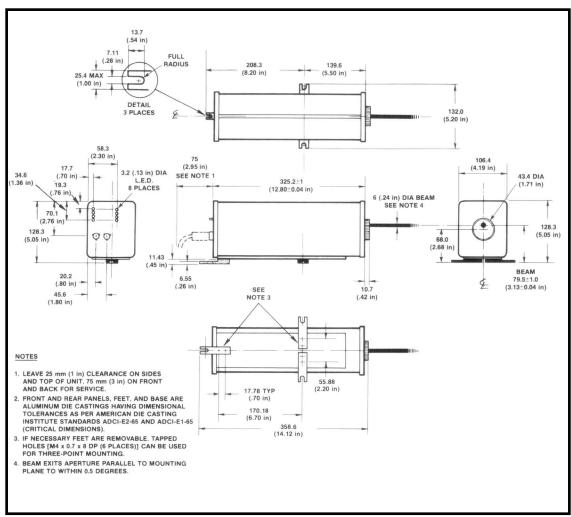


Figure 2-6. Mounting Details and Physical Characteristics

2-33. Mounting and Fixturing

- 2-34. Heat Flow Considerations. The laser tuning technique of the **HP5501B** requires efficient heat exchange with the ambient. Heat flow is primarily through the base of the laser head assembly to the surrounding environment. An external heat sink is not required but free air circulation around the laser head will ensure good performance.
- 2-35. In cases where vertical mounting of the **HP5501B** is desired, care should be taken to minimize laser beam disturbances due to air turbulence caused by the **HP5501B** heat exchange. It is most important to prevent differential effects which can occur due to turbulence in the beam path between a polarizing beam splitter and a retroreflector or plane mirror. Differential turbulence causes fluctuations in the optical path length difference that is being measured. Both differential and common mode turbulence can cause fluctuations in alignment by bending the light beam. Common mode turbulence is turbulence that is present in the beam path between the **HP5501B** and a polarizing beam splitter. In either case some amount of noise can be present in the interferometer measurement due to turbulence.
- 2-36. If interferometer components (optics) are mounted very close to the **HP5501B** such that the operating temperature of the optics are affected, it is recommended that alignment and operation of the interferometer be performed after the **HP5501B** has been running for a sufficient period of time to allow thermal equilibrium to be established. In well ventilated installations, one hour of running time should be sufficient. When enclosures are used and the ambient temperature is changed by several degrees (centigrade) by the **HP5501B**, thermal equilibrium is not established as quickly and the laser should be run for a longer period of time.
- 2-37. Mounting. Mount the laser head by means of the three slotted tabs that extend outward from the bottom edges of the unit (refer to Figure 2-1 for exact locations and dimensions). The mounting tabs may be secured to the work surface in any fashion that will not transmit stresses to the main enclosure and, consequently, to the laser tube or printed-circuit assemblies. If necessary, the tabs can be removed and the unit mounted on a flat surface with 4 mm machine screws; use the same tapped holes that are used to secure the tabs, ensuring that the mounting method does not stress the base casting and that the screws do not penetrate the base casting more than 7 mm.
- 2-38. Beam Alignment. Rotate the turret at the front of the laser head so that the beam exits through the large aperture. DO NOT STARE DIRECTLY INTO THE BEAM APERTURE. Presence of the red laser beam can be verified by placing a piece of paper in the beam path and observing the beam reflection on the paper. The components of the laser transducer system must now be aligned so that the laser beam strikes the photodetector of the receiver (HP10780A). Refer to the HP10780A Receiver documentation and the Laser Transducer System Manual for further alignment information.
- 2-39. Pointing Stability. The angle at which the laser beam exits the **HP5501B** can change from turnon through the time when the **HP5501B** and its surroundings reach thermal equilibrium.
- 2-40. The **HP5501B** should not be exposed to ambient temperature changes greater than ±5 Centigrade during operation to keep pointing stability variations to a minimum during interferometer measurements.

3 OPERATION

3-1. Introduction

- 3-2. This section provides operating information for the **HP5501B** Laser Head. Included are operation features of the instrument's front and rear panel controls and connectors. Also provided is supplemental operating information for **HP5501A** Laser Transducer Systems equipped with **HP5501B** Laser Heads.
- 3-3. Installation instructions for the HP5501B Laser Head are given in Section 2 of this manual.

3-4. Power Application

3-5. The laser head installed is activated when +15 Vdc and -15 Vdc are applied to the unit. ±15 Volts is applied by connecting the power cable (**HP10778B** or fabricated equivalent) to the rear panel POWER connector (A1J5). Ensure that the power source is adjusted to conform to the following requirements before connecting it to the **HP5501B**:

Measured Voltage $+15\text{V} \pm 0.3 \text{ Vdc} -15\text{V} \pm 0.3 \text{ Vdc}$ NOTE

REPETITIVE POWER-UP CYCLING SHOULD BE AVOIDED. THIS WILL REDUCE THE EXPECTED LIFE OF THE HIGH VOLTAGE COMPONENTS.

3-6. HP5501B Laser Head Front Panel Controls

3-7. Figure 3-1 identifies and describes each of the operating controls, connectors, and indicators. Refer to Table 2-1 for information regarding the specific power and signal/lines at each of the connectors.



Figure 3-1. HP5501B Front Panel Controls

 Shutter: The shutter, also known as the aperture ring, allows for three aperture settings: open, reduced, and closed. The open aperture position is used during normal operation and the reduced aperture is used during alignment of measurement axes.

3-8. HP5501B LASER HEAD REAR PANEL INDICATORS AND CONNECTORS NOTE

A TILDE (" \sim ") PRECEDING A SIGNAL NAME INDICATES NEGATIVE-TRUE LOGIC LEVELS.

3-9. Following are descriptions of the **HP5501B** rear panel features shown in Figure 3-2.



2. +15V SUPPLY RED UNBALANCE LED

LED lights if the ± 15 V input voltages are unbalanced in the positive direction by one Volt or more. For example:

When the positive supply measures +16 Volts (or more positive) and the negative supply remains at -15 Volts.

When the positive supply measures +15 Volts and the negative supply is -14 Volts (or less negative).

3. -15V SUPPLY RED UNBALANCE LED

LED lights if the ± 15 V input voltages are unbalanced in the negative direction by one Volt or more. For example:

When the negative supply measures -16 Volts (or more negative) and the positive supply remains at +15 Volts.

When the negative supply measures -15 Volts and the positive supply is +14 Volts (or less positive).

Both $\pm 15V$ SUPPLY UNBALANCE LED's light if the TEST-NORM switch (A1S2) is in NORM position with cover off or in TEST with cover on.

Figure 3-2. HP5501B Rear Panel Connectors and Indicators



4.	+15V FUSE OPEN	RED LED	LED lights if +15 Vdc fuse opens.
5.	-15V FUSE OPEN	RED LED	LED lights if -15 Vdc fuse opens.
6.	+15V POWER ON	GREEN LED	LED lights when +15 Vdc power is applied to the HP5501B .
7.	-15V POWER ON	GREEN LED	LED lights when -15 Vdc power is applied to the HP5501B .
8.	READY	GREEN LED	LED remains off while heating rod to normal operating temperature. At this point the READY LED begins to flash and continues to do so until the laser head reaches operating temperature. When the laser head is ready for use, the READY LED stays on steady (i.e., Laser has achieved lock and is now generating a stable reference signal).
9.	LASER ON	AMBER LED	LED lights to indicate that the high voltage power supply (HVPS) is on and that laser light is being emitted.
10.	POWER	CONNECTOR (A1J5)	Provides connection point for external power supply input (i.e., 10778B Power Cable connector).
11.	REFERENCE	CONNECTOR (A1J6)	Allows the reference signals (REF and -REF), and +15 power to be connected to other system components (i.e., 10779B Reference Cable connector).
	Figure 0.0 LIDEFOR	D. Daniel O	

Figure 3-2. HP5501B Rear Panel Connectors and Indicators (Continued)

3-10. OPERATING MODES

3-11. When power is applied to the HP5501B, an internal state machine resets the laser head to a warmup mode. This mode is used to establish the initial operating temperature of a glass rod that controls the laser cavity length. When this temperature is reached, the state machine switches to an optical tuning mode. Upon successfully switching from warmup to optical mode, the laser head enables the REFerence signal and lights a READY LED indicator on the rear panel to indicate that the laser head is ready for use. The following table will give the proper operating sequence for the HP5501B rear panel Led's from initial power-up (warmup mode) to when the laser is ready to use (optical mode).

Table 3-1. Proper 55018 Rear Panel LED Power-up Sequence

			OPERATING MODES*						
			WARMUP			OPTICAL			
LED's		PREI	HEAT	HEA ⁻ QUAL		LOC	KING	LOC	CKED
		←3-6 N	∕lin**→	← 100 s	ec →	← 50 s	sec →	Continu	ious use
+15V SUPPLY UNBALANCE (Red LED)		OFF		OFF		OFF		0	FF
-15V SUP UNBALAN (Red LED	ICE	0	FF	OF	F	OF	=F	0	FF
+15V FUSE OPEN (Red LED)		0	OFF OFF OF		F-F	0	FF		
-15V FUSE OPEN (Red LED)		0	FF	OFF		OFF		OFF	
+15V POWER ON (Green LED)		C	N	OI	N	0	N	C	ON
-15V POWER C (Green LE	-15V POWER ON		N	OI	N	0	N	C	ON
READY (Green LE	ED)	0	FF	Flashin	g 2Hz	Flas 2H	_	C	N
LASER OI (Amber Li		0	FF	OF	F	0	N	C	N
	15V Ap to Lase Head. Full Or	er Heater	Glass recently reaches temperate (begin second stabilizate)	s ature 100	HVPS on Laser E on		Refere signal prese Laser ready	nt	

^{*}Time intervals reflect that laser tube was cold at turn-on; shorter times can be expected if tube is warm at turn-on.

^{**}Refer to paragraph 8-100 for further explanation of laser operating modes.

3-12. Warmup Time Operating Notes

- Allow a full 10 minute warmup period for the **HP5501B**.
- Warmup completion is indicated by the READY LED on the HP5501B rear panel.
- If warmup is not complete after 10 minutes, a failure may be indicated.
- If the READY indication at the laser head is not convenient to use because of the mounting scheme, try the alternate monitoring suggestions that follow.

3-13. HP 10740A Coupler Based Systems - Manual Monitoring

- The REFerence and MEASurement signals terminate at either the HP10760A Counter Card or the HP10764A/B/C Fast Pulse Converter Card.
- Each of these cards includes an LED to monitor the presence of the REFerence and MEASurement signals.
- The REFERENCE LED will be extinguished until the **HP5501B** is ready for use.

HOWEVER, FOR SYSTEMS WITH MULTIPLE HP 10760A CARDS

- Every ODD HP10760A that uses the replicated REF and -REF will have their REFERENCE LED lit during the laser head warmup period. (This is due to inversion in the replication circuitry.) Note that this does not apply to multiple HP10764A/B/C card installations.
- The MEASUREMENT LED will momentarily light several times during the laser head warmup period provided that the HP10780A Receiver is aligned properly with the beam. (This occurs because the laser periodically produces functional optical frequencies during warmup.)

NOTE

The above monitoring scheme assumes no reversal of the REF and -REF lines in the cabling.

3-14. Systems with HP10745A or HP10746A Cards - Automatic Monitoring

3-15. Systems with these cards can use the system computer and software to monitor the laser head warmup. Before describing the software, it will be helpful to examine some background information on the **HP10740A** Coupler, **HP10745A** HP-IB Interface, and **HP10746A** Binary Interface.

3-16. HP10740A Coupler - Error Signal Information

- Four error signal lines are provided on the HP 10740A Backplane:
 - REFERENCE ERROR BIT
 - MEASUREMENT ERROR BIT
 - V.O.L. ERROR BIT
 - OVFL BIT

3-17. HP10746A Error Signal Processing

- If any of the **HP10740A** backplane error bits are true, the four most significant bits of the most significant word in a data transfer from the **HP10746A** to the host computer will be all ones. These four bits are normally the decimal point bits.
- Errors are not the only condition that can set these bits to all ones. When the difference output of an addressed **HP10762A** is within tolerance, these bits will also be set.
- After detecting all ones, the host computer must check the next four MSB's to differentiate between an error condition and the within tolerance condition.
- If the tolerance condition is true, these next four bits will also be all ones. Otherwise, each of these bits corresponds to one of the backplane error bits.

3-18. HP 10745A Background Information

 When a backplane error bit is true, the HP10745A asserts SRQ. The STATUS BYTE of the HP10745A can be read to determine the source of SRQ. In the STATUS BYTE, bit 0 corresponds to the REFERENCE ERROR-BIT.

3-19. Program Modifications

- 3-20. To monitor warmup time, the following program modifications can be added to the example programs contained in Tables 4-12 and 4-13 of the **HP5501A** Laser Transducer Operating and Service Manual, HP Part Number 05501-90028. If desired, some form of time-out algorithm can be added to check if the **HP5501B** warms up within 10 minutes.
- 3-21. Table 3-1 shows the program steps used to modify Table 4-12 in the **HP5501A** System Manual. The program uses the **HP10760A** x-axis card to monitor the laser warmup.
- 3-22. Table 3-2 shows the program steps used to modify Table 4-13 in the System Manual. The program is for a two axis system with the **HP10746A** in 16-bit mode and using positive-true logic. The program uses the x-axis card to monitor the laser warmup.
- 3-23. Tables 3-3, 3-4, and 3-5 are complete listings of the modified versions of Tables 4-12 and 4-13 found in the **HP5501A** System Manual.

Table 3-1. Program Modifications for Table 4-12 in the HP5501A System Manual

Branch to subroutine to monitor laser status
Send Device Clear: Send Remote Enable
Send 10740A Backplane reset preset x- axis counter and select normal resolution
Transfer x-axis counter (10760A), contents including error bits to 10745A
If SRQ false ~REFERENCE ERROR BIT must be false laser ready
Read 10745A STATUS BYTE to verify that it is asserting SRQ
If 10745A not asserting SRQ; alert operator.
Isolate ~REFERENCE ERROR BIT
If true; 5517A not READY
Try again
Otherwise, use subroutine "check" to identify remaining error
Return to step one if only ~OVF ERROR true
Alert operator that another device asserted SRQ
Return to step 0 if CONTINUE pressed

Table 3-2. Program Modifications for Table 4-13 in the HP5501A System Manual

Branch to warmup subroutine monitor laser status 0: qsb "warmup" System reset 10746A in 16 bit mode 66: "warmup":wtb 2,0,0,0 1 = simultaneous sample 130 = transfer X Comparator Counter contents to 10746A 67: wtb 2,1,130, 3 3 = prepare for output to host computer Read first word 68: rdb(2) → B; if B < 0; 65536 + B → BIf 4 MSB's are clear, 5517A is READY 69: if B<61440; ret Otherwise isolate ~REFERENCE ERROR BIT 70: int(B/256)240→B;15-B→B 71: if B>=8;B8→B 72: if B>=4;B4→B 73: if B>=2;dsp "LASER NOT READY" If ~REFERENCE ERROR BIT true, try again 74: if B>=2;sto -8 Abort transfer and setup new transfer in order to read first word again.
Use subroutine "er" to identify remaining error 75: wtb 2,1,130, 3 76: rdb(2) →B;if B<0;65536+B→B 77: gsb "er" Return to program step 1 only if ~OVL ERROR BIT is 78: ret true 79: end

Table 3-3. Modified HP10745A HP-IB Interface Program

```
0: gsb "warmup"
1: wrt 709,"006X"
2: wrt 709,"2V30"
 3: red 709,C
 4: 0→E
 5: "loop": E+1→E; if E=10;gto -3
 6: wrt709,"102X30"
7: red 709,x

8: if rds(7)<128;gto +2

9: 0-A; gsb "status"

10: (x-16)*6.23023e-6*C-X

11: fmt 1,f12.6
12: dsp X
13: gto "loop"
14: "status":rds(709)→B
15: if B>=64;gsb "check"
16: wrt 709, "OP"
17: ret
18: "check": B-112→B

19: if B>=8;gsb "ovf"

20: if B>=4; prt "VOL OUT OF RANGE";B-4→B;O→D

21: if B>=2; prt "MEAS ERROR";B-2→B;O→D
22: if B=1; prt "REF ERROR";0→D
23: if D=2; ret
24: if A=0; prt "X-AXIS ERROR"
25: if A=1; prt "Y-AXIS ERROR"
26: dsp "GO TO GAGE"; stp
27: gto 0
28: "ovf":B-8→B; 1→D
29: if A=0;X-2^28/10→X
30: if A=1;Y-2^28→Y
31: ret
32: "warmup": clr 7; rem 7
33: wrt 709,"000x"
34: wrt 709, "1x2x30"
35: if rds(7)<128;ret
36: rds(709)→B
37: if B<64;gto "bus error"
38: B-112→B
39: if B>=8;B-8→B
40: if B>=4;B-4→B
41: if B>=2:B-2→B
42: if B=1;dsp "LASER NOT READY"
43: if B=1;qto -11
44: gsb "check"
45: ret
46: "bus error":
47: prt "SRQ ASSERTED BUT 10745A STATUS BYTE, BIT6 CLEAR" 48: stp
49: gto 0
50: end
```

Table 3-4 Modified HP10746A Binary Interface Program

```
0: gsb "warmup"
1: wtb 2,0,0,0,98,3
2: gsb "in"
3: B→C
4: ent "X TOLERANCE IN MICRONS?", r1
5: ent "Y TOLERANCE IN MICRONS?", r2
6: "newdest":0→X;ent "X DESTINATION IN MM?",X
7: 0→Y;ent "Y DESTINATION IN MM?",Y
8: "comp":wtb 2,98,3
9: gsb "in"
10: B→C
11: X→A;gsb "cnv"
12: A→X
13: Y→Ajgsb "cnv"
14: A→Y
15: int(r1/1.58248e-1)*2^228+X→A
16: gsb "out"
17: wtb 2,131
18: int(r2/1.528248e-1)*2^228+Y→A
19: gsb "out"
20: wtb 2,147
21: "newsample":wtb 2,1,130,3
22: 0→F
23: gsb "in"
24: B→r3
25: wtb 2→146,3
26: I→F
27: gsb "in"
28: B→r4
29: fmt 1,2fi0.0,fi0.7
30: wrt .1,r3-160,r4-160,C
31: if abs(X-r3) \le r1/1(.158*C) and abs(Y-r4) \le r2/1(.158*C); gto "newdest"
32: gto "newsample"
33: "in":rdb(2)→B if B(0;65536+B→B
34: if B>=61440;gto "er"
35: rdb(2)→G;if G(0;65536+G→G
36: int(B/14096) →D
37: B-4096*D→B
38: (65536*B+G)*tn^{(2-D)}→B;ret
39: "cnv":A/1(1.58248e-4*C)+160→A;ret
40: "out":wtb 2,4
41: int(A/165536)→B;if B>32767;B-65536→B
42: wtb 2,B
43: A-65536*intCR/165536)→B;if B>32767;B-65536→B
44: wtb 2,B
45: ret
46: "er":int(B/1256)-240→B; 15-B→B
47: if B>=8;prt "vol error";B-8→B;0→D
48: if B>=4;B-4)B;1→D
49: if B>=2;prt "ref error";0→D
50: if B=I;prt "meas error";0→D
51: if D:0;gto "prterr"
52: rdb(2) →B
53: wtb 2,240,3
54: rdb(2)→B; if B<0;65536+B→B
55: rdb(2)→G;if G<0;65536+G→G
56: int(B/4096)→D
57: B-4096*D→B
58: (65536*B+G)*tn^(2-D)→B
59: if F=0 and B-160#0;B-2^28→B
60: if F=1 and B-160#0; B-2^28
61: ret
```

```
62: "prterr": if F=0;prt "X-AXIS ERROR"
63: if F=1;prt "Y-AXIS ERROR"
64: dsp "GO TO GAGE";stp
65: gto 0
66: "warmup":wtb 2,0,0,0
67: wtb 2,1,130,3
68: rdb(2)→B;if B<0;65536+E→B
69: if B<61440;ret
70: int(B/256)-240→B;15-B→B
71: if B>=S;B-S→B
72: if B>=4;B-4→B
73: if B>=2;dsp "LASER NOT READY"
74: if B>=2;gto -S
75: wtb 2,1,130,3
76: rdb(2)→B; if B<0;65536+B→B
77: gsb "er"
78: ret
79: end
```

4 PERFORMANCE TESTS

4-1. Introduction

4-2. This section contains a performance test for the **HP5501B** Laser Head. A test record is included to record test results for future comparison.

4-3. RECOMMENDED TEST EQUIPMENT

4-4. Test equipment requirements are included in the following procedure. Detailed critical specifications for the required test equipment are contained in Table 1-2, Recommended Test Equipment. Any equipment that satisfies the critical specifications given in the table may be substituted for the recommended model(s).

4-5. TEST RECORD

4-6. Results of the performance test may be tabulated on the test record at the end of these procedures.

4-7. HP5501B PERFORMANCE TEST

4-8. The **HP5501B** performance test consists of measuring the **HP5501B** input voltages and laser power output.

4-9. Input Voltage Check

4-10. Check the **HP5501B** voltages in the following manner:

Disconnect the POWER cable.

Measure the voltages at the disconnected cable plug as outlined in Table 4-1.

Table 4-1. Input Voltage

Plug Pin	Voltage				
A1J5 (A)	+15 ±0.3 Vdc				
A1J5 (B)	-15 ±0.3 Vdc				

4-11. Laser Power Output Test

4-12. Test Equipment Required. The following test equipment is required to test the laser output power.

Laser Power Meter, United Detector Technology (Model No. 351L)

4-13. Procedure

a. Connect the **HP5501B** to the **HP5501A** system (or any suitable dual DC voltage power supply such as the **HP6255A**) using **HP10778B** Power Cable as shown in

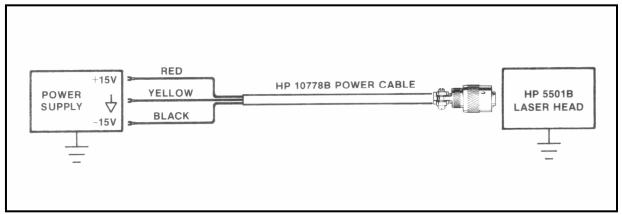


Figure 4-1. HP5501B Power Connection

- b. On the **HP5501B**, set the exit shutter of the turret assembly to its open aperture position.
- c. Turn the ± 15 Volt power supply on and wait until the READY indicator is on, not blinking. This should occur less than 10 minutes after power is applied.
- d. Using the Laser Power Meter, align the power meter detector for maximum reading.

NOTE

Laser beam must fall totally within the active region of the power meter's detector.

e. If the laser power output is less than 120 microwatts, perform the laser tube current adjustment procedure in <u>Section 5</u>.

5 ADJUSTMENTS

5-1. Introduction

5-2. This section describes adjustments and checks required to return the **HP5501B** Laser Head to peak operating capabilities when repairs have been made. Included in this section are the test equipment required, equipment setups, and procedures to perform the adjustments.

5-3. Safety Considerations

5-4. The following warnings contain information that must be understood for your safety.

WARNING

FROM 1.2 KILOVOLTS TO 12 KILOVOLTS DC IS PRESENT ON THE ANODE OF THE LASER TUBE IN THE HP5501B. EXERCISE EXTREME CAUTION WHEN WORKING INSIDE THE INSTRUMENT. THE HIGH VOLTAGE COULD CAUSE SERIOUS PERSONAL INJURY IF CONTACTED. THE FOLLOWING ADJUSTMENTS SHOULD BE PERFORMED BY SERVICETRAINED PERSONNEL.

NOTE

The High Voltage Power Supply, A2, is disconnected automatically by A1S1, when the HP5501B covers are removed. For Adjustments and Servicing purposes, the High Voltage Supply can be re-enabled by setting the TESTNORM switch, A1S2, to TEST after the HP5501B covers are removed.

WARNING

LASER RADIATION IS ACCESSIBLE WHEN THE HP5501B COVERS ARE REMOVED AND THE TEST-NORM SWITCH, A1S2, IS IN THE TEST POSITION.

5-5. Recommended test equipment

5-6. Test equipment required for each adjustment is included in the adjustment procedure. Detailed critical specifications for the required test equipment are contained in Table 1-2. Any equipment that satisfies the critical specifications given in the table may be substituted for the recommended model(s).

5-7. Factory Selected Components

5-8. As of the publication date on the title page of this manual there are no factory selected components.

5-9. Adjustment Procedures

5-10. The following paragraphs contain the adjustment procedures for the **HP5501B** Laser Head. A performance test is given in <u>Section 4</u>.

5-11. Reference Temperature Adjustments

- 5-12. This adjustment sets the laser preheat temperature to 105°C (221°F). The adjustment must be performed when the laser tube is at room temperature, 21 to 25°C (69.8 to 77.0°F).
- 5-13. Test Equipment Required. The reference temperature adjustment requires the following test equipment: Digital Voltmeter, HP Model 3435A

5-14. Preliminary Procedure

5-15. This adjustment must be made with the laser tube at room temperature. If the laser High Voltage Power Supply (A2) or heater has been on, allow at least two hours with ±15 Volts off before performing this procedure. Regardless of whether power is on or off, observe the safety precautions in paragraph 5-4 and proceed as follows:

Remove the HP5501B Laser Head covers by following the procedure outlined in paragraph 8-55.

a. Check that the TEST-NORM switch (A1S2) located on the A1 Connector Board is set to NORM. See Figure 5-1.

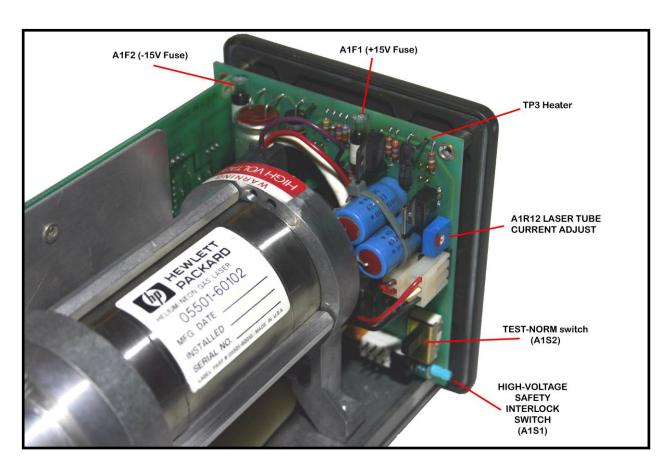


Figure 5-1. A1 Connector Board, TEST-NORM Switch and Adjustment Locations

- b. On A3, change the HEATER jumper from NRM to OFF. See Figure 5-2.
- c. Apply power to the Digital Voltmeter and set its controls to the 1 Volt DC range. Connect the positive lead of the Digital Voltmeter to A3TP11 then connect the negative lead to A3TP1. See Figure 5-2.
- d. If **HP5501B** power has been disconnected for least 2 hours, reconnect ± 15 Volts system power supplies and continue with the adjustment procedure in Paragraph 5-16.
- 5-16. Procedure to adjust the reference temperature, proceed as follows:
 - a. Check that the Voltmeter reads between +0.22V and +0.31V. This voltage is V(A3TP11).
 - b. Record value of V(A3TP11) measured in step 5-16(a).
 - c. Calculate the heater adjust set point using the following equation:
 - d. $Vset = 1.285 \times V(A3TP11)$
 - e. Connect Digital Voltmeter plus lead to A3TP15. Connect the minus lead to A3TP1. See Figure 5-2.
 - f. Check that the voltage at A3TP15 equals Vset \pm 1 millivolt as calculated in step b. If not, adjust A3R16 SET TEMP (see Figure 5-2).
 - g. Note and record the SET TEMP voltage in the "ADJUSTMENT RECORD" table located at the end of this section.
 - h. Disconnect ±15 Volts from **HP5501B** Laser Head.
 - i. On A3, change the HEATER jumper back to NRM (left-most position). Remove the test equipment leads, and reinstall the laser head covers.

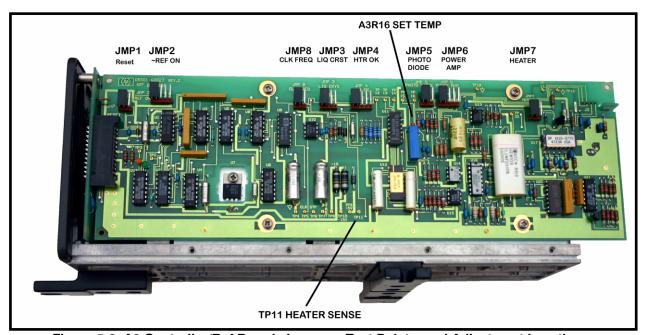


Figure 5-2. A3 Controller/Ref Board, Jumpers, Test Points, and Adjustment Locations

5-17. Laser Tube Current Adjustment

NOTE

A TILDE (" \sim ") PRECEDING A SIGNAL NAME INDICATES NEGATIVE-TRUE LOGIC LEVELS.

5-18. This procedure adjusts the laser tube current to 3.5 milliamperes \pm 0.1 milliampere.

Test Equipment Required. The laser current adjustment requires the following test equipment:

Clip-On DC Milliammeter, HP Model 428B

- 5-19. Procedure to adjust the laser tube current, observe the safety precautions in Paragraph 5-4 and proceed as follows:
 - a. Turn the system power supplies OFF.
 - b. Remove the laser head covers by following the procedures outlined in paragraph 8-55.
 - c. On the A1 Connector Board, set TEST-NORM (A1S2) switch to TEST. See Figure 5-1.
 - d. Set indicated jumpers to the following positions:

1.	JMP2 (~REF ON)	.LO
2.	JMP4 (HTR OK)	.HI
3.	JMP7 (HEATER)	.OFF
4.	JMP8 (CLK FREQ)	.HI

NOTE

Setting the A3 jumpers causes the laser to come on soon after power is applied.

- e. Set the milliammeter to the 10 milliampere range.
- f. Clip the HP428B probe around the red (Anode) High Voltage Power Supply wire located underneath the laser tube (See Figure 5-3). The arrow on the milliammeter probe should point away from the supply. Keep the probe as far as possible from and perpendicular to the magnet assemblies. It may be necessary to prop up the probe to achieve the perpendicular orientation.
- g. On the milliammeter, adjust for zero indication. If zero indication cannot be obtained, degauss the probe as directed on the back of the milliammeter.

NOTE

After the zero setting has been made on the milliammeter, do not move the probe, this will affect the zero setting.

h. Apply power to the system power supplies.

NOTE

READY LED will flash rapidly for about 5 seconds. LASER LED illuminates followed almost immediately by emission of laser light.

- i. Adjust A1R12 (Figure 5-1) for 3.5 milliamperes \pm 0.1 milliampere. If the current cannot be adjusted to this value, see Laser High Voltage Troubleshooting in Section 8. If the laser power output (as measured in paragraph 4-9) is not greater than 120 microwatts (at this current level), the laser assembly may require replacement.
- j. Record the laser tube current in the "ADJUSTMENT RECORD" located at the end of this section.
- k. Turn off the system power supplies, disconnect the probe, set the TEST-NORM switch to NORM, and reinstall the laser head covers.
- I. Return all A3 jumpers, moved in step 5-20(d), back to NRM position (left-most position).

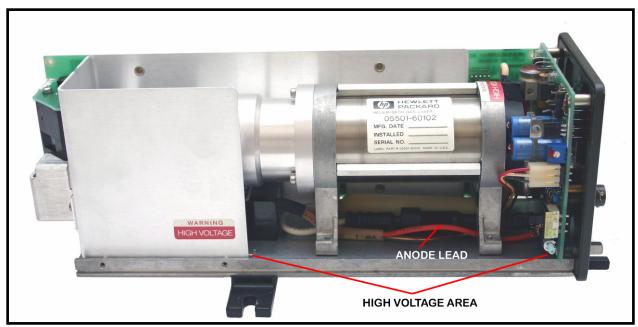


Figure 5-3. 55018 High Voltage Areas and Anode Lead

6 REPLACEABLE PARTS

6-1. Introduction

- 6-2. This section contains information for ordering replacement parts. Part numbers for replacement parts are provided in either illustrated parts breakdown or tabulated listings depending on the type of part. Purchase Order and Direct Mail Order information are provided in Paragraphs 6-9 through 6-13.
- 6-3. Table 6-1 is a list of exchange assemblies and Table 6-2 gives abbreviations and reference designators used in the parts lists and throughout the manual. Table 6-3 lists replaceable parts that are mounted on pc board assemblies. Table 6-4 contains the names and addresses that correspond to the manufacturer's code numbers given in Table 6-3. Figure 6-1 shows illustrated parts breakdowns showing the chassis mounted parts and assemblies for the **HP5501B**.

6-4. Exchange Assemblies

6-5. Table 6-1 lists assemblies within the **HP5501B** Laser Head that may be replaced on an exchange basis. Factory repaired and tested exchange assemblies are available on a trade-in basis; therefore the defective assemblies must be returned for credit. For this reason, assemblies required for on-site spare parts stock must be ordered by the "New Assembly" part number.

Table 6-1. Exchange Assemblies

Assembly	HP Part No.	New Assembly HP Part No.	Exchange Assembly HP Part No.
Laser Assembly	05501-60102	05501-60202	05501-69102

6-6. ABBREVIATIONS AND REFERENCE DESIGNATIONS

6-7. Table 6-2 lists abbreviations used in the parts list, the schematics and throughout the manual. In some cases, two forms of the abbreviations are used, one in all capital letters, and one partial or no capital letters. This occurs because the abbreviations in the parts list are always all capital letters. However, in the schematics and the other parts of the manual, other abbreviation forms are used with both upper and lower case letters.

6-8. ORDERING INFORMATION

- 6-9. To order a part listed in the replaceable parts tables or figures, then quote the Hewlett-Packard part number, indicate the quantity required, and address the order to the nearest Hewlett-Packard office.
- 6-10. To order a part that is not listed in this section, include the instrument model number, instrument serial number, the description and function of the part, and the number of parts required. Address the order to the nearest Hewlett-Packard office.

6-11. DIRECT MAIL ORDER SYSTEM

- 6-12. Within the USA, Hewlett-Packard can supply parts through a direct mail order system. Advantages of using the system are as follows:
 - a. Direct ordering and shipment from the HP Parts Center in Mountain View, California.
 - b. No maximum or minimum on any mail order (there is a minimum order amount for parts ordered through a local HP office when the orders require billing and invoicing).
 - c. Prepaid transportation (there is a small handling charge for each order).
 - d. No invoices to provide these advantages, a check or money order must accompany each order.
- 6-13. Mail order forms and specific ordering information are available through your local HP office. Addresses and phone numbers are located at the back of this manual.

Table 6-2. Reference Designations and Abbreviations

REFERENCE DESIGNATIONS

			NEFENENCE I				
A	= assembly	F.	= fuse	MP	= miscellaneous mechanical part	TC	= thermocouple
AT	= attenuator; isolator; termination	FL	= filter	Р	= electrical connector (movable	TP	= test point
В	= fan; motor	Н	= hardware		portion); plug	U	= integrated circuit; microcircuit
BT	= battery	HY	= circulator	Q	= transistor: SCR, triode, thyristor	V	= electron tube
C	= capacitor	J	= electrical connector (stationary	R	= resistor	VR	= voltage regulator; breakdown
CP	= coupler		portion); jack	RT	= thermistor		diode
CR	= diode: diode thyristor; varactor	DL	= delay line	S	= switch	W	cable; transmission path; wire
DC	= directional coupler	DS	= annunciator; signaling device	T	= transformer	X	= socket
DL	= delay line		(audible or visual); lamp; LED	TB	= terminal board	Υ	= crystal unit-piezo-electric
DS	 annunciator; signaling device 	K	= relay	TC	= thermocouple	Z	tuned cavity; tuned circuit
	(audible or visual); lamp; LED	L	= coil; inductor	T	= transformer		
E	 miscellaneous electrical part 	M	= meter	TB	= terminal board		
			ABBRE\	/IATION	10		
			ADDNE	VIATION	13		
Α	= ampere	h	= hour	NOM	= nominal	μV	= microvolt
ac	 alternating current 	HET	= heterodyne	NORM	= normal	μVac	= microvolt, ac
ACCESS	= accessory	HEX	= hexagonal	NPN	= negative-positive-negative	μVdc	= microvolt, dc
ADJ	= adjustment	HD	= head	NPO	= negative-positive zero (zero	μVpk	= microvolt, peak
AID	= analog-to-digital	HOW	= hardware		temperature coefficient)	μp-p	= microvolt, peak-to-peak
AF	= audio frequency	HF	= high frequency	NRFR	= not recommended for field	μVrms	= microvolt, rms
AFC	= automatic frequency control	HG	= mercury		replacement	μW	= microwatt
AGC	= automatic gain control	HI	= high	ns	= nanosecond	nA	= nanoampere
AL	= aluminum	HP	= Hewlett-Packard	NSR	= not separately replaceable	NC	= no connection
ALC	= automatic level control	HPF	= high pass filter	nW	= nanowatt	N/C	= normally closed
AM	= amplitude modulation	HR	= hour (used in parts list)	OBD	= order by description	SPST	= single-pole, single-throw
AMPL	= amplifier	HV	= high voltage	OD	= outside diameter	SSB	= single sideband
APC	= automatic phase control	Hz	= hertz	OH	= oval head	SST	= stainless steel
ASSY	= assembly	IC	= integrated circuit	OP AMPL	= operational amplifier	STL	= steel
AUX	= auxiliary	ID	= inside diameter	OPT	= option	SQ	= square
AVG	= average	IF	= intermediate frequency	OSC	= oscillator	SWR	= standing-wave ratio
AWG	= American wire gauge	 IMPG	= impregnated	OX	= oxide	SYNC	= synchronize
BAL	= balance	in	= inch	OZ OZ	= ounce	T	= timed (slow-blow fuse)
BCD	= binary coded decimal	INCD	= incandescent	Ω	= ohm	TA	= tantalum
BO	= board	INCL	= include(s)	P	= peak (used in parts list)	TC	= temperature compensating
BE CU	= beryllium copper	INP	= input	PAM	= pulse-amplitude modulation	TO	= time delay
BFO					= pulse-amplitude modulation = printed circuit	TERM	
	= beat frequency oscillator	INS	= insulation	PC			= terminal
BH	= binder head	INT	= internal	PCM	= pulse-code modulation; pulse-	TFT	= thin-film transistor
BKDN	= breakdown	kg	= kilogram	DD14	count modulation	TGL	= toggle
BP	= bandpass	kHz	= kilohertz	PDM	= pulse-duration modulation	THO	= thread
BPF	= bandpass filter	kΩ	= kilohm	pF	= picofarad	THRU	= through
BRS	= brass	kV	= kilovolt	PH BAZ	= phosphor bronze	TI	= titanium
BWO	= backward-wave oscillator	lb	= pound	PHL	= phillips	TOL	= tolerance
CAL	= calibrate	LC	= inductance-capacitance	PIN	= positive-intrinsic-negative	TRIM	= trimmer
CCW	= counterclockwise	LED	= light-emitting diode	PIV	= peak inverse voltage	TSTR	= transistor
CER	= ceramic	LF	= low frequency	pk	= peak	TTL	= transistor-transistor logic
CHAN	= channel	LG	= long	PL	= phase lock	TV	= television
cm	= centimeter	LH	= left hand	PLO	= phase lock oscillator	TVI	= television interference
CMO	= coaxial	UM	= limit	PM	= phase modulation	TWT	= traveling wave tube
COEF	= coefficient	UN	 linear taper (used in parts list) 	PNP	= positive-negative-positive	U	= micro (10-6 used in parts list)
COM	= common	lin	= linear	P/O	= part of	UF	 microfarad (used in parts list)
COMP	= composition	LK WASH	= lockwasher	POLY	= polystyrene	UHF	 ultrahigh frequency
COMPL	= complete	LO	= low; local oscillator	PORC	= porcelain	UNREG	= unregulated
CONN	= connector	LOG	= logarithmic taper (used in parts	POS	= positive; position(s) (used in	V	= volt
CP	= cadmium plate		list)		parts list)	VA	= voltampere
CRT	= cathode-ray tube	log	= logarithm(ic)	POSN	= position	Vac	= volts ac
CTL	= complementary transistor logic	LPF	= low pass filter	POT	= potentiometer	VAR	= variable
CW	= continuous wave	LV	= low voltage	р-р	= peak-to-peak	VCO	= voltage-controlled oscillator
cw	= clockwise	m	= meter (distance)	PP	= peak-to-peak (used in parts list)	Vdc	= volts dc
O/A	= digital-to-analog	mA	= milliampere	PPM	= pulse-position modulation	VDCW	= volts, dc, working (used in parts
dB	= decibel	MAX	= maximum	PREAMPL	= preamplifier		list)
dBm	= decibel referred to 1 mW	ΜΩ	= megohm	PRF	= pulse-repetition frequency	V(F)	= volts, filtered
dc	= direct current	MEG	= meg (106) (used in parts list)	PRR	= pulse repetition rate	VFO	= variable-frequency oscillator
deg	= degree (temperature interval or	MET FLM	= metal film	ps	= picosecond	VHF	= very-high frequency
9	difference	MET OX	= metal oxide	PT			
•••°	= degree (plane angle)	MF			= point	Vpk	
°C	= degree Celsius (centigrade)		= medium frequency: microfarad		= point = pulse-time modulation	Vpk Vp-p	= volts peak
°F		IVII	= medium frequency; microfarad (used in parts list)	PTM	= pulse-time modulation	Vp-p	= volts peak = volts peak-to-peak
			(used in parts list)	PTM PWM	pulse-time modulationpulse-width modulation	Vp-p Vrms	= volts peak = volts peak-to-peak = volts rms
°K	= degree Fahrenheit	MFR	(used in parts list) = manufacturer	PTM PWM PWV	 pulse-time modulation pulse-width modulation peak working voltage 	Vp-p Vrms VSWR	= volts peak = volts peak-to-peak = volts rms = voltage standing wave ratio
°K OEPC	= degree Fahrenheit = degree Kelvin	MFR mg	(used in parts list) = manufacturer = milligram	PTM PWM PWV RC	 pulse-time modulation pulse-width modulation peak working voltage resistance capacitance 	Vp-p Vrms VSWR VTO	= volts peak = volts peak-to-peak = volts rms = voltage standing wave ratio = voltage-tuned oscillator
OEPC	degree Fahrenheitdegree Kelvindeposited carbon	MFR mg MHz	(used in parts list) = manufacturer = milligram = megahertz	PTM PWM PWV RC RECT	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier	Vp-p Vrms VSWR VTO VTVM	= volts peak = volts peak-to-peak = volts rms = voltage standing wave ratio
OEPC OET	= degree Fahrenheit = degree Kelvin = deposited carbon = detector	MFR mg MHz mH	(used in parts list) = manufacturer = milligram = megahertz = millihenry	PTM PWM PWV RC RECT REF	pulse-time modulation pulse-width modulation peak working voltage resistance capacitance rectifier reference	Vp-p Vrms VSWR VTO	= volts peak = volts peak-to-peak = volts rms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched
OEPC OET diam	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter	MFR mg MHz mH mho	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance	PTM PWM PWV RC RECT REF REG	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated	Vp-p Vrms VSWR VTO VTVM V(X)	= volts peak = volts peak-to-peak = volts rms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt
OEPC OET diam OIA	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list)	MFR mg MHz mH mho MIN	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum	PTM PWM PWV RC RECT REF REG REPL	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable	Vp-p Vrms VSWR VTO VTVM V(X) W	= volts peak = volts peak-to-peak = volts rms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with
OEPC OET diam OIA OIFF AMPL	degree Fahrenheit degree Kelvin deposited carbon detector diameter diameter diameter (used in parts list) differential amplifier	MFR mg MHz mH mho	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time)	PTM PWM PWV RC RECT REF REG REPL RF	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency	Vp-p Vrms VSWR VTO VTVM V(X) W W/ WIV	= volts peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage
OEPC OET diam OIA OIFF AMPL div	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division	MFR mg MHz mH mho MIN min	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle)	PTM PWM PWV RC RECT REF REG REPL RF	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference	Vp-p Vrms VSWR VTO VTVM V(X) W W/ WIV WIV	= volts peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound
OEPC OET diam OIA OIFF AMPL div DPDT	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = dioxision = double-pole, double-throw	MFR mg MHz mH mho MIN min	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = miniature	PTM PWM PWV RC RECT REF REG REPL RF RFI RH	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = restifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand	Vp-p Vrms VSWR VTO VTVM V(X) W W/ WIV WWV W/O	= volts peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without
OEPC OET diam OIA OIFF AMPL div DPDT DR	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive	MFR mg MHz mH mho MIN min •••• MINAT mm	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = minuture = millimeter	PTM PWM PWV RC RECT REF REG REPL RF	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-	Vp-p Vrms VSWR VTO VTVM V(X) W W/ WIV WW/ WIV WWO YIG	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB	= degree Fahrenheit = degree Kelvin = deposited darbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband	MFR mg MHz mH mho MIN min ••• MINAT mm MOD	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = millimeter = millimeter = modulator	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RLC	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = restifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance	Vp-p Vrms VSWR VTO VTVM V(X) W W/ WIV WWV W/O	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL	degree Fahrenheit degree Kelvin deposited carbon detector diameter diameter (used in parts list) differential amplifier division double-pole, double-throw drive double sideband dide transistor logic	MFR mg MHz mH mho MIN min •••• MINAT mm MOD MOD	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = miniture = millimeter = modulator = momentary	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RLC RMO	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance- capacitance = rack mount only	Vp-p Vrms VSWR VTO VTVM V(X) W W/ WIV WIV WW W/O YIG Zo	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS	(used in parts list) = manufacturer = milligram = megahertz = milliherry = conductance = minimum = minute (time) = minute (plane angle) = miniature = miniature = modulator = momentary = metal-oxide semiconductor	PTM PWM PWV RC RECT REF REG REPL RF RF RFI RH RH RH RLC RMO rms	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square	Vp-p Vrms VSWR VTO VTVM V(X) W W/WIV WWV WWV WWW W/O YIG Zo	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (plane angle) = minute (plane angle) = miniture = millimeter = modulator = modulator = momentary = metal-oxide semiconductor = millisecond	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RLC RMO rms RND	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WW W/O YIG Zo All abbreviation case.	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE sin the parts list will be in upper
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromotive force	MFR mg MHz mH mho MIN min MINAT mm MOD MOS ms MTG	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (plane angle) = minute (plane angle) = minuter = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RLC RMO rms RMD ROM	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory	VP-P Vrms VSWR VTO VTVM V(X) W/ WIV WW W/O YIG Zo All abbreviation case.	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing	MFR mg MHz mH mho MIN min •••• MINAT mm MOD MOM MOS ms MTG MTR	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = miniture = millimeter = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device)	PTM PWM PWV RC RECT REF REGREPL RF RFI RH RLC RMO RMS RND ROM R&P	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = restifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel	VP-P Vrms VSWR VTO VTVM V(X) W/ WIV WW W/O YIG Zo All abbreviation case.	= volts peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE ns in the parts list will be in upper
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = deuter deuter deuter deuter deuter coupled logic = electromotive force = electronic data processing = electrolytic	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mV	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (plane angle) = minute (plane angle) = miniture = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivetor	PTM PWW PWV RC RECT REF REG REPL RF RFI RH RH RH RLC RMO rms RND ROM RAP RWV	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ W/ W/ W/ W/ All abbreviation case. M Abbreviation	= volts peak = volts peak-to-peak = volts peak-to-peak = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper
OEPC OET diam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double-pole, double-throw = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromotive force = electronitic data processing = electrolytic = encapsulated	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mV	(used in parts list) = manufacturer = milligram = megahertz = millinenry = conductance = minimum = minute (time) = minute (plane angle) = miniature = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt = millivolt, ac	PTM PWM PWV RC RECT REF REG REPL RF RFI RH RLC RMO RMO RMO R&P RWV S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WIV V/O Zo All abbreviation Case. M Abbreviation	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage standing vave ratio = vacuum-tube voltmeter = volts, switched = watt = with = with = wirding inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE ns in the parts list will be in upper
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing = electrolytic = encapsulated = external	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mV mVac	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minute (plane angle) = minute (plane angle) = minuter = millimeter = millimeter = modulator = modulator = modulator = metal-oxide semiconductor = millivott = millivott = millivott, dc	PTM PWW PWV RC RECT REF REG REPL RF RFI RH RH RH RLC RMO rms RND ROM RAP RWV	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time)	VP-P Vrms VSWR VTO VTVM V(X) W W/W WIV WW W/O YIG Zo All abbreviation case. M Abbreviation T	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = wait = with = with = withing inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper **IULTIPLIERS Prefix Multiple tera 1012 giga 108
OEPC OET diam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromotive force = electronytic = encapsulated = external = farad	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mV mVac mVac	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minature = millimeter = modulator = modulator = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, ac = millivolt, peak	PTM PWM PWV RC RECT REF REG REPL RF RFI RH RLC RMO rms RNDD ROM R&P RWV S s ****	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (oplane angle)	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WW W/O YIG Zo All abbreviation case. M Abbreviation T G M	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE Is in the parts list will be in upper ### MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EAT EXT F FET	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double-sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromotive force = electrolic data processing = electrolic exercision = exercision = exercision = field-effect transistor	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTG mVac mVac mVp-p	(used in parts list) = manufacturer = milligram = megahertz = millienry = conductance = minimum = minute (time) = minute (plane angle) = miniature = millimeter = millimeter = modulator = modulator = modulator = momentary = metal-oxide semiconductor = millivolt = millivolt = millivolt, dc = millivolt, peak	PTM PWM PWW RC RECT REF REGREPL RF RFI RH RLC RMO rms RND RND RWV S S S S-B	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list)	VP-P Vms VSWR VTO VTVM V(X) W W/ WIV WIV V/O JCO All abbreviation case. M Abbreviation T G M k	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witnum-inon-garnet = characteristic impedance NOTE sin the parts list will be in upper **IULTIPLIERS** Prefix Multiple tera 1012 giga 108 mega 106 kilo 103
OEPC OET diam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELLECT EN CAP EXT F FET FFF	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = mitter coupled logic = electromitive force = electromity force = electronic data processing = electrolytic = encapsulated = external = farad = field-effect transistor = flip-flop	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTG MTR mV mVac mVpk mVpk mVpp mVms	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minute (plane angle) = minute (plane angle) = minute (minute = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, dc = millivolt, dc = millivolt, dc = millivolt, peak = millivolt, ms	PTM PWW PWV RC RECT REF REG REPL RF RIC RIN RIC RMO RMS RND ROM R&P RWV S S S SCR	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = slicon controlled rectifier; screw	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ W/ W/ W/ W/ All abbreviation case. M Abbreviation T G M k da	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper VILTIPLIERS VILTIPLIERS
OEPC OET diam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT F F FET F/F FH	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromotive force = electronitic data processing = electrolytic = encapsulated = external = farad = field-effect transistor = ligi-flop = flat head	MFR mg MHz mH mho MIN min ••• MINAT mm MOD MOM MOS ms MTG MTG mVpc mVpc mVpc mVpc mVpc mWy-p mVms mW	(used in parts list) = manufacturer = milligram = megahertz = millienry = conductance = minimum = minute (time) = minute (plane angle) = miniture = millimeter = millimeter = modulator = modulator = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, dc = millivolt, peak	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RLC RMO RMO RMP RWV S S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (olpane angle) = slow-blow fuse (used in parts list) = silicon controlled rectifier; screw = selenium	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WIV Zo All abbreviation case. M Abbreviation T G M k da d	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE ns in the parts list will be in upper ##################################
OEPC OET Giam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF ECD ELECT EN CAP EXT F FET FFF FH FOL H	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing = electrolytic = encapsulated = external = farad = field-effect transistor = fiij-flop = lat head = fillister head	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mV mVac mVdc mVdc mVdc mVdc mVdc mVdc mVdc mVd	(used in parts list) = manufacturer = milligram = megahertz = millimenry = conductance = minute (plane angle) = minute (plane angle) = minuter = millimeter = millimeter = modulator = modulator = modulator = modulator = motilimeter (indicating device) = millivolt = millivolt = millivolt, dc = millivolt, dc = millivolt, peak = millivolt, peak = millivolt, ms = millivolt, ms = millivolt, ms = millivolt, ms	PTM PWM PWV RC RECT REF REG REPL RF RIG RH RIC RMO rms RNO RAP RWV S S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (plane angle) = slow-blow fuse (used in parts list) = silicon controlled rectifier; screw = selenium = sections	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ W/ V/ VIG Zo All abbreviation Case. M Abbreviation T G M k da d c	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2
OEPC OET diam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT F FET F/F FH FOL H FM	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electronotive force = electronic data processing = electrolic descending = enapsulated = external = farad = field-effect transistor = filip-flop = flat head = filister head = frequency modulation	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mVac mVac mVac mVac mVp-p mVrms mW MUX MY	(used in parts list) = manufacturer = milligram = megahertz = millimory = conductance = minimum = minute (time) = miniture = millimeter = midlimeter = modulator = modulator = modulator = modulator = modulator = millisecond = mounting = meter (indicating device) = millivolt = millivolt, ac = millivolt, peak = millivolt = multiplex = mylar	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RLC RMO rms RND ROM R&P RWV S S S S S SCR SCR SEMICON	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (oplane angle) = slicon controlled rectifier; screw = selenium = sections = semiconductor	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/W W/V W/O Zo All abbreviation case. M Abbreviation T G M k da d c m	= volts peak volts peak volts peak-to-peak voltage standing wave ratio voltage-tuned oscillator voltage-tuned oscillator voltage-tuned oscillator voltage-tuned voltmeter volts, switched with with with without ythrium-iron-garnet characteristic impedance NOTE sin the parts list will be in upper
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT F FET FFF FH FH FM FP	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drouble sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing = electronic data processing = electrolitic = encapsulated = artard = farad = field-effect transistor = fiipf-flop = flat head = flillster head = frequency modulation = front panel	MFR mg MHz mH mho MIN min III MOD MOM MOS ms MTG MTR mV mVac mVdc mVpcp mVms mW MUX MY MUX MY MA	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (plane angle) = miniture = millimeter = millimeter = modulator = modulator = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt = millivolt, dc = millivolt, peak = millivolt, peak-to-peak = millivolt, peak = millivolt, peak = millivolt, peak = millivolt, peak = millivolt, ms = millivolt, ms = millivolt, ms = millivolt = m	PTM PWM PWW PWV RC REGT REF REGREPL RF RFI RH RLC RMO RMS RND RND R&P RWV S S S S-B SCR SE SECT SEMICON SHF	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (plane angle) = slow-blow fuse (used in parts list) = silicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WIV V/O Zo All abbreviation case. M Abbreviation T G M k da d c m µ	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = with = witning inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE sin the parts list will be in upper **IULTIPLIERS** Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6
OEPC OET diam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELLECT EN CAP EXT F FFF FH FOL H FM FP FREQ	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromotive force = electromic data processing = electrolytic = encapsulated = external = farad = field-effect transistor = flip-flop = flat head = frequency modulation = front panel = frequency	MFR mg MHz mH mho MIN min **** MINAT mm MOD MOM MOS ms MTG MTG MTR mV mVac mVpk mVpk mVpp mVmp mVmW MUX MY	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minute (plane angle) = minute (plane angle) = minute (minute = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, ac = millivolt, dc = millivolt, dc = millivolt, ms = millivolt, ms = millivolt = millivolt, ms = millivolt = mill	PTM PWM PWW RC RECT REF REG REPL RF RRI RH RLC RMO RMS RND ROM RAP RWW S S S S SCR SE SEMICON SHF	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = slow-blow fuse (used in parts list) = slicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency = silicon = superhigh frequency = silicon	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ W/ V/ S Zo All abbreviation case. M Abbreviation T G M k da d c m µ n	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = yttrium-iron-garnet = characteristic impedance NOTE sin the parts list will be in upper ### Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6 nano 10-9
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECH EMF EOP ELECT EN CAP EXT F FET FF FH FOL H FM FP FREQ FXD	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = diwision = double-pole, double-throw = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electronitive force = electronitive force = electronitive force = electronitive force = field-effect transistor = figi-flop = flat head = fillister head = frequency modulation = frougency = fixed	MFR mg MHz mH mho MIN min IIII MOD MOM MOS ms MTG MTG MTG mVdc mVp-p mVrms mW MUX MY	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = miniture = millimeter = millimeter = modulator = modulator = modulator = modulator = moterial esemiconductor = millisecond = mounting = meter (indicating device) = millivolt = millivolt, ac = millivolt, peak = millivolt, peak = millivolt, peak = millivolt, ms = millivolt, ms = millivolt = multiplex = mylar = microampere = microfarad = microfarad = microferad = microferad = microferad = microferad	PTM PWM PWW PWV RC RECT REF REG REPL RF RFI RH RLC RMO RMN RWV S S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list) = silicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency = silicon = silver	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WIV V/O Zo All abbreviation case. M Abbreviation T G M k da d c m µ n p	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE ns in the parts list will be in upper **NOTE** **IDULTIPLIERS** Prefix Multiple tera 1012 giga 108 mega 108 mega 108 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 miloro 10-6 nano 10-9 pico 10-12
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELLECT EN CAP EXT F FET F/F FH FOL H FM FP FREQ FXD 9	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double-bole, double-throw = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing = electrolytic = encapsulated = external = farad = field-effect transistor = filip-flop = fill thead = frequency modulation = frequency = fixed = gram	MFR mg MHz mH mho MIN min MINAT mm MOD MOM MOS ms MTG MTR mV mVac mVdc mVdc mVdc mVdc mVdc mVdc mVdc mVd	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minute (plane angle) = minute (plane angle) = minuter = millimeter = millimeter = midlimeter = modulator = modulator = modulator = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, dc = millivolt, peak = millivolt, peak = millivolt, ms = millivatt = multiplex = mylar = microampere = microfarad = microfarad = microhenry = micromho	PTM PWM PWW RC RECT REF REG REPL RF RIG RH RH RH RLC RMO rms RND ROM R&P RWV S S S SCR SE SECT SEMICON SHF SI SIL SL	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = restifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list) = selenium = sections = semiconductor = superhigh frequency = silicon = siliver = slide	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ V/O YIG Zo All abbreviation case. M Abbreviation T G G M k da d c m µ n p f	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6 nano 10-9 pico 10-12 femto 10-15
OEPC OET Giam OIA OIFFAMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT F FET F/F FH FO FM FP FM FP FREQ FXD GE	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = disher (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electronic data processing = electrolytic = encapsulated = external = farad = field-effect transistor = flip-flop = flat head = lillister head = frequency modulation = front panel = frequency = fixed = garm = germanium	MFR mg MHz mH mho MIN MIN min ••• MOD MOM MOS MTG MTG MTG MTG MVpc mVac mVpc mVpc mVpc mVpc mVpc mVpc mVpc mVp	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (time) = minute (plane angle) = miniture = millimeter = millimeter = modulator = modulator = modulator = modulator = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, ac = millivolt, peak = millivolt, peak-to-peak = millivolt, peak = millivolt, ms = millivolt = multiplex = mylar = microampere = microfarad = micromho = neon	PTM PWM PWW PWV RC RECT REF REG REPL RF RFI RH RLC RMO RMD RAP ROM R&P RWV S S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = soattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list) = silicon controlled rectifier; screw = selicon = superhigh frequency = silicon = siliver = slide = signal to-noise ratio	VP-P Vrms VSWR VTO VTVM V(X) W W/ WIV WIV V/O Zo All abbreviation case. M Abbreviation T G M k da d c m µ n p	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = without = yttrium-iron-garnet = characteristic impedance NOTE ns in the parts list will be in upper **NOTE** **IDULTIPLIERS** Prefix Multiple tera 1012 giga 108 mega 108 mega 108 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 miloro 10-6 nano 10-9 pico 10-12
OEPC OET Giam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELECT EN CAP EXT F FET FFF FH FOL H FM FP FREQ FXD G G G G G G G G G G G G G G G G G G G	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drouble sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing = electronic data processing = electrolitic = encapsulated = atrad = farad = field-effect transistor = flip-flop = liat head = frequency = fixed = gram = germanium = germanium = gigahentz	MFR mg MHz mH mho MIN min MIN MIN MIN MOD MOM MOS ms MTG MTR mV dc mVpcp mVms mW MUX MY µF µH µH µH µH µH NEG	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minute (plane angle) = minute (plane angle) = minuter = millimeter = millimeter = modulator = momentary = metal-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, dc = millivolt, dc = millivolt, peak-to-peak = millivolt, ms = millivolt, ms = millivolt, mrs = millivolt, mrs = millivolt = millivolt, mrs = millivolt = microampere = microfarad	PTM PWM PWW RC RECT REF REG REPL RF RFI RH RIC RMO rms RND ROM R&P RWW S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (plane angle) = slow-blow fuse (used in parts list) = slicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency = silicon = silice = signal to-noise ratio = signal to-noise ratio = single-pole, double-throw	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ V/O YIG Zo All abbreviation case. M Abbreviation T G G M k da d c m µ n p f	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6 nano 10-9 pico 10-12 femto 10-15
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELLECT EN CAP EXT F FFF FH FOL H FM FP FPEQ FXD G G G G G G G G G G G G G G G G G C	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromictive force = electronic data processing = electrolic descending = farad = field-effect transistor = flip-flop = flat head = filister head = frequency = fixed = gram = germanium = gigahertz = glass	MFR mg MHz mH mho MIN min ••• MOD MOM MOS ms MTG MVG mVac mVac mVac mVp-p mVms mW MUV MV	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (lime) = miniture = millimeter = millimeter = modulator = modulator = modulator = modulator = modulator = modulator = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, ac = millivolt, peak = millivolt, ms	PTM PWM PWW RC RECT REF REG REPL RF RRI RH RLC RMO RMS RND ROM RAP RWW S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list) = slicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency = silicon = siliver = slide = signal to-noise ratio = single-pole, double-throw = spring	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ V/O YIG Zo All abbreviation case. M Abbreviation T G G M k da d c m µ n p f	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6 nano 10-9 pico 10-12 femto 10-15
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DTL DVM ECL EMF EOP ELECT ENF EFF FFF FFF FFF FFF FFF FFF FFF FFF	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drouble sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromic data processing = electronic data processing = electronic data processing = descriptic = encapsulated = external = farad = field-effect transistor = fiip-flop = fiigl-effect transistor = fiip-flop = fiigl-effect transistor = fiip-flop = fiflet head = fiflet mead = frequency = fixed = gram = germanium = gigahertz = glass = ground(ed)	MFR mg MHz mH mho MIN min MIN MIN MOD MOM MOS ms MTG MTR mV	(used in parts list) = manufacturer = milligram = megahertz = millimenry = conductance = minimum = minute (time) = minute (plane angle) = miniature = millimeter = millimeter = modulator = modulator = modulator = modulator = moterial-oxide semiconductor = millisecond = mounting = meter (indicating device) = millivolt, dc = millivolt, dc = millivolt, peak = millivolt, ms = millivolt = microfarad = microfarad = microfarad = micromho = neon = negative = nanofarad = nickel plate	PTM PWM PWW PWV RC REF REF REF REF RFI RH RLC RMO RMN ROM ROM ROM ROM S S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list) = silicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency = silicon = siliver = signal to-noise ratio = single-pole, double-throw = spring = split ring	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ V/O YIG Zo All abbreviation case. M Abbreviation T G G M k da d c m µ n p f	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6 nano 10-9 pico 10-12 femto 10-15
OEPC OET diam OIA OIFF AMPL div DPDT DR DSB DTL DVM ECL EMF EOP ELLECT EN CAP EXT F FFF FH FOL H FM FP FPEQ FXD G G G G G G G G G G G G G G G G G C	= degree Fahrenheit = degree Kelvin = deposited carbon = detector = diameter (used in parts list) = differential amplifier = division = double-pole, double-throw = drive = double sideband = diode transistor logic = digital voltmeter = emitter coupled logic = electromictive force = electronic data processing = electrolic descending = farad = field-effect transistor = flip-flop = flat head = filister head = frequency = fixed = gram = germanium = gigahertz = glass	MFR mg MHz mH mho MIN min ••• MOD MOM MOS ms MTG MVG mVac mVac mVac mVp-p mVms mW MUV MV	(used in parts list) = manufacturer = milligram = megahertz = millihenry = conductance = minimum = minute (lime) = miniture = millimeter = millimeter = modulator = modulator = modulator = modulator = modulator = modulator = millisecond = mounting = meter (indicating device) = millivolt, ac = millivolt, ac = millivolt, peak = millivolt, ms	PTM PWM PWW RC RECT REF REG REPL RF RRI RH RLC RMO RMS RND ROM RAP RWW S S S S S S S S S S S S S S S S S S	= pulse-time modulation = pulse-width modulation = peak working voltage = resistance capacitance = rectifier = reference = regulated = replaceable = radio frequency interference = round head; right hand = resistance-inductance-capacitance = rack mount only = root-mean-square = round = read-only memory = rack and panel = reverse working voltage = scattering parameter = second (time) = second (plane angle) = slow-blow fuse (used in parts list) = slicon controlled rectifier; screw = selenium = sections = semiconductor = superhigh frequency = silicon = siliver = slide = signal to-noise ratio = single-pole, double-throw = spring	VP-P Vrms VSWR VTO VTVM V(X) W W/ W/ W/ V/O YIG Zo All abbreviation case. M Abbreviation T G G M k da d c m µ n p f	= volts peak = volts peak-to-peak = volts peak-to-peak = volts ms = voltage standing wave ratio = voltage-tuned oscillator = vacuum-tube voltmeter = volts, switched = watt = with = working inverse voltage = wirewound = witrout = yttrium-iron-garnet = characteristic impedance NOTE si in the parts list will be in upper MULTIPLIERS Prefix Multiple tera 1012 giga 108 mega 106 kilo 103 deka 10 deci 10-1 centi 10-2 milli 10-3 micro 10-6 nano 10-9 pico 10-12 femto 10-15

Table 6-3. HP5501B Board Assemblies Replaceable Parts

Reference Designation	HP Part Number	C	Qty	Description	Mfr Code	Mfr Part Number
A1	05501-60028	0	1	CONNECTOR BOARD ASSEMBLY	28480	05501-60028
				SERIES 2632, REVISION A		
A1C1	0160-4557	0	2	CAPACITOR-FXD .1UF ±20% 50VDC CER	16299	CAC04X7R104M050A
A1C2	0160-4557	0	_	CAPACITOR FXD .10F ±20% 50VDC CER		CAC04X7R104M050A
A1C3	0180-2867	3	2	CAPACITOR FXD 390UF+100-10% 40VDC AL		0180-2867
A1C4	0180-2867	3	_	CAPACITOR-FXD 390UF+100-10% 40VDC AL		0180-2867
A1C5	0160-4535	4	1	CAPACITOR FXD 1UF ±10% 50VDC CER		0160-4535
A1C6	0180-3196	3	2	CAPACITOR-FXD 120UF+50 -10% 40VDC AL		0180-3196
A1C7	0180-3196	3	_	CAPACITOR-FXD 120UF +50 -10% 40VDC AL		0180-3196
A1C8	0160-4822	2	1	CAPACITOR-FXD 1000PF ±5% 100VDC CER		0160-4822
A1C9	0160-0576	5	4	CAPACITOR-FXD .1UF ±20% 50VDC CER		0160-0576
A1C10	0160-0576	5		CAPACITOR-FXD .1UF ±20% 50VDC CER		0160-0576
A1C11	0160-0576	5		CAPACITOR-FXD .1UF ±20% 50VDC CER		0160-0576
A1C12	0160-0576	5		CAPACITOR-FXD .1UF ±20% 50VDC CER		0160-0576
A1CR1	1901-0731	7	2	DIODE-PWR RECT 400V 1 A		1N4004G
A1CR2	1901-0731	7		DIODE-PWR RECT 400V 1 A		1N4004G
A1CR3	1902-0945	7	1	DIODE-ZNR 3V 5% DO-35 PD=.4W TC043%		1902-0945
						
A1DS1	1990-0486	6	4	LED-LAMP LUM-INT 2MCD IF=25MA-MAX BVR=5V	28480	HLMP-1301
A1DS2	1990-0486	6		LED-LAMP LUM-INT 2MCD IF=25MA-MAX BVR=5V		HLMP-1301
A1DS3	1990-0485	5	3	LED-LAMP LUM-INT 2MCD IF=30MA-MAX BVR=5V		HLMP-1503
A1DS4	1990-0485	5		LED-LAMP LUM-INT 2MCD IF=30MA-MAX BVR=5V		HLMP-1503
A1DS5	1990-0486	6		LED-LAMP LUM-INT 2MCD IF=25MA-MAX BVR=5V		HLMP-1301
A1DS6	1990-0486	6		LED-LAMP LUM-INT 2MCD IF=25MA-MAX BVR=5V		HLMP-1301
A1DS7	1990-0487	7	1	LED-LAMP LUM-INT 2MCD BVR=5V		HLMP-1401
A1DS8	1990-0485	5		LED-LAMP LUM-INT 2MCD IF=30MA-MAX BVR=5V		HLMP-1503
A1F1	2110-0695	6	2	FUSE-8IPIN 1.5A 125V NTD .348X.25 UL	28480	2110-0695
	2110-0691	2	2	FUSEHOLDER-8IPIN SKT 5A 125 V		2110-0691
A1F2	2110-0695	6		FUSE-8IPIN 1.5A 125V NTD .348X.25 UL		2110-0695
	2110-0691	2		FUSEHOLDER-8IPIN SKT 5A 125 V	28480	2110-0691
A1J1	1251-8494	6	1	CONN-POST TYPE .100-PIN-SPCG 24-CONT	28480	1251-8494
A1J2				NOT ASSIGNED		
A1J3	1251-6010	8	1	CONNECTOR 3-PIN M POST TYPE	28480	1251-6010
A1J4	1251-5170	9	1	CONNECTOR 2-PIN M POST TYPE	28480	1251-5170
A1J5	1251-3448	0	1	CONNECTOR 4-PIN F CIRCULAR	28480	1251-3448
A1J6	1251-3449	1	1	CONNECTOR 4-PIN F CIRCULAR 45	28480	1251-3449
A1L1	9140-0171	3	2	INDUCTOR RF-CH-MLD 40UH 10%	28480	9140-0171
A1L2	9140-0171	3		INDUCTOR RF-CH-MLD 40UH 10%	28480	9140-0171
	1					
A1Q1	1854-0215	1		TRANSISTOR NPN SI TO-92 PD,350MW		2N3904
A1Q2	1853-0058	8		TRANSISTOR PNP SI PD=300MW FT=200MHZ		S32248
A1Q3	1854-0635	9	2	TRANSISTOR NPN SI PD=50W FT=20MHZ		D44H5
A1Q4	1853-0058	8		TRANSISTOR PNP SI PD=300MW FT=200MHZ		S32248
A1Q5	1853-0058	8		TRANSISTOR PNP SI PD=300MW FT=200MHZ		S32248
A1Q6	1853-0363	8	1	TRANSISTOR PNP SI PD=50W FT=20MHZ		X45H281
A1Q7	1854-0635	9		TRANSISTOR NPN SI PD=50W FT=20MHZ		D44H5
A1Q8	1853-0058	8		TRANSISTOR PNP SI PD=300MW FT=200MHZ		S32248
A1Q9	1854-0215	1		TRANSISTOR NPN SI TO-92 PD=350MW	04713	2N3904
				d 30:: d0/ d /0:	245.5	
A1R1	0757-0278	9	11	RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R2	0757-0278	9		RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R3	0757-0278	9		RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R4	0757-0278	9	-	RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R5	0698-3156	2	6	RESISTOR 14.7K 1% 1/8W F TC=0±100		CT4-1/8-T0-1472-F
A1R6	0698-3156	2		RESISTOR 14.7K 1% 1/8W F TC=0±100		CT4-1/8-T0-1472-F
A1R7	0757-0278	9		RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R8	0757-0278	9		RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R9	0757-0278	9		RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R10	0757-0278	9		RESISTOR 1.78K 1% 1/8W F TC=0±100		CT4-1/8-T0-1781-F
A1R11	0757-0279	0		RESISTOR 3.16K 1% 1/8W F TC=0±100		CT4-1/8-T0-3161-F
A1R12	2100-3274	2	1	RESISTOR-TRMR 10K 10% C SIDE-ADJ 1-TRN	28480	2100-3274
A1R13	0757-0397	3	1	RESISTOR 68.11% 1/8W F TC=0±100	24546	CT4-1/8-T0-68R1-F
A1R14	0698-3156	2		RESISTOR 14.7K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-1472-F
A1R15	0811-0229	6	1	RESISTOR 500 1% 3W PW TC=0±20	28450	DS8110229

Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)

	rubic 0-0. Til 0001B Bourd Assemblies Replaceable 1 arts (Continued)								
Reference Designation	HP Part Number	Р	Qty	Description	Mfr Code	Mfr Part Number			
A1R16 A1R17 A1R18 A1R19 A1R20 A1R21 A1R22 A1R23 A1R24	0757-0278 0757-0278 0698-0082 0698-0082 0698-0082 0698-3156 0698-3156 0757-0278 0698-3156	9 7 7 2 2 9	3	RESISTOR 1.78K 1% 1/8W F TC=0±100 RESISTOR 1.78K 1% 1/8W F TC=0±100 RESISTOR 464 1% 1/8W F TC=0±100 RESISTOR 464 1% 1/8W F TC=0±100 RESISTOR 464 1% 1/8W F TC=0±100 RESISTOR 14.7K 1% 1/8W F TC=0±100 RESISTOR 14.7K 1% 1/8W F TC=0±100 RESISTOR 14.7K 1% 1/8W F TC=0±100 RESISTOR 1.78K 1% 1/8W F TC=0±100 RESISTOR 14.7K 1% 1/8W F TC=0±100 RESISTOR 14.7K 1% 1/8W F TC=0±100	24546 24546 24546 24546 24546				
A1S1 A1S2	3101-2878 3101-2334	3 6	1 1	SWITCH-PB DPDT MOM .5A 60 VAC/VDC SWITCH-SL DPDT SUBMIN .5A 125VAC/DC PC	31918 28480	MP 3101-2334			
A1TP1 A1TP2 A1TP3	0360-0535 0360-0535 0360-0535	0 0 0		TERMINAL-TEST POINT .330IN ABOVE TERMINAL-TEST POINT .330IN ABOVE TERMINAL-TEST POINT .330IN ABOVE		0360-0535 0360-0535 0360-0535			
	0380-1512 0380-1548 4040-1617	7 9 7	2 4 8	A1 MISCELLANEOUS PARTS AND HARDWARE STANDOFF-RIVET-ON 9-MM-LG M3.0 X 0.5-THD STANDOFF-RIVET 10 LM 2.5 STANDOFF-LED .196-IN-WD .196-IN-LG BLK	28480	0380-1512 0380-1548 4040-1617			
				REFERENCE DESIGNATORS NOT USED: A3J2					
A2	05518-60303	3	1	HIGH VOLTAGE POWER SUPPLY ASSEMBLY	28480	05518-60303			

Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)

Reference Designation	HP Part Number	C		Description	Mfr Code	Mfr Part Number
A3	05501-60027	9	1	CONTROLLER/REFERENCE BOARD ASSEMBLY SERIES 2632. REVISION A	28480	05501-60027
A3C1	0180-2929	8	1	CAPACITOR-FXD 68UF±10% 10VDC TA	28480	0180-2929
A3C2	0160-2929	7	15	CAPACITOR-FXD 080F±10% 10VDC TA	28480	
A3C3	0160-4334	4		CAPACITOR-FXD 1010F ±20% 30VDC CER		0160-4334
A3C4	0180-1746	5	1	CAPACITOR FXD 47011 15% 100VDC CER		150D156X9020B2
A3C5	0180-0291	5 3	1	CAPACITOR-FXD 1UF ±10% 35VDC TA	56289	150D105X9035A2
A3C6	0160-4554	7		CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	
A3C7	0180-1735	2	1	CAPACITOR-FXD .22UF ±10% 35VDC TA		150D224X9035A2
A3C8	0160-4824	4 7	1	CAPACITOR-FXD .022UF ±10% 100VDC CER	28480	
A3C9	0160-4554			CAPACITOR-FXD .UIUF ±20% 50VDC CER		0160-4554
A3C10	0160-4554	7		CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	0160-4554
A3C11	0180-0049	9	2	CAPACITOR-FXD 20UF +75-10% 50VDC AL	56289	30D206G050CC2
A3C12	0180-0049	9	_	CAPACITOR-FXD 20UF +75-10% 50VDC AL	56289	
A3C13	0160-3072	2	2	CAPACITOR-FXD 1UF ±10% 100VDC MET-POLYE	28480	
A3C14	0160-3072	2 2 7		CAPACITOR FXD 0145 +20% FOURC CER		0160-3072
A3C15 A3C16	0160-4554	7		CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	0160-4554 0160-4554
A3C16 A3C17	0160-4554 0160-4554	7		CAPACITOR-FXD .01 UF ±20% 50VDC CER CAPACITOR-FXD .01UF ±20% 50VDC CER		0160-4554
A3C17 A3C18	0160-4554	1	1	CAPACTION-FAD .010F ±20% 30VDC CER	28480	0160-4534
A3C19	0160-2433	7		CAPACITOR-FXD .22UF ±10% 80VDC POLYE CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	
A3C20	0160-4334	5	1	CAPACITOR-FXD :010F ±20% 30VDC CER		0160-4334
A3C21	0160-4554	7	-	CAPACITOR-FXD 5UF ±10% CAPACITOR-FXD .01UF ±20% 50VDC CER CAPACITOR-FXD .1UF ±20% 50VDC CER		0160-4554
A3C22	0160-0576	5	3	CAPACITOR-FXD .1UF ±20% 50VDC CER	28480	
A3C23	0160-4557	0	7	CAPACITOR-FXD .1UF ±20% 50VDC CER	16299	
A3C24	0160-4557	0		CAPACITOR-FXD .1UF ±20% 50VDC CER	16299	CAC04X7R104M050A
A3C25	0160-4554	7		CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	0160-4554
A3C26	0160-0576	5		CAPACITOR-FXD .1UF ±20% 50VDC CER	28480	0160-0576
A3C27	0160-0576	5		CAPACITOR-FXD .1UF ±20% 50VDC CER	28480	
A3C28	0180-0309	4	1	CAPACITOR-FXD 4.7UF±20% 10VDC TA		150D475X0010A2
A3C29	0160-4557	0		CAPACITOR-FXD .1UF ±20% 50VDC CER	16299	
A3C30	0160-4554	7	_	CAPACITOR-FXD .01UF ±20% 50VDC CER		0160-4554
A3C31	0160-4824	4	1	CAPACITOR-FXD 680PF ±5% 100VDC CER	28480	
A3C32	0160-4557	0		CAPACITOR-FXD .1UF ±20% 50VDC CER		CAC04X7R104M050A
A3C33	0160-4808	4		CAPACITOR-FXD 470PF ±5% 100VDC CER	28480	
A3C34	0160-4557	4		CAPACITOR-FXD .1UF ±20% 50VDC CER CAPACITOR-FXD 470PF ±5% 100VDC CER	16299	CAC04X7R104M050A 0160-4808
A3C35 A3C36	0160-4808 0160-4809	5	1	CAPACITOR-FXD 470PF ±5% 100VDC CER		0160-4809
A3C37	0160-4557	0	1	CAPACITOR-FXD 350FF ±3% 100VDC CER	16299	CAC04X7R104M050A
A3C38	0160-4554	7		CAPACITOR FXD .101 120% 50VDC CER	28480	
A3C39	0160-4554	7		CAPACITOR FXD .01UF ±20% 50VDC CER		0160-4554
A3C40	0160-4557	0		CAPACITOR-FXD .1UF ±20% 50VDC CER	16299	
A3C41	0160-4554	7		CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	
A3C42	1810-0768	7	1	NETWORK-CAPACITOR SIP NETWORK CAPACITOR		470C7C0G471K5DG
A3C43	0160-4808	4		CAPACITOR-FXD 470PF ±5% 100VDC CER	28480	
A3C44	0160-4554	7		CAPACITOR-FXD .01UF ±20% 50VDC CER	28480	0160-4554
A3C45	0160-4808	4		CAPACITOR-FXD 470PF ±5% 100VDC CER	28480	0160-4808
A3CR1	1901-0050	3	3	DIODE-SWITCHING 80V 200MA 2NS DO-35	9N171	
A3CR2	1901-0731	7		DIODE-POWER RECT 400V 1A	14433	1N4004G
A3CR5	1990-0770	1		PHOTODIODE ID=30NA-MAX	32694	
A3CR6	1901-0518	8		DIODE-SM SIG SCHOTTKY	28480 0N171	1901-0518
A3CR7 A3CR8	1901-0050 1901-0050	3		DIODE-SWITCHING 80V 200MA 2NS DO-35 DIODE-SWITCHING 80V 200MA 2NS DO-35	9n171 9n171	1N4150 1N4150
A3DS1 A3DS2	1990-0485 1990-0487	5 7		LED-LAMP LUM-INT=2MCD IF=30MA-MAX BVR=5V LED-LAMP LUM-INT=2MCD BVR=5V	28480 28480	HLMP-1503 HLMP-1401
A3J1 A3J2	1251-8603 1251-5801	9		CONN-POST TYPE. 100-PIN-SPCG 24-CONT CONNECTOR 4-PIN M POST TYPE	28480 28480	1251-8603 1251-5801
A3JMP1 A3JMP2 A3JMP3 A3JMP4 A3JMP5	1251-4047 1251-4813 1251-6957 1251-4813 1251-4047	7 5 2 5 7	4	CONNECTOR 3-PIN M POST TYPE CONNECTOR 5-PIN M POST TYPE CONNECTOR 4-PIN M POST TYPE CONNECTOR 5-PIN M POST TYPE CONNECTOR 3-PIN M POST TYPE	28480 28480 28480 28480 28480	1251-4813 1251-6957 1251-4813

Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)

Deference	LID Dort		l		Mfr	
Reference	HP Part Number	C		Description	Code	Mfr Part Number
Designation A3JMP6	1251-4813			CONNECTOR 5-PIN M POST TYPE		1251 4813
	1251-4047	5 7		CONNECTOR 3-PIN M POST TYPE		1251 4813
	1251-4047	7		CONNECTOR 3-PIN M POST TYPE	28480	
	9100-2558	ó	2	INDUCTOR RF-CH-MLD 47UH 5%	28480	
	9100-2558	0	_	INDUCTOR RF-CH-MLD 47UH 5%		9100-2558
	9140-0531	9	1	INDUCTOR RF-CH-MLD 1UH 5% .105DX.26LG		9140-0531
	9140-0537	5		INDUCTOR RF-CH-MLD 2.2UH 5% .105DX.26LG		9140-0537
	9140-0537	5	_	INDUCTOR RF-CH-MLD 2.2UH 5% .105DX,26LG		9140-0537
A3Q1				NOT ASSIGNED		
A3Q5				NOT ASSIGNED		
A3Q6	1854-0215	Ι	2	TRANSISTOR NPN SI TO-92 PD-350MW	04713	2N3904
A3Q7	1854-0215	1		TRANSISTOR NPN SI TO-92 PD-350MW	04713	2N3904
A3R1				NOT ASSIGNED		
A3R2	0698-0084	9	6	RESISTOR 2.15K 1% 1/8W F TC=0±100	24546	
	0698-0084	9		RESISTOR 2.15K 1% 1/8W F TC=0±100		CT4-1/8-T0-2151-F
A3R4	1810-0367	2	2	NETWORK-RES 6-SIP 4.7K OHM X 5	11236	750-61-R4.7K
A3R5	1810-0279	5	1	NETWORK-RES 10-SIP 4.7K OHM X 9	91637	CSC10A01-472G/MSP10A01-
						472G
	0699-0069 0757-0458	2 7	4 1	RESISTOR 2.15M 1% 1/8W F TC=0±100		0699-0069 CT4-1/8-T0-5112-F
	0757-0458 0757-0440	7		RESISTOR 51.1K 1% 1/8W F TC=0±100 RESISTOR 7.5K 1% 1/8W F TC=0±100		CT4-1/8-T0-5112-F
A3R9	0131-0440	'	+	NOT ASSIGNED	24340	C1+-1/0-10-/301-F
	0698-6360	6	4	RESISTOR 10K .1% 1/8W F TC=0±25	28480	0698-6360
	0698-6360	6		RESISTOR 10K .1% 1/8W F TC=0±25	28480	
A3R11 A3R12	0030-0300	0		NOT ASSIGNED	20400	0030-0300
A3R13				NOT ASSIGNED		
	0698-6360	6		RESISTOR 10K .1% 1/8W F TC=0±25	28480	0698-6360
-	0698-6360	6		RESISTOR 10K .1% 1/8W F TC=0±25		0698-6360
	2100-3161	6		RESISTOR-TRMR 20K 10% C SIDE-ADJ 17-TRN		89PR20K
	0698-3457	6		RESISTOR 316K 1% 1/8W F TC=0±100		0698-3457
	0698-3156	2	1	RESISTOR 14.7K 1% 1/8W F TC=0±100		CT4-1/8-TO-1472-F
	0757-0416	7	4	RESISTOR 511 1% 1/8W F TC=0±100		CT4-1/8-T0-511R-F
A3R20	0757-0280	3	5	RESISTOR 1K 1% 1/8W F TC=0±100	24546	CT4-1/8-TO-1001-F
A3R21	0757-0280	7 3 3 3		RESISTOR 1K 1% 1/8W F TC=0±100		CT4-1/8-T0-1001-F
A3R22	0757-0438	3	3	RESISTOR 5.11K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-5111-F
A3R23	0698-3457	6		RESISTOR 316K 1% 1/8W F TC=0±100	28480	0698-3457
A3R24	0757-0438	3		RESISTOR 5.11K 1% 1/8W F TC=0±100	24546	
A3R25	0757-0442	9	5	RESISTOR 10K 1% 1/8W F TC=0±100		CT4-1/8-T0-1002-F
	0757-0442	9		RESISTOR 10K 1% 1/8W F TC=0±100		CT4-1/8-TO-1002-F
	0699-0069	2	_	RESISTOR 2.15M 1% 1/8W F TC=0±100		0699-0069
	0757-0443	0	2	RESISTOR 11K 1% 1/8W F TC=0±100		CT4-1/8-T0-1102-F
	0757-0280	3 2 3 2	_	RESISTOR 1K 1% 1/8W F TC=0±100	24546	
	0698-3453	2		RESISTOR 196K 1% 1/8W F TC=0±100		CT4-1/8-TO-1963-F
	0698-3454	3	2	RESISTOR 215K .1% 1/8W F TC=0±100		CT4-1/8-T0-2153-F
	0699-0069	2		RESISTOR 2.15M 1% 1/8W F TC=±100		0699-0069
	0698-3454 0757-0394	3	2	RESISTOR 215K 1% 1/8W F TC=0±100 RESISTOR 51.1 1% 1/8W F TC=0±100		CT4-1/8-T0-2153-F CT4-1/8-T0-51R1-F
	0757-0394 0757-0394	0		RESISTOR 51.1 1% 1/8W F TC=0±100 RESISTOR 51.1 1% 1/8W F TC=0±100		CT4-1/8-T0-51R1-F
	0757-0394	9		RESISTOR 31.1 1% 1/8W F TC=0±100	24546	
A3R37	0.31 0772			NOT ASSIGNED	2-3-0	C11 1/0 10 1002-1
A3R38				NOT ASSIGNED		
	0698-3153	9	1	RESISTOR 3.83K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-3831-F
A3R40			-	NOT ASSIGNED		,
A3R42				NOT ASSIGNED		
	0698-0083	8	1	RESISTOR 1.96K 1% 1/8W F TC=0±100		CT4-1/8-T0-1961-F
A3R44	0757-0438	3		RESISTOR 5.11K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-5111-F
	0757-0416	7		RESISTOR 511 1% 1/8W F TC=0±100	24546	
	0698-3155	1		RESISTOR 4.64K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-4641-F
A3R47				NOT ASSIGNED		
	1810-0374	1		NETWORK-RES 8-SIP 1.0K OHM X 4		750-83-R1K
	0699-0071	6	2	RESISTOR 4.64M 1% 1/8W F TC=0±100		0699-0071
	0699-0069	2		RESISTOR 2.15M 1% 1/8W F TC=0±100	28480	
	0699-0071	6		RESISTOR 4.64M 1% 1/8W F TC=0±100		0699-0071
	0757-0276	7		RESISTOR 61.9 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-6192-F
A3R53				NOT ASSIGNED		
A3R60						
	0757 0463	4		PECTSTOP 93 FW 19/ 1/9W 5 TO 0:100	24546	CT4 1/9 TO 9353 5
A3R61	0757-0463 0698-0084	4		RESISTOR 82.5K 1% 1/8W F TC=0±100 RESISTOR 2.15K 1% 1/8W F TC=0±100		CT4-1/8-TO-8252-F CT4-1/8-TO-2151-F

Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)

Reference Designation	HP Part Number	C		Description	Mfr Code	Mfr Part Number
A3R63	0698-0084	9		RESISTOR 2.15K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-2151-F
A3R64	1810-0374	1		NETWORK-RES 8-SIP 1. OK OHM X 4	11236	
43R65	1810-0374	1		NETWORK-RES 8-SIP 1 .OK OHM X 4		750-83-R1K
A3R66	0757-0416	7		RESISTOR 511 1% 1/8W F TC=0±100		CT4-1/8-T0-511R-F
A3R67	1810-0367	2		NETWORK-RES 6-SIP 4.7K OHM X 5		750-61-R4.7K
A3R68	0698-0084	9		RESISTOR 2.15K 1% 1/8W F TC=0±100		CT4-1/8-T0-2151-F
A3R69	0757-0443	0		RESISTOR 11K 1% 1/8W F TC=0±100	24546	
A3R70	0757-0280	3		RESISTOR 1K 1% 1/8W F TC=0±100		CT4-1/8-T0-1001-F
A3R71	0757-0442	9		RESISTOR 10K 1% 1/8W F TC=0±100		CT4-1/8-T0-1002-F
\3R72	0698-0084	9		RESISTOR 2.15K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-2151-F
A3R73	0757-0442	9		RESISTOR 10K 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-1002-F
43R74	0757-0280	3		RESISTOR 1K 1% 1/8W F TC=0±100	24546	
A3R75	0757-0416	7		RESISTOR 511 1% 1/8W F TC=0±100	24546	CT4-1/8-T0-511R-F
A3TP1	1251-5177	6	22	CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3TP2	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3TP3	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	
43TP4	1251-5177	6		CONNECTOR SGL CONT PIN .031 IN BSC 32	28460	
		6			28460	
43TP5	1251-5177			CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		
A3TP6	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		1251-5177
A3TP7	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		1251-5177
A3TP8	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	
A3TP9	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3TP10	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3TP11	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3TP12	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		1251-5177
A3TP13	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	
		6			28460	
A3TP14	1251-5177			CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		
A3TP15	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	
A3TP16	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		1251-5177
A3TP17	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ		1251-5177
A3TP18	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3TP19	1251-5177	6		CONNECTOR-SGL CONT PIN. 031-IN-BSC-SZ	28480	1251-5177
A3TP20	1251-5177	6		CONNECTOR-SGL CONT PIN. 031-IN-BSC-SZ	28460	
A3TP21	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	
A3TP22	1251-5177	6		CONNECTOR-SGL CONT PIN .031-IN-BSC-SZ	28460	1251-5177
A3U1	1820-1416	5	1	IC SCHMITT-TRIG TTL LS INV HEX 1-INP	01295	SN74LS14N
A3U2	1820-2889	8		IC GATE TTL ALS AND TPL 3-INP		SN74ALS11N
A3U3		3				SN74ALS74AN
	1820-2468	7		IC FF TTL ALS D- TYPE POS-EDGE-TRIG		
A3U4	1820-2078			IC CNTR TTL ALC AND GUAR 2 THE	01295	
A3U5	1820-2635	2	1	IC GATE TTL ALS AND QUAD 2-INP	01295	
A3U6	1820-2096	9		IC CNTR TTL LS BIN DUAL 4-BIT	01295	
A3U7	1826-0122	0		IC 7805 V RGLTR TO-220	07263	
43U8	1820-2468	3		IC FF TTL ALS D-TYPE POS-EDGE-TRIG	01295	SN74ALS74AN
A3U9	1260-0510	0	1	TEST IC PACKAGE	28460	1260-0510
A3U10	1820-2466	7		IC TIMER CMOS	32293	
A3U11	1826-0753	3		IC OP AMP LOW-BIAS-H-IMPD QUAD 14-DIP-C		MC340048L
		5		The state of the s		LF13331D
A3U12	1826-0416			IC SWITCH ANLG QUAD 16-DIP-C PKG		
43U13	1826-0493	8		IC OP AMP LOW-BIAS-H-IMPD 8-DIP-P PKG		MLM308AP1
43U14	1826-0519	9		IC OP AMP LOW-BIAS-H-IMPD 8-DIP-P PKG		TL071CP
A3U15	1826-0065	0		IC COMPARATOR PRCN 8-DIP-P PKG		LM311N
43U16	1820-2668	1		IC DRVR TTL LINE DRVR DUAL 3 - INP		SN75114N
A3U17	1826-0775	9	1	IC 16-DIP-P PKG	28460	1DA7Q
A3U18				NOT ASSIGNED		
A3U19	1820-3562	6	1	IC BFR TTL ALS INV HEX	01295	SN74ALS1005N
43U2O	1826-0428	9		IC 3524 MODULATOR 16-DIP-C	01295	
43U21	1820-0428	1		IC BFR TTL LS NOR QUAD 2-INP	01295	
				A3 MISCELLANEOUS PARTS AND HARDWARE		
	0340-0907	8	1	INSULATOR-XSTR NYLON JUMPER-REMOVABLE FOR 0.025 IN SQUARE PINS	28480	0340-0907
	1258-0141	8	8	REFERENCE DESIGNATORS NOT USED: A3CR3-4, Q1-5, R1, R12-13, R37-38, R40-42, R47, and U18.	28480	1258-0141

Table 6-3. HP5501B Board Assemblies Replaceable Parts (Continued)

Reference Designation	HP Part Number	C	Qty	Description	Mfr Code	Mfr Part Number
A4	05501-60029	1	1	SAMPLER BOARD ASSEMBLY SERIES 2632. REVISION B	28480	05501-60029
A4CR1	1990-0770	1	1	PHOTODIODE ID=30NA-MAX	32694	OP 913 (SELECTED)
A4P1	1251-6778	5		CONNECTOR 4-PIN F POST TYPE		1251-6778
				A4 MISCELLANEOUS PARTS AND HARDWARE		
	0340-0907	8	1	INSULATOR-XSTR NYLON	28480	0340-0907
A5	05501-60102	1	1	LASER TUBE ASSEMBLY	28480	05501-60102
				NOT FIELD REPAIRABLE		
				SEE TABLE 6-1 FOR LASER TUBE REPLACEMENT PART NUMBERS.		
A6	05501-60101	0	1	SAMPLER ASSEMBLY	28480	05501-60101
	1990-0768	7	1	LIQUID CRYSTAL SWITCH	28480	1990-0768
	8160-0530	9	2	ELASTOMERIC CONNECTOR	28480	8160-0530
	L	Ш			1	

Table 6-3. HP5501B Miscellaneous Chassis Parts (Continued)

		D	Qty	Description	Code	Mfr Part Number
		+		LASER HEAD MISCELLANEOUS CHASSIS		
A1	05501-60028	0	1	CONNECTOR BD ASSEMBLY	28480	05501-60028
A2	05518-60303	3		HIGH VOLTAGE POWER SUPPLY ASSEMBLY		05518-60303
		9	1	CONTROL/REFERENCE BD ASSEMBLY		05501-60027
A3	05501-60027	9		•		
14	05501-60029	T	1	SAMPLER BOARD ASSEMBLY		05501-60029
45	05501-60102	1	1	LASER TUBE ASSEMBLY		05501-60102
46	05501-60101	0	1	SAMPLER ASSEMBLY	28480	05501-60101
- 1	0510-0054	7	1	RETAINER-RING GRPR EXT .25-IN-DIA STL	28480	0510-0054
H2	0510-0252	7	2	ER DIVISION	28480	0510-0252
13	0515-0490	5	2	SCREW-SKT-HD-CAP M4 X 0.7 12MM-LG	28480	0515-0490
14	0515-0530	4	6	SCREW-SET M4 X 0.7 5MM-LG PLAIN-CUP-PT		ORDER BY DESCRIPTION
 15	0515-0886	3	7	SCREW-MACH M3 X 0.5 6MM-LG PAN-HD		0515-0886
16	0515-0890	9	2	SCREW-MACH M3 X 0.5 6MM-LG 90-DEG-FLH-HD		0515-0890
1 7	0515-0896	5	2	SCREW-MACH M4 X 0.7 10MM-LG	28480	0515-0896
48	0515-1129	9	8	SCREW-MACH M4 X 0.7 16MM-LG	28480	0515-1129
1 9	0515-1322	4	2	SCREW-MACH M3 X 0.5 30MM-LG	28480	0515-1322
110	0515-1351	9	4	SCREW-MACH M2.5 X 0.45 8MM-LG		0515-1351
111	1390-0314	7	1	FASTENER-1/4-TURN ASSY PANEL THKNS		1390-0314
112	2190-0584	0	2	WASHER-LK HLCL 3.0 MM 3.1-MM-ID		2190-0584
H13	2190-0586	2	2	WASHER-LK HLCL 4.0 MM 4.1-MM-ID	28480	2190-0586
H14	3050-0891	7	7	WASHER-FL MTLC 3.0 MM 3.3-MM-ID		3050-0891
115	3050-0893	9	2	WASHER-FL MTLC 4.0 MM 4.4-MM-ID		3050-0893
MР1	05501-00008	0	1	SAMPLER MOUNT	28480	05501-00008
4P2	05501-20215	3	1	LASER BASE	28480	05501-20215
ИР3	05501-20219	7	1	FRONT PANEL		05501-20219
л. 5 ИР4	05501-20221	1	1	REAR PANEL		05501-20221
MP5	05501-20222	2	3	F00T		05501-20222
мР6	05501-40003	9	1	SHUTTER MOUNT		05501-40003
мР7	05501-40004	0	1	SHUTTER	28480	05501-40004
мР8	05501-60007	5	1	LEFT COVER (AS VIEWED FROM FRONT PANEL)	28480	05501-60007
мР9	05501-00003	5	1	RIGHT COVER (AS VIEWED FROM FRONT PANEL)		05501-00003
MP10	05501-00007	9	1	SHIELD		05501-00007
P1 P2	1251-3450 1251-3447	4	1 1	CONNECTOR 4-PIN M CIRCULAR 45 (REFERENCE) CONNECTOR 4-PIN M CIRCULAR (POWER)		1251-3450 1251-3447
	5030-6770	2	1	WINDOWS-1.0 AIR	28480	5030-6770
	1000-0616	7		TEST POLARIZER		1000-0616
				LABELS AND NAMEPLATES		
	05501-80011	3	1	NAMEPLATE	28/80	05501-80011
	5080-0098	1		LABEL-SERIAL NO.		5080-0098
	7120-2444	3		LABEL-5501B LASER		7120-2444
	7120-3731	3	2	LABEL-HIGH VOLTAGE WARNING		7120-3731
	7120-5180	0	1	LABEL-WARNING	28480	7120-5180
	7121-1650	3		LABEL-MFG DATE		7121-1650
		0				9320-1744
	9320-1744	1 -	-	LABEL-MAGNETIC		
	05500-80007	6	2	LABEL-CAUTION		05500-80007
	05500-80008	7	1	LABEL-REGULATION	28480	05500-80008

6-14. Exploded View

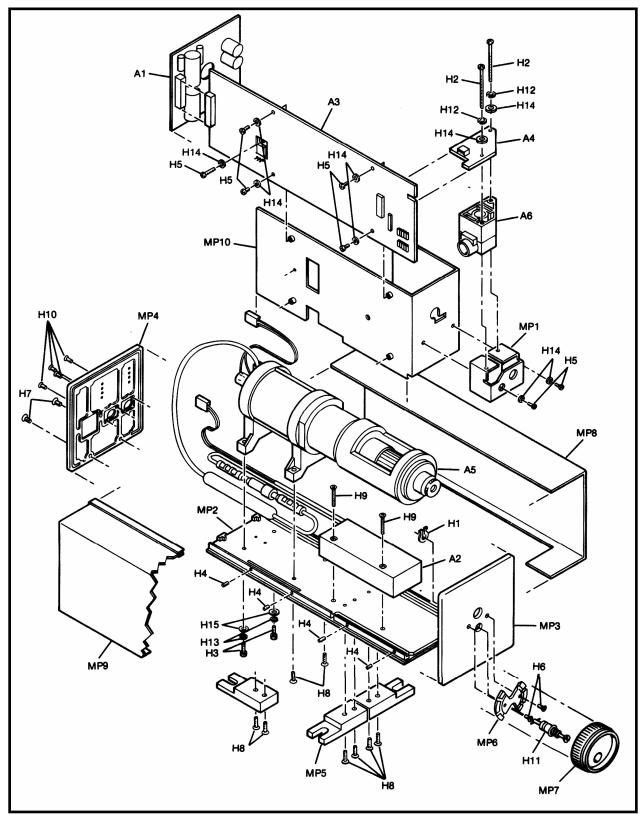


Figure 6-1. HP5501B Laser Head Exploded View

HP5501B Replaceable Parts

Table 6-4. Manufacturer's Code List

Mfr Code	Manufacturer Name	Address		Zip Code
00000	ANY SATISFACTORY SUPPLIER			
01295	TEXAS INSTRUMENTS INC	DALLAS	TX US	75265
03508	GE CO SEMICONDUCTOR PROD DEPT	AUBURN	NY US	13201
04713	MOTOROLA INC SEMI-COND PROD	PHOENIX	AZ US	85008
07263	FAIRCHILD CORP	MOUNTAIN VIEW	CA US	94042
11236	CTS CORP BERNE DIV	BERNE	IN US	46711
14433	ITT SEMICONDUCTORS DIV	TUSTIN	CA US	92680
16299	CORNING ELECTRONICS	RALEIGH	NC US	27604
24546	CORNING ELECTRONICS	SANTA CLARA	CA US	95050
27014	NATIONAL SEMICONDUCTOR CORP	SANTA CLARA	CA US	95052
28480	HEWLETT-PACKARD CO CORPORATE HQ	PALO ALTO	CA US	94304
31918	ITT SHADOW INC	EDEN PRAIRIE	MN US	55344
32293	INTERSIL INC	CUPERTINO	CA US	95014
32694	TRW OPTOELECTRONICS DIV	CARROLLTON	TX US	75006
32997	BOURNS INC	RIVERSIDE	CA US	92507
56289	SPRAGUE ELECTRIC CO	NORTH ADAMS	MA US	01247
73138	BECKMAN INDUSTRIAL CORP	FULLERTON	CA US	92632
9n171	UNIT RODE CORP	LEXINGTON	MA US	02173
91637	DALE ELECTRONICS INC	EL PASO	TX US	79936

7 MANUAL CHANGES

7-1. Introduction

7-2. This section normally contains information required to update or backdate this manual to cover newer or older instruments with serial prefixes different than those shown on the title page. Since this manual applies directly to new **HP5501B** units having the serial number prefix listed on the title page, no change information is given here. Refer to INSTRUMENTS COVERED BY THIS MANUAL in Section 1 for additional important information about serial number coverage.

7-3. Newer Instruments

7-4. As engineering changes are made, newer instruments may have a higher serial number prefix than that listed for the particular instrument. The manual shipped with a **HP5501B** Laser Head will include a "Manual Changes" sheet that describes all required changes to update the manual. If any of the instruments shipped with the system have a higher serial number than those listed on the title page and the" Manual Changes" sheet does not cover the prefix, contact your local HP Sales and Service Office for information.

8 SERVICE

8-1. Introduction

8-2. This section contains service information for the **HP5501B** Laser Head. Also included are safety considerations, theory of operation, block diagrams, schematic diagrams, component locators, and troubleshooting and repair procedures. Other useful service information also provided in other sections of this manual include: performance tests in <u>Section 4</u>, adjustments in <u>Section 5</u>, and exploded view illustrations and parts lists in <u>Section 6</u>.

8-3. Theory of Operation

- 8-4. The theory of operation is presented at two levels:
 - Block Diagram Description. These paragraphs describe the laser head's major functional blocks and modes of operation. The description references the HP5501B Laser Head Block Diagram, Figure 8-2.
 - Board Level Theory of Operation. These paragraphs are arranged by assembly number order and describe the circuitry at the component level. The descriptions are used with schematic diagrams for A1, A2, and A3.

8-5. Recommended Test Equipment

8-6. Table 1-2 in Section 1 lists the test equipment required for service. Any equipment that satisfies the critical specifications given in the table may be substituted for the recommended model (s).

8-7. Service Aids

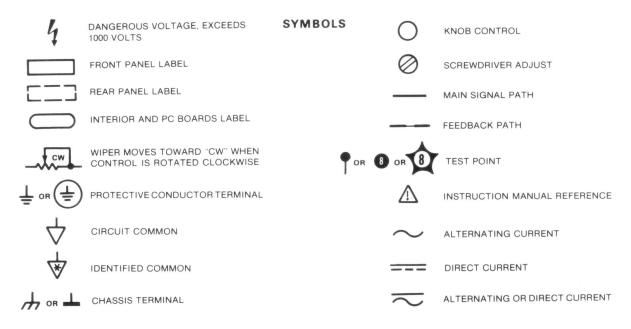
8-8. This system uses both Metric and English hardware. Figure 6-1 should be used to determine the correct hardware descriptions, part numbers and the proper tools to employ for assembly and disassembly.

8-9. Schematic Diagram Symbols and Reference Designations

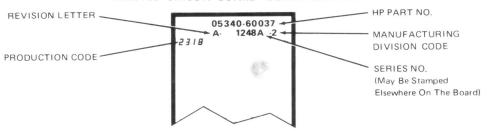
- 8-10. The logic symbology used on the schematic diagrams conforms to American National Standard (ANSI/IEEE Std. 91-1984). This standard supersedes MIL-STD-806B.
- 8-11. Figure 8-1 shows some of the symbols used on the schematic diagrams. In the center of this figure, the scheme for printed circuit board identification is presented. Also shown at the bottom of Figure 8-1 is the method used to identify reference designators, assemblies, and subassemblies.

NOTE

A TILDE (" \sim ") PRECEDING A SIGNAL NAME (I.E., \sim REF ON) INDICATES NEGATIVE-TRUE LOGIC.



PRINTED CIRCUIT BOARD IDENTIFICATION



REFERENCE DESIGNATIONS

REFERENCE DESIGNATIONS WITHIN ASSEMBLIES ARE ABBREVIATED. ADD ASSEMBLY NUMBER TO ABBREVIATION FOR COMPLETE DESCRIPTION. JACKS ARE THE STATIONARY CONNECTORS AND PLUGS ARE THE MORE MOVEABLE OF TWO CONNECTORS.

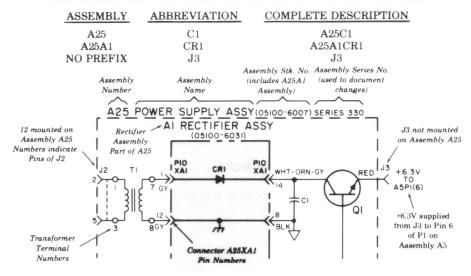


Figure 8-1. Schematic Diagram Notes

8-12. Safety Considerations

8-13. The following paragraphs contain warnings and cautions that must be followed for your protection and to avoid damage to the equipment.

WARNING

MAINTENANCE DESCRIBED HEREIN IS PERFORMED WITH POWER SUPPLIED TO THE EQUIPMENT AND WITH THE PROTECTIVE COVERS REMOVED. SUCH MAINTENANCE SHOULD BE PERFORMED ONLY BY SERVICE-TRAINED PERSONNEL WHO ARE AWARE OF THE HAZARDS INVOLVED (FOR EXAMPLE, FIRE AND ELECTRIC SHOCK). WHERE MAINTENANCE CAN BE PERFORMED WITHOUT POWER APPLIED, THE POWER TO THE EQUIPMENT SHOULD BE REMOVED.

WARNING

BEFORE ANY REPAIR IS COMPLETED, ENSURE THAT ALL SAFETY FEATURES ARE INTACT AND FUNCTIONING, AND THAT ALL NECESSARY PARTS ARE CONNECTED TO THEIR PROTECTIVE GROUNDING MEANS.

FROM 1.2 KILOVOLTS TO 12 KILOVOLTS DC IS PRESENT ON THE ANODE OF THE LASER TUBE IN THE HP5501B. EXERCISE EXTREME CAUTION WHEN WORKING INSIDE THE INSTRUMENT. THE HIGH VOLTAGE COULD CAUSE SERIOUS PERSONAL INJURY IF CONTACTED. THE INSTRUMENT SERVICE SHOULD BE PERFORMED BY SERVICE-TRAINED PERSONNEL ONLY.

NOTE

When the HP5501B covers are removed, the High Voltage Power Supply (HVPS), A2, is disconnected automatically by A1S1. For adjustments and servicing purposes, the High Voltage Power Supply can be reenabled by setting the TEST-NORM switch, A1S2; to TEST after the HP5501B covers are removed.

WARNING

LASER RADIATION IS ACCESSIBLE WHEN THE HP5501B COVERS ARE REMOVED AND THE TEST-NORM SWITCH, A1S2, IS IN THE TEST POSITION. AVOID EXPOSURE TO THE EYES.

8-14. Safety Symbols

8-15. The following safety symbols are used on the instrument or in this manual.



Instruction manual symbol. The product will be marked with this symbol when it is necessary for the user to refer to the instruction manual in order to prevent damage to the instrument.



Protective conductor terminal. For protection against electrical shock in case of a fault. Used with field wiring terminals to indicate the terminal that must be connected to ground before operating the equipment.



Frame and chassis terminal. A connection to the frame (chassis) of the equipment which normally includes all exposed metal structures.



Indicates dangerous voltage at input or output terminals that may exceed 1000 volts.



Low-noise or noiseless, clean ground (earth) terminal. Used for signal common as well as providing protection against electrical shock in case of fault. A terminal marked with this symbol must be connected to ground as described in Section 2 Installation in this manual before operating the equipment.



Alternating current.



Direct current.



The WARNING signal denotes a hazard. It calls attention to a procedure or practice which could result in personal injury if not adhered to or correctly performed.



The CAUTION signal denotes a hazard. It calls attention to an operating procedure or practice which could result in damage or destruction to part of or the entire product if not adhered to or correctly performed.

8-16. Before and After Service Product Safety Checks

8-17. Visually inspect the interior of the serviced instrument for any signs of abnormal internally generated heat, such as discolored printed circuit boards or components, damaged insulation, or evidence of electrical arcing. Determine and remedy the cause of any such condition.

8-18. LASER HEAD BLOCK DIAGRAM DESCRIPTION

- 8-19. The major structures of the HP 5501B are shown on the HP 5501B Laser Head Block Diagram in Figure 82 and include the control electronics, laser assembly, sampler assembly, reference receiver, and the high voltage power supply. All of the necessary control signals for the operation of the HP 5501B are generated internally. Power requirements are ±15 Volts DC from external system power supplies.
- 8-20. Overall, the purpose of the laser head is to emit a collimated, dual frequency laser beam with a high degree of stability. A portion of the emitted beam (about 10%) is directed to the sampler assembly to establish a reference frequency while the main portion of the beam is directed to external optics and returned to an external measurement receiver to develop a measurement frequency. The system electronics compare the reference and measurement frequencies to calculate the relative displacement of the optics.
- 8-21. The control electronics determine the tuning of the laser assembly to ensure an accurate laser wavelength for making measurements. Two phases of tuning are used, warmup mode and optical mode. When the desired characteristics of the laser beam are obtained during the optical mode, the system is ready to make measurements.
- 8-22. The laser assembly optics ensures correct laser frequency polarizations and also collimates the laser beam. Collimating minimizes variations in the diameter of the beam as it travels away from the laser head. Laser frequency F2 is polarized in a plane parallel to the base of the HP 5501B chassis. The other laser frequency F1 is polarized perpendicular to F2. The difference between the two laser frequencies F1 and F2 is small compared to their optical frequencies. The exit aperture shutter of the turret assembly has three positions. The first blocks the laser beam entirely; the second allows a small diameter laser beam to exit for optical alignment purposes; and the third passes the entire laser beam.
- 8-23. Before the laser light is emitted from the HP 5501B, a portion of it is sampled by the sampler assembly. Most of this sample feeds into the reference receiver while the remainder is used to control laser tuning. The reference receiver generates the reference frequency signal by mixing the two laser frequencies. The reference frequency is a 1.5 to 2.0 MHz, TTL level square wave. When the laser tuning stabilizes, the reference frequency is sent to the system electronics.
- 8-24. During a measurement, the laser beam follows a path through external measurement optics and to the HP 10780A Receiver. If the optics remain stationary, the measurement frequency and the reference frequency are the same. Relative motion between the measurement optics result in a change of the measurement frequency. The electronics compare the measurement frequency to the reference frequency and calculate the displacement of the optics. The measurement frequency output from the HP 10780A system receiver requires proper alignment of measurement optics in addition to stable laser tuning.
- 8-25. The High Voltage Power Supply (HVPS) requires -15 Vdc as input. This supply generates up to 12 kilovolts DC at power-on. After the laser emission starts, the power supply output drops to approximately 1.2 kilovolts DC.

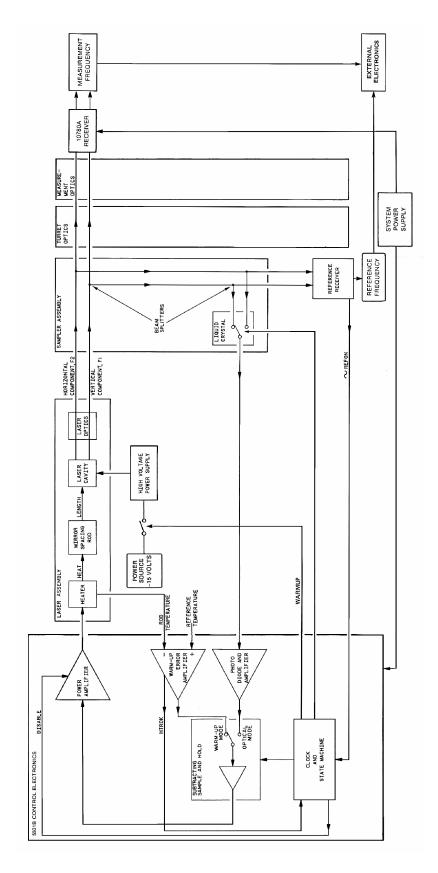


Figure 8-2.HP5501B Laser Head Block Diagram

8-26. Laser Tuning

- 8-27. The laser assembly produces stable frequency components only when the laser assembly cavity length is properly controlled. The cavity length is determined by the separation of two mirrors that are held against the ends of a glass rod. The HP 55018 uses a thermal tuning technique to control the cavity length. Cavity length increases when the rod is heated and decreases when it cools.
- 8-28. A heater coil wrapped around the glass rod is used to increase the cavity length. Rod cooling by conduction to surrounding material is used to decrease cavity length. To properly control the rod temperature, the rate at which it cools should approximate the rate at which it is heated. The HP 55018 raises the cooling rate by maintaining the rod at an elevated temperature.

8-29. Warmup Mode Tuning

8-30. One of two feedback loops used to control the laser assembly establishes the initial operating temperature of the glass rod. When power is first applied to the HP 55018, the state machine (see Figure 8-3) resets to its warmup mode. In the warmup mode, the state machine controls the subtracting sample and hold so that the feedback is as shown in Figure 8-4. The warmup error amplifier produces an error signal that is proportional to the difference between the rod temperature and a reference temperature. The warmup mode feedback loop controls the rod temperature until it equals the reference temperature. The reference temperature is adjustable and factory set to be higher than the hottest expected ambient temperature.

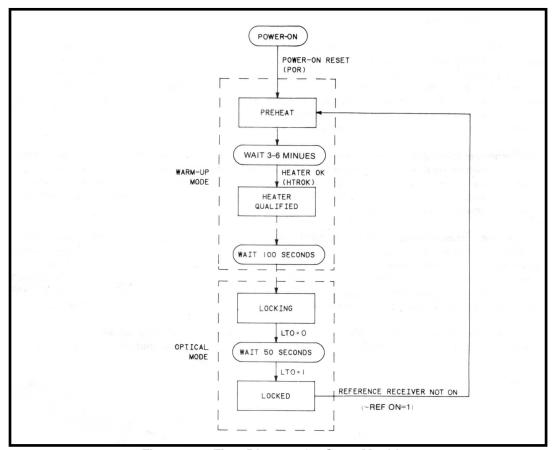


Figure 8-3. Flow Diagram for State Machine

8-31. The heater coil is used both to heat the rod and to sense its temperature. For 2.56 seconds (nominal) out of every 25.6 seconds (nominal) of the warmup cycle (see Figure 8-5), the state machine disables the power amplifier and the heater allowing the heater coil to stabilize to the rod temperature. The heater coil and a resistor in the power amplifier (A1R15) form a voltage divider. As the heater resistance increases with rising temperature, the divider voltage increases. The difference between this voltage and the reference voltage is amplified to provide the warmup mode error signal.

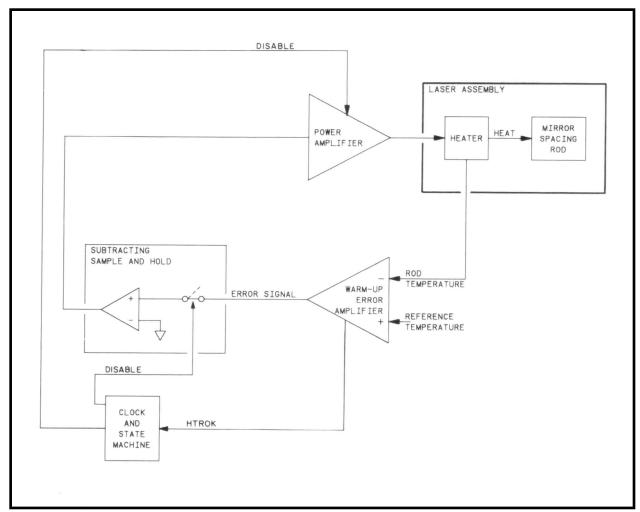


Figure 8-4. Feedback Loop during Warmup Mode

- 8-32. At the end of the 2.56 second disable period, the heater coil temperature has settled to the rod temperature. The error signal is sampled and held and the power amplifier is enabled. During the remainder of the 25.6 second period, the power amplifier, re-enabled and under control of the sampled error signal, drives the heater.
- 8-33. When the error signal gets close to zero, the warmup error amplifier sends a digital signal called HEATER OK (HTR OK) to the state machine. HTR OK is sampled by the state machine whenever the error signal is sampled. After HTR OK is sampled true, the state machine waits 100 seconds before switching to optical mode.

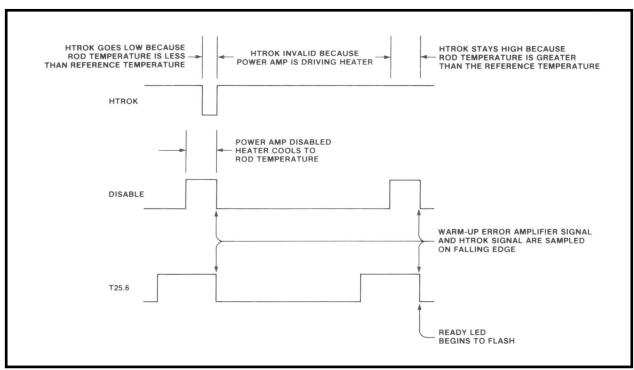


Figure 8-5. Warmup Mode Timing Diagram

8-34. Optical Mode Tuning

8-35. In optical mode, the state machine switches the subtracting sample and hold inputs from warmup feedback to optical feedback as shown in Figure 8-6. The optical mode feedback controls the laser cavity length by measuring and comparing the power of the two laser frequency components. Cavity length is controlled such that the difference in power is zero. When the difference is maintained at zero, the desired characteristics of the laser beam are established and a measurement can be performed.

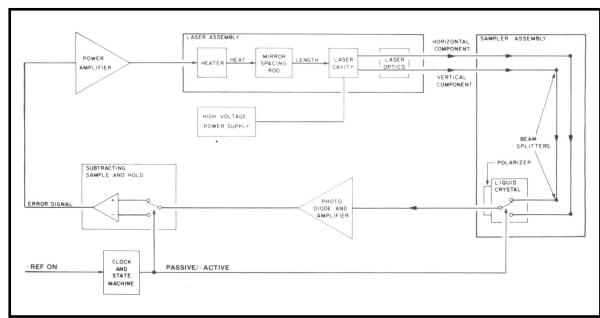


Figure 8-6. Feedback Loop During Optical Mode

8-36. The power in each laser frequency component is measured by sampling some of the laser light with a pair of non-polarizing beam splitters (see Figure 8-7) and passing one of the laser frequency components, then the other, through an optical switch and onto a photodiode. The beam splitters are part of the A6 Sampler Assembly and the photodiode is mounted on the A4 Sampler Board. A liquid crystal and a polarizer comprise the optical switch.

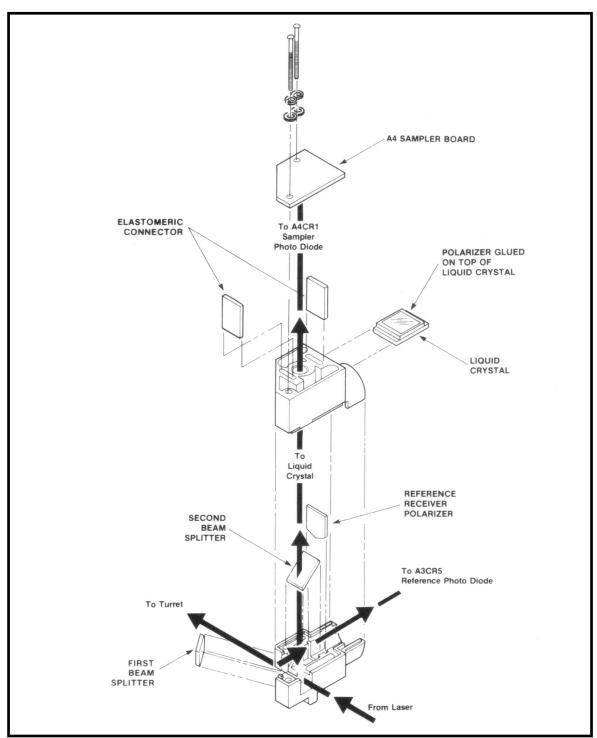


Figure 8-7. A6 Sampler Assembly, Exploded View

- 8-37. When the state machine excites the liquid crystal into its active state (see Figure 8-8), the laser beam passes through the liquid crystal unaltered. The polarizer blocks the horizontal component and passes the vertical component onto the photodiode. The photodiode current is proportional to the power in the vertical component and is amplified and converted to a voltage by the photodiode amplifier. The voltage is held on the positive input of the subtracting sample and hold circuit.
- 8-38. When the state machine places the liquid crystal in its passive state, the liquid crystal rotates the polarization of both components by 90 degrees. In this state, the polarizer blocks the vertical component and passes the horizontal component. The voltage out of the photodiode amplifier is proportional to the horizontal component and is held by the negative input of the subtracting sample and hold circuit. The error signal output of the subtracting sample and hold circuit is proportional to any difference in power between the two components.

NOTE

A TILDE (" \sim ") PRECEDING ALL SIGNALS INDICATES NEGATIVE-TRUE LOGIC.

8-39. After the optical mode tuning has stabilized; LOCKED TUNED OPTICAL (LTO) signal is held true enabling the reference frequency output. Proper laser tuning and reference receiver operation is indicated by ~REF ON true. ~REF ON false will cause the state machine to reset to the warmup mode.

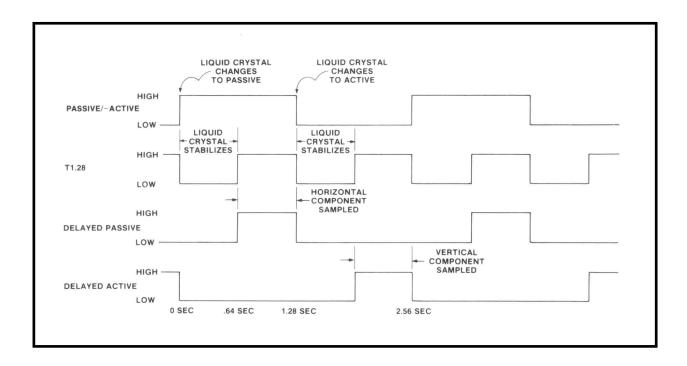


Figure 8-8. Liquid Crystal Timing Diagram (Optical Mode)

8-40. Laser Assembly Optics

8-41. The laser assembly optics ensures correct laser frequency polarizations and also collimates the laser beam. When the laser beam leaves the laser assembly, the horizontal component is polarized parallel to the base of the **HP5501B**. The vertical component is polarized perpendicular to the horizontal component. The laser beam is collimated to minimize variations in beam diameter as it travels away from the laser head.

8-42. Reference Receiver

8-43. The beam splitters of the A6 Sampler Assembly direct some of the laser light through a second 45° polarizer and onto another photodiode. Because of the polarization orientation, the beam power after this polarizer varies sinusoidally at the difference frequency of the two laser frequency components. The beam power at the difference frequency is converted to current by the photodiode and amplified to TTL levels. The frequency of the TTL output is the reference frequency. The reference receiver electronics also provide a digital signal called REFERENCE RECEIVER ON (REF ON) that tells the state machine the laser is working properly

8-44. Shutter Mechanism

8-45. The exit aperture shutter of the shutter (turret) assembly has three positions. The first blocks the laser beam entirely; the second allows a small diameter laser beam to exit for optical alignment purposes; and the third passes the entire laser beam.

8-46. ASSEMBLY/SCHEMATIC LOCATIONS OF HP5501B BLOCK DIAGRAM ELEMENTS

ELEMENT	HP5501B ASSEMBLY		
Control Electronics	A3 and A4		
Power Amplifier	A1 and A3		
Warmup Error Amplifier	A3		
Subtracting Sample & Hold	A3		
Photodiode & Amplifier	A4 and A3		
Clock and State Machine	A3		
Laser Assembly	A5		
Sampler Assembly	A6		
Reference Receiver	A3 and A6		

8-47. REAR PANEL LED INDICATORS

8-48. The diagnostic LED's, mounted on the **HP5501B**'s rear panel, provide status information on power supply input (±15 Volts), fuses, laser output and tuning, and the reference frequency output. See Figure 3-2 for a more detailed description of the LED's.

- 8-49. BUILT-IN TEST AIDS
- 8-50. Several jumpers are included to aid in testing. The RESET jumper, JMP1, places the state machine in a repetitive mode to allow signature measurements. The ~REF ON jumper, JMP2, sets the ~REF ON signal so that U17 cannot influence the state machine. LIQ CRYS jumper, JMP3, places the liquid crystal in either the active or passive state. The HTR OK jumper, JMP4, sets the HTR OK signal so that U15 cannot influence the state machine. JMP5, PHOTO DIODE, substitutes a known current for the photodiode and is used for testing the photodiode amplifier and the subtracting sample and hold circuits. JMP6, POWER AMP, supplies ±100 mV to U13 (Pin 3) to test the power amplifier. JMP7, HEATER, disables the power amplifier. The CLK FREQ, JMP8, allows the clock circuitry to generate either of the following three clock rates: NRM = 100 Hz, HI = 1000 Hz, and with the jumper removed completely =75 kHz. Test IC U9 is dummy 16-pin DIP package with no integrated circuit. All of the important digital signals connect to U9 so that a logic clip can be used for monitoring.

NOTE

There are two "LO" positions for the REF ON jumper, and two "UP" positions for the POWER AMP jumper. For proper placement, refer to the schematics for A3 when using these jumpers.

8-51. The following is a summary of the signal functions on U9:

Table 8-1. A3U9 Test IC Signal Summary

PIN	PURPOSE
1, 2, 3, 4	Timing of sample and hold during optical mode.
5,6	Timing of sample and hold during warmup mode.
7, 10	Liquid crystal drive
9	Presets digital circuitry
11, 12, 13	Indicates state of the state machine
14, 15	Inputs to the state machine

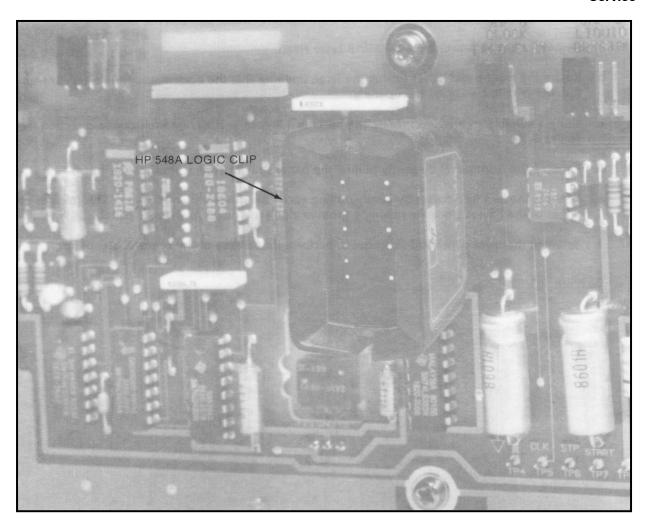


Figure 8-9. Logic Clip Monitoring of Test IC U9

8-52. ASSEMBLY REMOVAL INSTRUCTIONS

- 8-53. Figure 6-1, the exploded view diagram in <u>Section 6</u>, shows the **HP5501B** assembly locations, provides access and removal information, and gives assembly part number references.
- 8-54. Access to the assemblies within the laser head is required to troubleshoot or adjust the laser head circuits. The following paragraphs describe how to remove the laser head covers and how to remove and reinstall the major assemblies.

WARNING

HIGH VOLTAGES ARE GENERATED WITHIN THE LASER HEAD HOUSING. THE COVERS OF THE LASER HEAD CONTROL A SAFETY INTERLOCK SWITCH (A1S1) TO PREVENT ACCIDENTAL ACCESS TO THESE VOLTAGES. TO ENSURE SAFETY AND POSSIBLE EQUIPMENT DAMAGE, HOWEVER, ALWAYS DISCONNECT THE POWER SOURCE FROM THE LASER HEAD BEFORE REMOVING THE COVERS.

- 8-55. To remove the front panel and side covers from the laser head, perform the following procedure:
 - a. Remove ±15 Volt power from **HP5501B** Laser Head.
 - b. Rotate the front-panel turret so that the large opening is at the bottom and the slotted, 1/4-turn fastener is visible through the opening.
 - c. Using a suitable screwdriver, rotate the fastener 1/4-turn in the counterclockwise direction (see *Figure 8-10*).
 - d. Remove the front panel by gently pulling the panel straight away from the laser head.
 - e. Remove the two half-covers by gently pulling each cover outward and forward. This releases the edges of the covers from the retaining grooves along the edges of the rear panel.
 - f. To install the front panel and side covers, perform the reverse of the removal procedure.

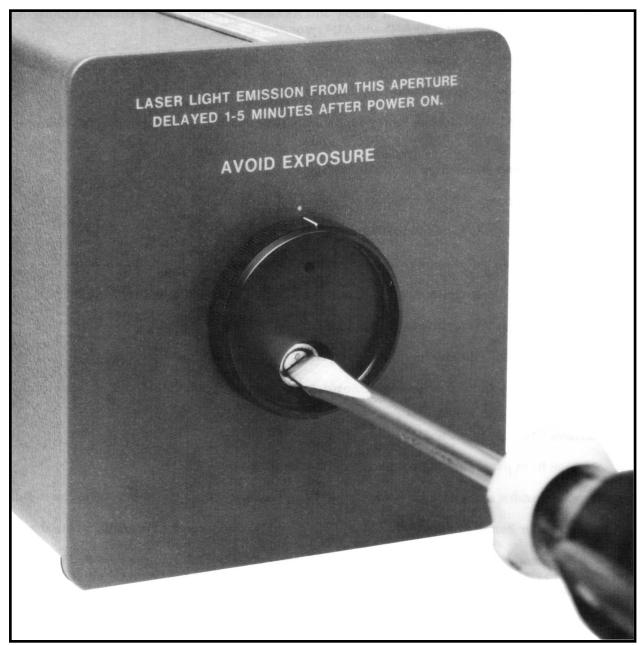


Figure 8-10. HP5501B Front Panel and Side Cover Removal

- 8-56. To remove the A1 Connector Board Assembly from the **HP5501B** chassis, perform the following procedure.
 - a. Remove ± 15 Volt power from **HP5501B** Laser Head.
 - b. Remove front panel and side covers as described in paragraph 8-55.
 - c. Remove two Pozidriv screws (H7) that secure rear panel (MP4) to laser base (MP2).
 - d. Remove four Pozidriv screws (H10) that secure A1 Connector board to rear panel assembly (MP4).
 - e. Remove A3 Reference/Controller Board Assembly as described in paragraph 8-58.

- f. Disconnect A2 High Voltage Power Supply and A5 Laser Assembly cabling from A1 Connector Board. These wires connect to A1J3 and A1J4 respectively.
- g. Remove A1 Connector Board Assembly.
- h. To install the A1 Connector board Assembly, perform the reverse of the removal procedure.
- 8-57. To remove the A2 High Voltage Power Supply from the **HP5501B** chassis, perform the following procedure.
 - a. Remove ±15 Volt power from **HP5501B** Laser Head.
 - b. Remove front panel and side covers as described in paragraph 8-55. e. Remove the A5 Laser Assembly as described in paragraph 8-60.
 - c. Disconnect A2 High Voltage Power Supply cable connector A2P1 from connector A1J3.
 - d. Remove two Pozidriv screws (H9) that fasten the A2 assembly to the laser base (MP2).
 - e. Remove A2 High Voltage Power Supply from laser head chassis.
 - f. To install the laser assembly, perform the reverse of the removal procedure.
- 8-58. To remove the A3 Reference/Controller Board Assembly from the **HP5501B** chassis, perform the following procedure.
 - a. Remove ±15 Volts from **HP5501B** Laser Head.
 - b. Remove front panel and side covers as described in paragraph 8-55.
 - Remove Pozidriv screw (H5) and flat washer (H14) that secures voltage regulator A3U7to the shield.
 - Remove four Pozidriv screws (H5) with flat washers (H14) that secures A3 assembly to the shield.
 - e. Gently extend front-panel end of A3 away from shield in order to disengage A3J2 from A4P1 and also for A3 to clear the A4 Sampler Board tab. Disengage A3J1 from A1J1 and remove A3 from **HP5501B** chassis.
 - f. To install the laser assembly, perform the reverse of the removal procedure.
- 8-59. To remove the A4 Sampler Board and/or the A6 Sampler Assembly from the **HP5501B** chassis, perform the following procedure.
 - a. Remove ± 15 Volt power from **HP5501B** Laser Head.
 - b. Remove front panel and side covers as described in paragraph 8-55.
 - c. Remove A3 Reference/Controller Board Assembly as described in paragraph 8-58.
 - d. Remove two Pozidriv screws (H2), lock washers (H12), and flat washers (H14) that fasten the A4 Sampler board and Sampler Assembly to the sampler mount (MP1).
 - e. Gently remove the A4 Sampler board and sampler assembly.
 - f. To install the A4 Sampler board and/or the sampler assembly, perform the reverse of the removal procedure.

NOTE

Sampler Mount (MP1) is adjusted at the factory to ensure that the laser beam is not truncated as it exits the laser head. Two screws (H5) secure the Sampler Mount to the shield (MP10).

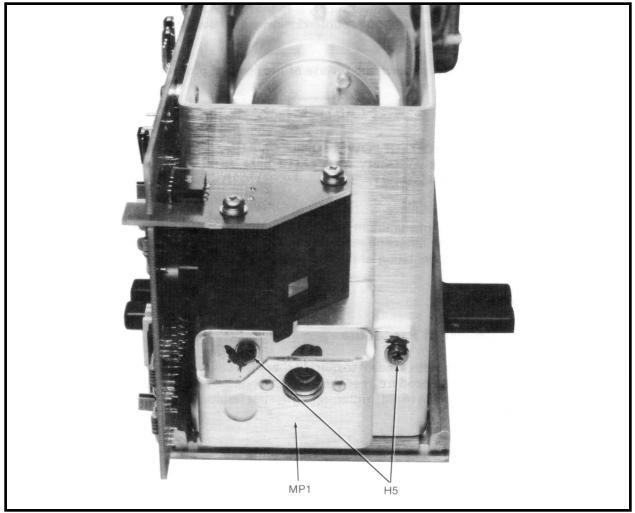


Figure 8-11. Factory-adjusted Sampler Mount (MP1)

- 8-60. To remove the A5 Laser Assembly (HP Part No. 05501-60102) from the **HP5501B** chassis, perform the following procedure.
 - a. Remove ± 15 Volt power from **HP5501B** Laser Head.
 - b. Remove front panel and side covers as described in paragraph 8-55.
 - c. Disconnect laser assembly connector A5P1 from A1J4.
 - d. Remove two Pozidriv screws (H7) that secures rear panel (MP4) to laser base (MP2).

- e. Remove four Pozidriv screws (H10) that secure A1 Connector board to rear panel assembly (MP4).
- f. With rear of laser head facing you, tilt the top edge of the A1 assembly toward you. This will give ample clearance to remove the laser assembly.
- g. Remove two Pozidriv screws (H8) from laser base. Secure the laser assembly to ensure that it doesn't move. Remove two set screws (H3), associated lock washers (H13), and flat washers (H15) using a 3.0 mm Allen wrench.
- h. Remove laser assembly from laser head chassis.
- i. Disconnect the tube's high voltage power supply lead from the A2 High Voltage Power Supply by rotating the black, knurled fastener in the counterclockwise direction; prevent the wire's rotation as you unscrew the fastener.
- j. To install the laser assembly, perform the reverse of the removal procedure.



ENSURE A2 HIGH VOLTAGE POWER SUPPLY CABLES ARE NOT PINCHED BETWEEN A5 LASER ASSEMBLY AND LASER BASE DURING REINSTALLATION OF LASER ASSEMBLY.

- 8-61. The laser assembly consists of an aluminum housing, laser tube, magnets, telescope and the quarterwave/half-wave plate assembly. The telescope expands and collimates the beam. The quarter-wave plate and half-wave plate establish the orientation of the two laser beam components.
- 8-62. TROUBLE ISOLATION
- 8-63. Quick Tuning Checkout Procedure
- 8-64. The following procedure provides a means to quickly check the entire optical tuning subsystem of the laser head. Before performing the procedure, read the information in paragraphs 8-26 through 8-39 to gain the necessary background information to aid in interpreting the test results. Figure 8-12 illustrates the effects of mirror spacing on F1 and F2.

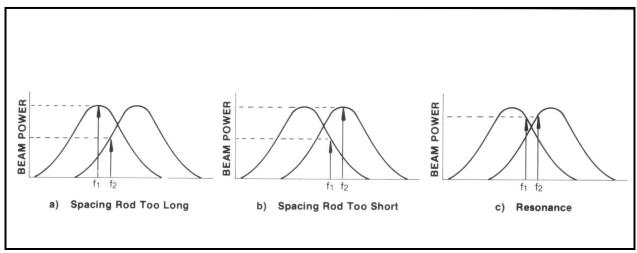


Figure 8-12. Laser Tube Tuning Characteristics

- 8-65. This procedure consists of monitoring test point TP16 on A3 with an oscilloscope to determine the relative amplitudes of F1 and F2 with the heater turned off. If the sampler, photodiode, and amplifier are functioning properly and the heater is turned off, the traces on the oscilloscope will show switching to different levels as it monitors the sampling of F1 and F2. With continued observation of the trace switching, these levels which correspond to F1 and F2 will change amplitudes since the tuning is uncontrolled.
- 8-66. To perform the quick isolation procedure, proceed as follows:
 - a. Observe the READY LED on the rear panel of the HP5501B. If after approximately 6 minutes from power-up (cold start), the LED begins flashing, you can assume that the clock, dividers, state machine, warmup and power amplifier stages are working properly.
 - b. Remove the **HP5501B** covers as described in paragraph 8-55.
 - c. Connect a dc-coupled oscilloscope to A3TP16 on A3 as shown in Figure 8-13. Also see Figure 8-24 (Component Locator) for test point locations.

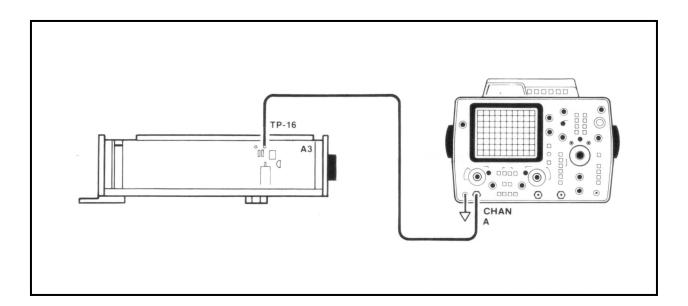


Figure 8-13. Quick Tuning Check Test Setup

- d. Enable the laser high voltage section by setting the TEST-NORMAL switch (A1S2) on A1 Connector board to TEST.
- e. On A3, change HEATER jumper, JMP 7 from NRM to OFF.
- f. Set oscilloscope controls as follows:
- g. Timebase to 2 milliseconds/division or faster.
- h. Trigger to normal. Adjust the triggering for minimum flickering of the trace.
- Vertical attenuator to 0.05V /division for X10 probe use or to 0.5V /division when using a direct probe. Set coupling to DC.
- j. To simulate a failure to observe how the waveforms at TP16 behave, move JMP 3 LIQ CRYS jumper to ACT. Note that the scope trace wanders up and down in a very smooth continuous manner with varying speed. If this occurs in step h, the liquid crystal switch or A3U11 is defective. Return JMP 3 LIQ CRYS jumper to original position.

k. If the sampler, photodiode, and amplifier are working properly, the oscilloscope display will show the trace switch between two distinct levels. See Figure 8-14 below. With continued observation these levels, which correspond to F1 and F2, will change amplitudes since the tuning is uncontrolled. The difference between the levels varies with time between a maximum difference and a minimum difference.

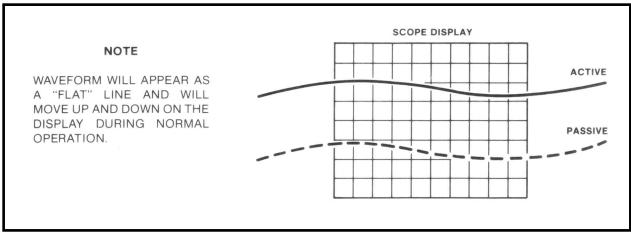


Figure 8-14. Quick Tuning Check Waveform Display

 Disconnect the test equipment and set HEATER jumper JMP7 to NRM. Set TEST-NORM switch to NORM and replace HP5501B covers.

8-67. Testing the Liquid Crystal Switch

- 8-68. The following material and test equipment is required for the test:
 - a. A white piece of cardboard.
 - b. 50 Hz Square Wave Generator (TTL Level)
 - c. Test Polarizer (HP Part Number 1000-0616)
- 8-69. To test the liquid crystal, proceed as follows:
 - a. Remove the liquid crystal from the sampler assembly as shown in Figure 8-15 below:

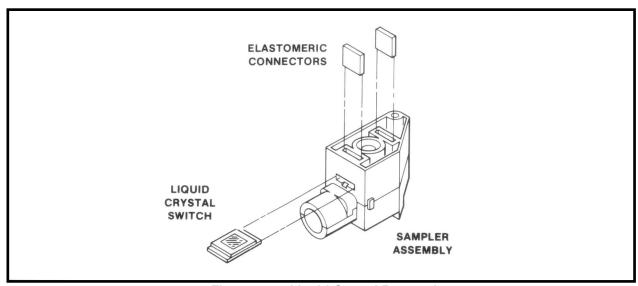
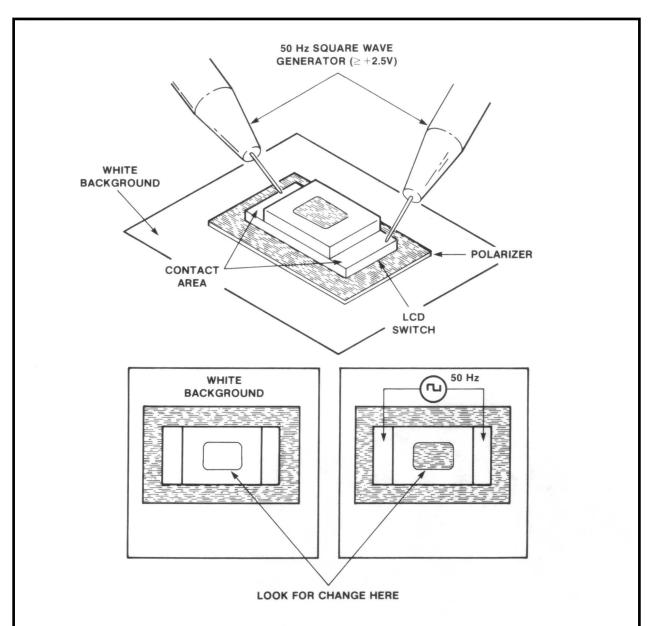


Figure 8-15. Liquid Crystal Removal



b. Place the liquid crystal in the test setup shown in Figure 8-16 below:

Figure 8-16. Liquid Crystal Test Setup

CAUTION

Do not apply DC voltages across the liquid crystal switch. Sustained dc current flow through the liquid crystal may damage the device.

c. Gently place the probes of the 50 Hz signal source on the end shoulders of the liquid crystal as shown in Figure 8-16 and observe the window area; it should go from light to dark while probing the device. A faint change of color or no change indicates a faulty liquid crystal. The replacement HP part number for the liquid crystal is 1990-0768.

8-70. HP5501B Trouble Isolation Procedures

8-71. Before **HP5501B** trouble isolation is attempted; the Laser Head Block Diagram Description (paragraphs 8-18 through 8-45) should be read. All electronic tests can be performed using an HP 5005A/B Signature Multimeter.

WARNING

WITH THE HP5501B COVERS REMOVED AND A1S2 SET TO THE TEST POSITION, VOLTAGES OF UP TO 12 KV WILL BE PRESENT AT THE OUTPUT OF THE HIGH VOLTAGE POWER SUPPLY ASSEMBLY A2.

NOTE

After servicing the HP5501B, be sure to set A1S2 to the NORM position, otherwise power will be disconnected.

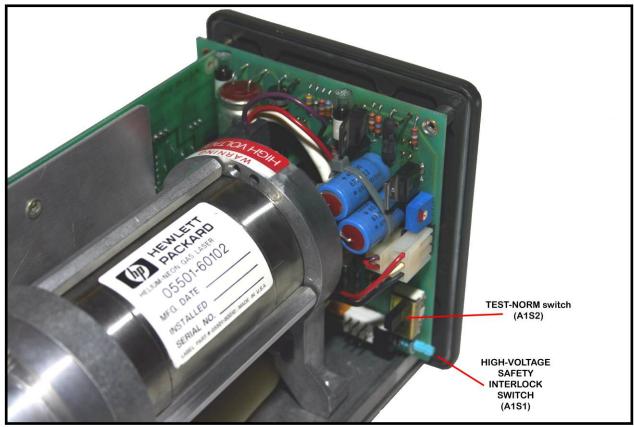


Figure 8-17. HP5501B TEST-NORM Switch A1S2

8-72. Procedure

- a. Apply power to the **HP5501B**.
- b. Wait until rear panel LED's finish sequencing (see *Table 3-1*). The LED's should reflect the following status.

+15V SUPPLY UNBALANCEOFF	+15V POWER ONON
-15V SUPPLY UNBALANCEOFF	-15V POWER ONON
+15V FUSEOFF	READYON
-15V FUSEOFF	LASER ONON

- c. If laser light is not emitted from the laser head, check that the exit shutter is open. Otherwise, see High Voltage Power Supply Troubleshooting in paragraph 8-89. Within 10 minutes of turn-on, the HP5501B's READY LED indicator should turn on continuously, and the REFerence frequency signal should have been applied to the rear panel REFERENCE SIGNAL connector. Otherwise proceed with step d of this procedure. If the failure mode occurs after the 5501B has reached the optical tuning mode (normal operation), skip steps d through k of this procedure. Steps d through k address failures that prevent the laser from reaching stable tuning.
- d. Disconnect power and remove the covers of the **HP5501B**. Set A1S2 to TEST and verify that all boards are seated correctly and all test jumpers on the A3 board are in the leftmost position (NRM).
- e. Connect power. Check the following voltages. If any are incorrect, see Power Supply Troubleshooting in A3 Troubleshooting Procedures (paragraph 8-151 or see A1 Connector Board Troubleshooting Procedures (paragraph 8-84):

WARNING

WITH A1S2 IN THE TEST POSITION, THE HP5501B HIGH VOLTAGE POWER SUPPLY IS ENABLED WHEN THE LASER HEAD IS IN OPTICAL MODE.

A3TP8: +14.7V to +15.3V

A3TP9: +4.75V to +5.25V

A3TP10: -14.7V to -15.3V

- f. Disconnect power for a few seconds, then reconnect. Observe READY LED on the **HP5501B**. Find the READY LED description in steps **g** through **j** that matches your observation and follow that step.
- g. READY LED (green) takes longer than 6 minutes to start to blink. Either the digital section is not working or the heater is not being heated properly. Check the following procedures:
 - A3 Digital Section
 - A3 Power Amplifier
 - A3 Warm-Up Error Amplifier
 - A3 Subtracting Sample and Hold

- h. READY LED (green) blinks within 6 minutes, blinks for less than approximately 150 seconds, goes off, and then repeats this action. This indicates that the warmup mode feedback is not properly controlling the heater voltage. Check the following procedures:
 - A3 Power Amplifier
 - A3 Warm-Up Error Amplifier
 - A3 Digital Section
 - A3 Subtracting Sample and Hold
- READY LED (green) blinks within 6 minutes, blinks for less than approximately 150 seconds, come on for one second (twice as long as when it is blinking) then goes off briefly. This action is then repeated. (An equivalent observation is LTO line [A3U9 (Pin 11)] comes on for 1 second every few minutes). Either the optical mode feedback is not working or the reference receiver is defective. See Quick Tuning Checkout Procedure, paragraph 8-64, and Reference Receiver Troubleshooting, paragraph 8-152.
- j. READY LED (green) blinks within 5 or 10 seconds, comes on for a few minutes after approximately 3 minutes, and then starts blinking again. Check A1/ A3 Power Amplifier section; especially A3U20 and A1Q5-9.
- k. Any other READY LED (green) observation indicates a defective digital section. See A3 Digital Section Troubleshooting, paragraph 8-138.
- I. If a REFerence frequency signal error is indicated after the laser has successfully reached normal operation (READY LED on continuously and REFerence frequency signal output) then make the following observation. Does the READY LED extinguish when the failure occurs? If so, the optical tuning may be failing or the reference receiver may be resetting the state machine due to marginal signal strength. Use the Laser Power Output Test (paragraph 4-11) as a check of the laser assembly and Quick Tuning Checkout Procedure to get an indication of the function of the optical tuning subsystem before proceeding with lower level testing. Use the Reference Receiver Troubleshooting Procedure, paragraph 8-152, to check signal level if the laser assembly and tuning circuits appear to be functioning properly. If the READY LED does not extinguish, spurious errors may be occurring on the REFerence frequency signal. Various internal and external noise or interference may be responsible. Check A3 ground connections and Vcc coupling capacitors. Check that the **HP5501B** covers are fastened securely. Marginal optical signal to the reference receiver may aggravate noise problems. Check for adequate signal according to Reference Receiver Troubleshooting, paragraph 8-152. Improper system grounding may also cause noise problems, see Section 2.

8-73. A1 CONNECTOR BOARD CIRCUIT THEORY

- 8-74. The A1 Connector Board interconnects the main laser cable, laser tube heater and power amp, laser power supply, and the A3 Controller/Reference Board. The schematic diagram for A1 is shown in Figure 8-23. Additional information covering heater power amp control circuitry can be found in paragraph 8-119.
- 8-75. Capacitors A1C1 through A1C4 serve to filter out noise on the ±15 Volt power supply lines. Capacitors A1C6 and A1C7 and inductors A1L1 and A1L2 filter current spikes created by the high voltage power supply and the switching power amplifier. Diodes A1CR1 and A1CR2 provide reverse voltage protection. Switch A1S1 is a safety interlock which removes power from the laser high voltage power supply when the **HP5501B** covers are removed. Switch A1S2 bypasses the interlock so that the laser can be serviced. A1S1 and A1S2 are wired in such a way that the interlock must be enabled before replacing the covers. A1F1 and A1F2 protect the system against laser power supply failures. A1J4 is the connector for the laser tube heater and cathode. A1DS3 and A1DS4, +15V POWER ON and -15V POWER ON LED's respectively, turn on when the power cable is connected to POWER connector A1J5. A1DS7 (LASER ON LED) lights when the high voltage supply is powered on, and A1DS8 (READY LED) lights when the **HP5501B** is ready for use. A1R12 is used to adjust laser current as per the adjustment procedures in Section 5.

8-76. High Voltage Power Supply Switch (A1Q3 and A1Q4)

- 8-77. When optical mode begins, the laser beam should be on. This is accomplished by applying the WARMUP logic line through current limiting resistor A1R10 to the base of transistor A1Q4. A1Q4 saturates which, in turn causes A1Q3 to turn on and saturate. The high voltage power supply senses ground through saturated A1Q3, thus turns on.
- 8-78. If the **HP5501B** left and right covers are placed on the unit prior to resetting the TEST-NORM switch (A1S2) to NORM; both SUPPLY UNBALANCE LED's will turn on. When power is applied, A1 transistors Q1 and Q2 sample the heater switching voltage through ac voltage divider A1R23 and A1R24. A1C5 ensures that transistor bases of A1Q2 and A1Q2 remain at "virtual" dc ground so that the unbalance circuits operate normally.

8-79. Power Distribution

8-80. When +15 Vdc and -15 Vdc are applied to the laser head, the ±15V POWER ON light-emitting diode indicator (on the A1 Connector Board) are forward biased and illuminate. The dc input potentials also produce a virtual ground level at the junction of two 14.7K Ohm resistors. This balanced condition results in an open circuit at transistors A1Q1 and A1Q2. An unbalanced condition exists when either the positive or negative dc input deviates from 15 Volts by approximately 1 Volt or more. This offset causes a corresponding forward biasing of A1Q1 or A1Q2 thus placing the anode of LED DS5 or DS6 (±15V SUPPLY UNBALANCE) at "virtual" ground potential. Table 8-2 lists the unbalanced DC voltage conditions and the resulting unbalanced indications.

Table 8-2. DC Unbalanced Failures

		UNBALANCED INDICATORS			
DC INPUT VOLTAGE	UNBALANCED CONDITION	+15V SUPPLY UNBALANCE	-15V SUPPLY UNBALANCE		
+15 Vdc	High (more positive)	ON	OFF		
	Low (less positive)	OFF	ON		
-15 Vdc	High (more negative)	OFF	ON		
	Low (less negative)	ON	OFF		

- 8-81. If either the +15 Vdc or -15 Vdc 1.5 Amp fuse opens, the difference in potential that results (across DS1 or DS2) will forward bias the associated LED indicator, turning that fuse indicator on.
- 8-82. System operating power is distributed to the laser head and other transducer units via the connector board. Safety switch A1S1 opens when the laser head covers are removed. This disconnects -15 Vdc from the high voltage power supply. As a result, this power supply becomes inoperative. The +15 Vdc input is applied to regulator A3U7 on the A3 Reference/Control Board. This regulator provides +5 Volts for use within the laser head. The +5 Volts is used to drive laser head's logic circuitry, READY LED (A1DS8), and as a reference for the high voltage power supply switch.

8-83. A1 CONNECTOR BOARD TROUBLESHOOTING

WARNING

HIGH VOLTAGE IS PRESENT ON A1J4 IF THE LASER IS ON AND THE TUBE CONNECTOR IS NOT CONNECTED TO A1J4.

8-84. Use the schematic diagram Figure 8-23, an ohmmeter, and a voltmeter to troubleshoot A1. Check to see if A1F1 is blown. Check for proper transmission of power supply voltages. Check for proper diode action across A1CR1 and A1CR2. Check A1C1 through A1C5 for shorts. Check switches A1S1 and A2S2. Check A1R3 and A1R4.

8-85. Rear Panel LED Operational Check

WARNING

MAINTENANCE DESCRIBED HEREIN IS PERFORMED WITH POWER SUPPLIED TO THE EQUIPMENT AND WITH THE PROTECTIVE COVERS REMOVED. SUCH MAINTENANCE SHOULD BE PERFORMED ONLY BY SERVICE- TRAINED PERSONNEL WHO ARE AWARE OF THE HAZARDS INVOLVED (FOR EXAMPLE, FIRE AND ELECTRIC SHOCK). WHERE MAINTENANCE CAN BE PERFORMED WITHOUT POWER APPLIED, THE POWER TO THE EQUIPMENT SHOULD BE REMOVED.

WARNING

FROM 1.2 KILOVOLTS TO 12 KILOVOLTS DC IS PRESENT ON THE ANODE OF THE LASER TUBE IN THE HP5501B. EXERCISE EXTREME CAUTION WHEN WORKING INSIDE THE INSTRUMENT. THE HIGH VOLTAGE COULD CAUSE SERIOUS PERSONAL INJURY IF CONTACTED. THE INSTRUMENT SERVICE SHOULD BE PERFORMED BY SERVICE-TRAINED PERSONNEL ONLY.

- 8-86. The following procedure can be used as an operational check of the rear panel LED's. Perform only if a problem is suspected.
 - a. Remove **HP5501B** instrument covers as described in paragraph 8-55.
 - b. Leave TEST-NORM switch (A1S2) set to NORM.
 - c. Apply power to laser head as per Figure 4-1. (Use HP 6255A Dual DC Power Supply or its equivalent.)

d. Within 10 minutes of applying power to the laser head, the rear panel LED's should reflect the following status.

+15V SUPPLY UNBALANCE ON +15V POWER ON ON -15V SUPPLY UNBALANCE ON -15V POWER ON ON

+15V FUSE OFF READY OFF or FLASHING

-15V FUSE OFF LASER ON OFF

- e. Disconnect power from laser head.
- f. Using a pair of insulated long-nose pliers, CAREFULLY remove -15 Volt fuse from A1 board. Pull fuse straight out: DO NOT TWIST.
- g. Reapply power to laser head.
- h. The rear panel LED's should reflect the following status.

+15V SUPPLY UNBALANCE	ON	+15V POWER ON	ON
-15V SUPPLY UNBALANCE	OFF	-15V POWER ON	OFF
+15V FUSE	OFF	READY	OFF
-15V FUSE	ON	LASER ON	OFF

- i. Disconnect power from laser head.
- j. Using a pair of insulated long-nose pliers, CAREFULLY return -15V fuse to its A1 board location. Remove +15V fuse. Pull fuse straight out: DO NOT TWIST.
- k. Reapply power to laser head.
- I. The rear panel LED's should reflect the following status.

```
OFF
+15V SUPPLY UNBALANCE
                            +15V POWER ON
                                            OFF
-15V SUPPLY UNBALANCE
                       ON
                            -15V POWER ON
                                            OFF
+15V FUSE
                       OFF
                            READY
                                            OFF
-15V FUSE
                       ON
                            LASER ON
                                            OFF
```

- m. Disconnect power from laser head.
- n. Replace both fuses in A1 Connector board sockets.
- o. Reapply ±15 Volts to rear panel POWER connector.
- p. Set TEST-NORM switch (A1S2) to TEST to re-enable the High Voltage Power Supply.
- q. Wait until the rear panel LED does reflect the following status.

+15V SUPPLY UNBALANCE	OFF	+15V POWER ON	ON
-15V SUPPLY UNBALANCE	OFF	-15V POWER ON	ON
+15V FUSE	OFF	READY	ON
-15V FUSE	OFF	LASER ON	ON

r. Adjust +15 Volt supply to +17 Volts.

- s. +15V SUPPLY UNBALANCE LED should turn on at a maximum of +16.6 Volts.
- t. Adjust +15 Volt supply to +13 Volts.
- u. -15V SUPPLY UNBALANCE should turn on at a maximum of +13.4 Volts.
- v. Readjust ± 15 Volt supplies to $15V \pm 0.3$ Volts.

8-87. A2 HIGH VOLTAGE POWER SUPPLY CIRCUIT THEORY

8-88. The High Voltage Power Supply (Figure 8-18) receives -15V from the system power supplies through A1F2 and A1Q3. A1R11 and A1R12 set the high voltage output current limit. The laser discharge current passes through the high-voltage connector and ballast resistor to the laser anode and from the laser cathode to A1J4 (Pin 1). The High Voltage Power Supply switch also requires the +5 Volt supply (see Figure 8-18).

WARNING

NEVER REMOVE A1J4 WITH THE HIGH VOLTAGE SUPPLY ON. DANGEROUS HIGH VOLTAGE EXISTS.

8-89. HIGH VOLTAGE POWER SUPPLY TROUBLESHOOTING

WARNING

LASER RADIATION IS ACCESSIBLE WHEN THE HP5501B COVERS ARE REMOVED AND THE TEST-NORM SWITCH A1S2 IN THE TEST POSITION.

FROM 1.2 KILOVOLTS TO 12 KILOVOLTS DC IS PRESENT ON THE ANODE OF THE LASER TUBE IN THE HP5501B. EXERCISE EXTREME CAUTION WHEN WORKING INSIDE THE INSTRUMENT. THE HIGH VOLTAGE COULD CAUSE SERIOUS PERSONAL INJURY IF CONTACTED. ANY MAINTENANCE SHOULD BE PERFORMED BY SERVICE TRAINED PERSONNEL ONLY.

- 8-90. Various conditions result from a faulty HV power supply.
 - a. No laser light is emitted.
 - Check that A1S2 is set to NORM when HP5501B covers are on or TEST when the covers are off.
 - 2. Check high voltage connectors (A1J3 and A1J4).
 - 3. Check voltage at transistor A1Q3's emitter. With High Voltage Power Supply on, this voltage should approach zero.
 - Check that A1F1 and A1F2 are OK and that the voltages are +15V and -15V respectively.
 - If rear panel LASER ON LED is on but the laser beam remains off, there is a high probability that the HVPS is defective.

- 5. Turn the power off and disconnect the high voltage connector. Carefully connect a high voltage probe, (you will need to make a jumper to extend the probe into the high voltage connector).
- 6. Turn power back on and perform an open circuit voltage test. Before performing the open circuit voltage test, wait until the laser is in optical mode. This is indicated when LED A3DS2 is on. If A3DS2 is off, check A3 logic circuitry. A3DS2 should turn off approximately 100 seconds after reapplying power. The voltage should be 10kV to 12kV. If not, replace the high voltage power supply. If the laser still doesn't work then replace the laser assembly.

WARNING

AFTER TESTING, THE POWER SUPPLY MAY TAKE UP TO 3 MINUTES FOR THE OPEN-CIRCUIT VOLTAGE TO DECAY. THEREFORE, SHORT ANODE TO GROUND IMMEDIATELY.

- b. Laser light is emitted but flashes or causes a REF Error.
 - 1. Turn power off and disconnect A1J4. Insert a 1K, 1%, 0.5 Watt resistor (Rt) between the J4 (pin 1) connector. [Leave J4 (Pin 2) disconnected].
 - 2. Connect an oscilloscope across Rt.
 - 3. Turn on power and allow the laser to warm up.
 - 4. Observe DC test voltage. It should be between 3 and 4 Volts. If not, perform the current adjustment procedure in <u>Section 5-17</u> of this manual.
 - 5. Set the oscilloscope to view the AC component and calculate the percent ripple. There should be less than 3% ripple in the test voltage. If not, replace the HV power supply. If the ballast resistor is bad, the test voltage might be an aperiodic intermittent voltage. If this is the case, replace laser tube assembly.
 - 6. Disconnect external ±15 Volt power supplies from laser head.
 - 7. Remove resistor R, and replace connector to A1J4.

NOTE

If a power supply problem seems intermittent, gently tapping the HVPS with a screwdriver will induce the problem for test purposes.

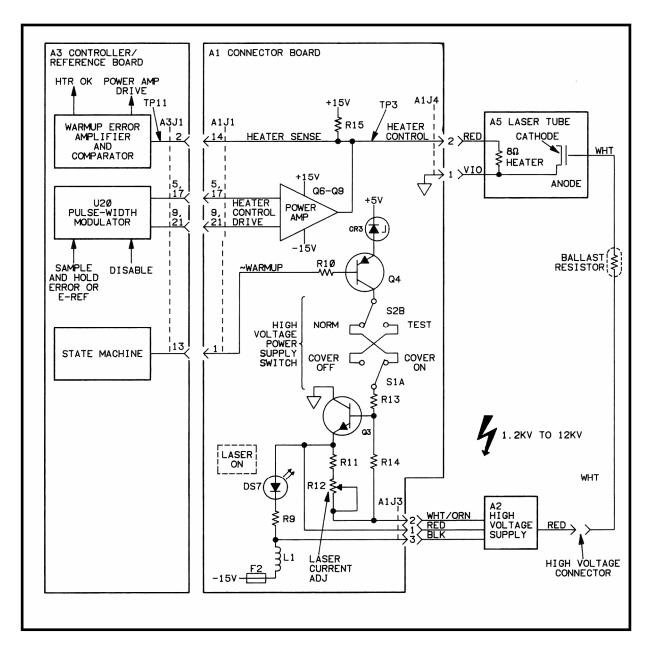


Figure 8-18. High Voltage Power Supply, Schematic Diagram

8-91. A3 CONTROLLER/REFERENCE BOARD AND A4 SAMPLER BOARD CIRCUIT THEORY

8-92. Introduction

- 8-93. Figure 8-18 (two sheets) shows the schematic diagram for the A3 Controller/Reference Board and the A4 Sampler Board.
- 8-94. The A1, A3, and A4 boards contain the electronics for the following portions of the Laser Head Block Diagram:
 - Power Amplifier
 - Warmup Error Amplifier
 - Photodiode and Amplifier
 - Liquid Crystal
 - Clock and State Machine
 - Subtracting Sample and Hold
 - Reference Receiver

8-95. Clock (A)

8-96. The frequency of oscillator U10 is determined by timing components R8, C3, C7, and C8. For normal operation, C7 gives an output frequency of approximately 100 Hz. For testing purposes capacitors C3, C7, and C8 can be configured so that the oscillator circuit generates a 1000 Hz output (JMP8 in HI position). To troubleshoot using signature analysis, the oscillator can be configured to run at 75 kHz (±20%) by removing the CLK FREQ jumper JMP8 completely.

8-97. Dividers ®

8-98. The dividers, consisting of U4A and U6, convert the 100 Hz oscillator signal into the desired periods. The first stage of the divider is U6, a dual 4-bit counter, which divides the 100 Hz by 256. The last output of U6 at Pin 8 has a period of 2.56 seconds (nominal). The output of U4A at Pin 13 has a period of 5.12 seconds while the output at Pin 9 provides a period of 25.6 seconds. These two outputs are AND'ed by U2C to produce a signal called DISABLE which is high 2.56 seconds out of every 25.6 seconds. DISABLE is used by the subtracting sample and hold circuit and the power amplifier.

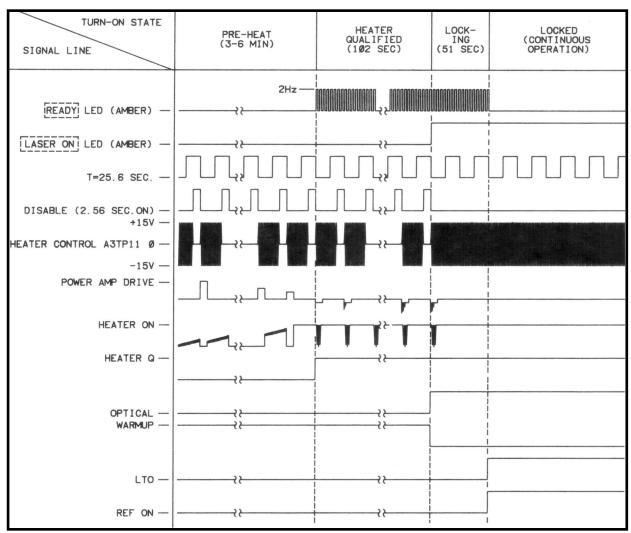


Figure 8-19. State Machine Timing Diagram

8-99. State Machine (F)

- 8-100. The state machine, consisting of U3, U4B, and U8A, determines the four states of controller operation. The warmup mode is divided into two states, preheat and heater qualified. The optical mode is divided into locking and locked states (see Figure 8-3, Flow Diagram for State Machine). The sequence from preheat to locked is described in the following paragraphs.
- 8-101. Upon power-up, the power-on reset circuit places the state machine in the preheat state and the power amplifier turns the heater full on.
- 8-102. U8A samples the HTR OK signal on the falling edge of DISABLE to allow sufficient time for the heater coil to cool to the rod temperature. See Figure 8-5, Warmup Mode Timing Diagram. When the heater temperature rises to the proper value, the HTR OK signal from U15 causes the output of U8A, HTRQ, to go high. The state machine enters the heater qualified state and the READY LED blinks approximately twice per second. The rate of blinking is determined by the output of U6B which is gated through U2A and U19C to the READY LED. Blinking continues until the state machine enters the locked state.
- 8-103. When HTRQ goes high; U4B changes states from reset to count. Unless reset by HTR OK dropping low, U4B counts for 100 seconds and then clocks U3A. This sets OPTICAL high and locks HTRQ on. The 100 second period is sufficient to stabilize the heater temperature.

8-104. When OPTICAL goes high, the state machine enters the locking state and optical feedback controls the heater. After this state has been held for 50 seconds, LTO [U1F (Pin 12)] goes high and the controller enters the locked state. If REF ON (a signal from the Reference Receiver) is low, the entire circuit will be reset by the Power-On-Reset circuit. Otherwise U1F and U19E turn on the READY indicator LED indicating that the **HP5501B** is ready for use.

8-105. Liquid Crystal ®

- 8-106. The liquid crystal, which is mounted within the A6 Sampler Assembly, connects to CMOS driver U8B via elastomeric connector strips.
- 8-107. When the PASSIVE/~ACTIVE signal at U6B (Pin 8) is high, both outputs of U8B are high, thereby placing zero potential across the liquid crystal. This is the passive state of the liquid crystal and causes the laser beam polarization to rotate by 90 degrees.
- 8-108. When PASSIVE/~ACTIVE is low, U8B produces a 50 Hz, symmetrical square wave output to configure the liquid crystal in the active state. During this state, the liquid crystal does NOT rotate the laser beam polarization.

8-109. Photodiode and Amplifier (E)

8-110. The polarizing filter, which lies between the liquid crystal and the photodiode (A1CR1), allows only one of the two orthogonal components of the laser beam to strike the photodiode. During the passive state of the liquid crystal, the polarizing filter blocks the vertical component and the photodiode current is proportional to the horizontal component. During the active state, the photodiode current is proportional to the vertical component. The output of U11D (at TP16) is the photodiode current multiplied by an effective resistance of:

8-111. Warmup Error Amplifier and Comparator ①

- 8-112. The bridge formed by A1R15 and the heater on one side, and A3R16, A3R18, and A3R19 on the other, generates an error signal on the order of 1 mV/deg C because the resistance of the heater increases with increasing temperature. The Warmup Error Amplifier, A3U14, amplifies this error.
- 8-113. The output of the HTR OK comparator, A3U15, goes high when the error voltage nears zero. The temperature at which HTR OK occurs is set by potentiometer A3R16 as described in the Reference Temperature Adjustment in Section 5. NOTE: See Section 9.1 Service Note

8-114. Subtracting Sample and Hold \oplus

- 8-115. During warmup mode, A3U2C output (DISABLE high) disables the heater (via the power amp) for 2.56 seconds out of every 25.6 seconds. During the 2.56 second disable, the heater temperature stabilizes and U12B samples the output of U14. When A3U12B opens, the sampled voltage is held on A3C13 and buffered by A3U11B. Switch A3U12C connects A3C14 and the input of A3U11C to ground.
- 8-116. During the optical mode, A3U11 0 alternately drives one of the sample and hold circuits, then the other. One sample and hold circuit (A3U12D, A3C14, and A3U11C) samples the output of A3U11D proportional to the horizontal component. The other sample and hold circuit (A3U12A, A3C13, and A3U11 B) is used for the vertical component.

8-117. The first counter (A3U6) in the divider section controls the liquid crystal and the sample and hold circuits. A sample and hold is performed once per cycle of n.28 alternating between the vertical and horizontal components [see Figure 8-8 (Optical Mode Timing Diagram)]. Thus each component is sampled once every 2.56 seconds. The liquid crystal is allowed to stabilize for 0.64 seconds before the switch to the sample and hold is closed. The hold cycle begins when the switch opens at the end of a cycle of n.28 and at the end of a half cycle of PASSIVE. The present half cycle of PASSIVE/- ACTIVE determines which component is sampled. Op-amp A3U11A computes the difference between the two sample and holds.

8-118. A1/A3 Power Amplifier ①

8-119. The output of A3U11A (from Subtracting Sample and Hold) drives the Power Amplifier section which in turn, drives the laser tube heater. The frequency response of the Power Amplifier is determined by both the input filter (A3R31, A3R27 and A3C18) and the A3U13 op-amp feedback filter (A3R32, A3R33, A3R39 and A3C20). Feedback is through A3R65B and A3C37, which integrates only the positive portion of the heater voltage. This integrated signal is proportional to heater power. A3U13 drives the input of A3U20, a switching regulator, which divides the heater power between the +15V and the -15V supplies. A3R36, A3CR7, and A3R61 form a current limiter and prevents applying a negative voltage to A3U20 (Pin 9). A3R63 and A3C38 determine the switching frequency (approximately 22 kHz or 46 microsecond period) and A3C36 controls the deadtime (off) to insure that the +15V and -15V outputs are not on at the same time. A1Q8 and A1Q6 form the positive Darlington that drives the heater to +15 Volts. A1Q9 and A1Q7 form the negative Darlington that drives the heater to -15 Volts. A1Q5 provides downshifting of negative-drive voltage level. A3U20 is disabled at Pin 10 by A3U2C when the heater error voltage is sampled during the warmup mode. The resistor networks (A3R54A, A3R54B, A3R54C, A3R65A, A3R65C, A3R65D, and A3R66) drive the output Darlington's and limit the A3U21 input voltage to +5 Volts.

NOTE

Positive and Negative Darlington-configured transistors are located on the A1 Connector board.

- 8-120. To maintain the +15V and -15V currents within maximum specified range and, because the High Voltage Power Supply (HVPS) turns on at the start of optical mode (using only the -15 Volt current supply), the maximum currents must be limited during each of the following three conditions:
 - 1. +15 Volt supply current during warmup and optical mode,
 - 2. -15 Volt supply current during warmup mode, and
 - 3. -15 Volt supply current during optical mode (-warmup mode).

The current used by each of the two Darlington's is proportional to the pulse length. The pulse begins at the fall of the positive rising sawtooth waveform (0.5V to 3.5V) at A3U20 (Pin 7) and, during the maximum current condition, is terminated when the sawtooth reaches the voltage at A3U20 (Pin 9), which is E REF at the base of Q7. A3CR8 provides temperature matching and separation between A3U13 and A3Q7when current limiting is off. E REF is the output of a multiple voltage divider network (A3R68, R69, R70, R71, R72, R73, R74) set by the open collector logic network of A3U21 which monitors the Darlington "ON" states and the warmup signal line. The voltage divider resistors are set sequentially. A3R73 and R74 are set first and limit the maximum current of the -15 Volt Darlington's during the optical mode. Next, A3R68 and R69 set the maximum current limit for the +15 Volt Darlington's during either warmup or optical mode. And last, A3R70 and R71 set the -15 Volt Darlington's to the maximum current limit during the warmup mode.

8-121. Reference Receiver (L)

NOTE

A TILDE (" \sim ") PRECEDING ALL SIGNALS INDICATES NEGATIVE-TRUE LOGIC.

- 8-122. The reference receiver consists of photodiode A3CR5, an amplifier A3U17, a transistor level shifter A3Q6, and associated passive components. The receiver amplifies and converts the sinusoidal output from A3CR5 to a square wave. When ~LTO (LOCKED TUNED OPTICAL) goes low, and the receiver amplifier has adequate signal level input, the receiver is enabled and provides a low TTL signal ~REF ON. During the warmup and locking modes, the receiver supplies no useful information and is therefore disabled (~LTO high).
- 8-123. A3CR5 is reverse biased to reduce its capacitance. The +15V bias voltage is filtered by A3R46 and A3C27. A polarizer, oriented at 45 degrees to both optical frequency components, passes optical power at the reference frequency onto A3CR5. The reference frequency is the difference in frequency between the two optical frequency components of the laser beam.
- 8-124. A3U17 contains two amplifiers. The gain of the first amplifier is set by A3R44. The gain of the second amplifier is fixed. A peak detector circuit charges A3C28 to a DC value proportional to the output of A3U17. With no current from the photodiode, the voltage on A3C28 is approximately equal to the voltage on A3C24. When photodiode current is present, the change in voltage on A3C28 is the amplitude of the signal coming out of the second amplifier. When the amplitude exceeds 100 mV, the voltage at A3U17 Pin 2 (~REF ON) drops to TTL low. A3Q6, A3CR6 and A3R45 shift the output of A3U17 to TTL levels. A3 capacitors C22, C23, C24, C26 and C29 are used for coupling and bypass. A TTL high on A3U17 Pin 11 (~LTO) gates off the reference frequency output and raises A3U17 Pin 2 to Vcc.

8-125. Line Driver (K)

8-126. A3U16 provides the necessary power to output the reference frequency signal to the system electronics. A3L3 limits the current spikes in A3U16. The special grounding and decoupling of the line drivers and receivers prevent crosstalk and oscillations.

8-127. Power-On Reset (POR) @

8-128. When power is turned on, or REF ON drops low during the locked state of the optical mode, the power-on reset circuit sets the state machine in preheat state.

8-129. Laser Head Power ©

8-130. +15V and -15V are supplied by the system power supplies via the rear panel POWER connector A1J5. The +5V is generated by A3U7. A3CR2 protects A3U7. A3C5 stabilizes A3U7 and A3C4 filters A3U7 output. Output +15V is the supply after being filtered by A3L2 and A3C11. A3L1 and A3C12 filter -15V. A3 capacitors C2, C3, C6, C16, C17, and C21 provide local decoupling of the supplies.

8-131. A4 Sampler Board

8-132. The Sampler board connects to Controller/Reference board A3. The only active component on A4 is A4CR1, a photodiode that provides a signal to U11D (Pin 13) on A3. Pads on the underside of A4 connect to the liquid crystal via elastomeric connectors which project from the A6 Sampler Assembly. Liquid crystal operation is discussed in the A3 theory section.

8-133. A3 CONTROLLER/REFERENCE BOARD TROUBLESHOOTING

- 8-134. Service for A3 is divided into the following procedures, consult paragraph 8-64, **HP5501B** Trouble Isolation to determine which procedure to use.
 - a. Digital
 - b. Photodiode and Amplifier
 - c. Liquid Crystal
 - d. Subtracting Sample and Hold
 - e. Power Amplifier
 - f. Warmup Error Amplifier
 - g. Power Supplies
 - h. Reference Receiver

8-135. Standard Troubleshooting Procedures

- 8-136. In the following tests, reference is frequently made to "localize the defective element by standard troubleshooting procedures". This consists of the following:
 - a. The test procedure places a group of IC's in a definite state and:
 - 1. Provides the correct values of the input and output signals characteristics

OR

2. Implies use of the schematic to determine the signal characteristics

OR

- 3. Simply states a suspected component
- b. When the test procedure specifies a suspected component, replace it and run the test again.
- c. When signal characteristics are known, measure the signals until a component is found that has correct inputs but erroneous outputs. Most likely this component is defective. If not, check for:
 - 1. output loading such as a board short
 - 2. shorted input on a downstream circuit

If inputs are incorrect, check for open traces and faulty outputs from previous stages.

d. If an erroneous signal comes from another board, perform the test procedure for the suspected board.

8-137. Digital Troubleshooting

- 8-138. This procedure covers the clock, dividers, power-on-reset, and state machine blocks of the A3 board. The procedure assumes that the power supplies are functioning properly. The procedure requires use of standard troubleshooting procedures which are outlined in paragraph 8-136.
- 8-139. Troubleshooting Strategy: Signature analysis is used in this section to isolate faulty digital components. Malfunctions in the clock, dividers, or power-on-reset blocks will not allow the signature analyzer to operate properly. Proper clock operation is verified first, and then an attempt at verifying the state machine using signature analysis is made. If the signature analyzer doesn't work, the dividers and resets must be repaired and then the state machine can be

CAUTION

verified.

WHEN TAKING SIGNATURES, ENSURE THAT THE TEST-NORM SWITCH (A1S2) IS SET TO NORM AND THAT HEATER TEST JUMPER IS IN THE OFF POSITION. DAMAGE TO THE HIGH VOLTAGE POWER SUPPLY OR LASER ASSEMBLY COULD RESULT IF THESE INSTRUCTIONS ARE NOT ADHERED TO.

IMPORTANT NOTE

Upon successful completion of a check, unless otherwise specified, return all test jumpers to their original position [i.e., left-most NRM position)].

- a. With power disconnected, remove front panel and side covers as described in paragraph 8-55.
- b. Do not bypass high voltage interlock. Leave TEST-NORM A1S2 set to NORM. Set HEATER JMP7 to OFF. Turn power on. Position all jumpers to the left. Measure clock frequency at TP5 (CLK). If it is 100 Hz \pm 20% go to step $\bf c$. If not, check clock section components.
- c. Remove CLK FREQ jumper completely. If clock frequency is now 75 kHz $\pm 20\%$, go to step **d**. If not, check C3 and C7.
- d. Set HTR OK to HI and ~REF ON jumper to HI. Set up signature analysis clock, start, and stop signals for falling edge detection as indicated in the lower center portion of A3. Take signatures on U9.

Pin 16 (+5 V Test Signature)	104C
Pin 2	5653
Pin 3	2333
Pin 5	3357
Pin 7	U8PU
Pin 10	F103
Pin 11	6PCP
Pin 12	0148
Pin 13	A10H

Check signature at U19 (Pin 10) = A957

If these are OK, go to step **n**.

If the signature analyzer will not take signatures, then there is a malfunction in the dividers or power on-reset sections go to step \mathbf{e} .

If the signature analyzer works, but one or more signatures are wrong, go to step f.

e. Set HTR OK to HI, REF ON to HI, and RESET to TEST. ConnectTP2, TP3, and pin X of HTR OK jumper to ground (TP1 or TP18). Verify the dividers by measuring the frequencies at the IC pins indicated in Table 8-3 and determine if they are equal to the indicated ratios, i.e. the frequency at U6 (Pin 13) should be equal to the frequency at TP5 divided by 16. Note: The counter function of the signature analyzer may not work so a dedicated counter might be needed.

Measure Frequency Frequency should If Incorrect, be equal to at faulty part is: IC Pin ratio of F (TP5/16) U6 13 U6 = or ~ 4.8 kHz F(U6 pin 13/16) U4 15 U4 or U6 or 300 Hz F(U4 pin 15/10) U4 1 U4 or \sim 30 Hz f(U4 pin 1/10) U4 7 U4 or \sim 3 Hz

Table 8-3. IC A3U4 and A3U6 Divider Check

If no problem is found, proceed to step f.

- f. Set HTR OK to HI, ~REF ON to HI, RESET to TEST. Connect TP2, TP3, and Pin "X" of HTR OK jumper to ground. (TP1 or TP18). Set up the signature analysis clock, start, and stop signals for falling edge detection. Using the signatures listed in step t; localize the defective element by using standard signature analysis troubleshooting. Begin with U9 and use the schematic to trace back faulty signals. Check U1 (Pin 6), U19 (Pin 10), and U2 (Pin 6) right away, they are critical points. If no trouble is found, go to step g.
- g. Remove ground connection on HTR OK jumper. Is U8 (Pin 6) signature 05C5? If not, U8A or R48B is faulty. If so, go to step **h** or see Warm-Up Error Amplifier Troubleshooting.
- h. Remove the ground connection on TP3 and leave off. Is the +5V signature (TP9) CP5P? If not, go to step **i**. If so go to step **k**.
- i. Set HTR OK to LO. Is U8 (Pin 5) low? If not, U8 is bad. If yes, go to j.
- j. Is TP3 high? If yes, go to k. If no, check U4B, U5D, U19D, and R5D.
- k. Remove ground connection on TP2 and leave off. Set HTR OK to HI. Is +5V signature AF7A? If yes, go to step **n**. If no, go to step **l**.
- I. Remove RESET jumper. Tie center pin to +5 V. Is TP2 high? If not, replace U1, U19, or R5. If so, go to **m**.

- m. With settings same as step I, check that U4 pins 1, 2, 9, 12, 13, and 16 are all high. If not, U4 is bad. At this point, the digital section should be OK.
- n. Set REF ON to HI, HTR OK to "X", and ALL other jumpers to left. U9 (Pin 13) (HTRQ) should be high. If not, check U8A. If so go to step **o**.
- o. Keep ~REF ON to HI, set HTR OK to LO. U9 (Pin 13) (HTRQ) should be low. If not, U8A is bad. If so, go to step **p**.
- p. Set \sim REF ON to LO. U9 (Pin 9) (POR) should be low. If not, U2B is bad. If so, go to step **q**.
- q. Turn the power off. Set ~REF ON to HI, HTR OK to HI, HEATER to NRM. Check that U9 (Pin 9) comes on then blinks at a few Hz or so at power on. If OK go to step **r**. If not, replace C1 and check CR1, R5A, R51, and R48A.
- r. Return HTR OK and ~REF ON jumpers to NRM. The READY LED should start blinking in a minute or two. If yes, go to step **s**. If no, check A1R18 and A1DS8.
- Turn power off. Set ~REF ON to HI. Set POWER AMP jumper to UP. Turn power on and S. allow the laser to run for five minutes. Observe the voltage level at U2C Pin 8 with an oscilloscope. Pin 8 will be at TTL low and will periodically go high (>2.4 Vdc) for a few seconds (approximately 2seconds). The laser head will go through the following cycle and can be monitored by observing the rear panel READY and LASER ON (or the corresponding LED's mounted on A3) and the oscilloscope display. The cycle begins with both LED's off and the voltage at U2C (Pin 8) at TTL low. The READY LED begins flashing and continues to do so for approximately 150 seconds. About 100 seconds into the cycle the laser beam and the LASER ON LED turn on. The READY LED continues to flash. After 150 seconds, the READY LED stops flashing and remains on steady. Both LED's remain on only momentarily. At this point, the DISABLE line goes high, and the laser beam and both LEDS turn off. This cycle is repetitive with the test jumpers set as they are. If the cycle occurs as described, remove power return all jumpers to their NRM position. The Digital section is OK. If Pin 8 doesn't go high, check divider and state machine circuitry. See A3 Power Amp section for additional information.
- t. Signature Analysis:

CAUTION

WHEN TAKING SIGNATURES, ENSURE THAT THE TEST-NORM SWITCH (A1S2) IS SET TO NORM AND THAT HEATER TEST JUMPER IS IN THE OFF POSITION. DAMAGE TO THE HIGH VOLTAGE POWER SUPPLY OR LASER ASSEMBLY COULD RESULT IF THESE INSTRUCTIONS ARE NOT ADHERED TO.

With the power (± 15 Vdc) disconnected, set the HP5501B switches and test jumpers as follows:

TEST-NORM = NORM, HTR OK = HI, ~REF ON =HI, RESET=TEST, CLK FREQ = Remove, HEATER = OFF; TP2, TP3, and Pin "X" of HTR OK jumper to ground.

Connect the signature analyzer (HP5005A/B) test pod leads as follows:

START = A3TP7, STOP = A3TP6, CLOCK = A3TP5, GND = A3TP4

Set signature analyzer front panel controls as follows:

CLOCK, START, and STOP Polarity set for falling edge.

Table	8-4.	Sign	ature	Table
-------	------	------	-------	-------

Pin	U1	U2	U3	U4	US	U6	U8	U9	U19
1	41A5	4UHP	CCPC	6678	4CCA	41A5	CCPC	4CCA	F9C3
2	0000	7U30	41A5	0000	FP96	0000	41 A 5	4H86	8816
3	8816	41A5	FP96	8A5F	P861	FO9F	27HH	A5P7	41A5
4	F9C3	4A39	41 A 5	0000	4UHP	CU8C	0000	4UHP	0000
5	UA4P	41A5	FP96	20H3	P861	267H	41A5	7130	4A39
6	CCPC	4A39	8U33	FP96	4H86	9CHA	UA4P	6678	3721
7	0000	0000	0000	UA4P	0000	0000	0000	7C10	0000
8	27HH	7130	3P9S	0000	41 A 5	4UHP	34FP	0000	0000
9	6678	8U33	7U30	6678	41 A 5	4CCA	7C10	UA4P	41A5
10	OP7C	6678	41A5	AOHO	41 A 5	4A39	4UHP	34FP	3721
11	4UHP	538U	20H3	88F5	A5P7	FF57	41 A 5	7U30	7U30
12	7U30	F9C3	FP96	0000	P861	0000	34FP	FP96	0000
13	3P9S	41A5	CCPC	538U	OP7C	9CHA	4UHP	41 A 5	CCPC
14	41 A 5	41A5	41A5	0000	41 A 5	41A5	41 A 5	0000	41A5
15	NC	NC	NC	4UHP	NC	NC	NC	XXXX	NC
16	NC	NC	NC	41A5	NC	NC	NC	41 A 5	NC
NC = A	NC = A3U1-3, A3U5-6, and A3U19 are 14-pin package Configuration.								

8-140. Photodiode and Amplifier Troubleshooting

- 8-141. This procedure assumes that the power supplies are functioning properly. Use a dedicated digital voltmeter, not the signature analyzer voltmeter function.
 - a. Bypass high-voltage interlock by setting A1S2 to TEST. Set HTR OK jumper to LO, PHOTO DIODE jumper to TEST, LIQ CRYS jumper to PASS. Is voltage at TP16 more negative than -4V? If no, go to step **e**. If yes, go to step **b**.
 - b. Set LIQ CRYS jumper to ACT. Is voltage at TP16 more positive than -1V? If no, go to step **e**. If yes, go to step **d**.
 - c. Verify U11 (Pin 13) is 0 V \pm 10 m V. If not, replace U11. Verify voltage atTP16 is 6/11 of that at U11 D pin 14 and voltage at junction of R20 R22 is 1/11 of that at U11D (Pin 14). If not, check A3R6, R17, R20, R22, and R24. Also U12A or U12D may be incorrectly loading this node.
 - d. Amplifier is OK. Check photodiode. Verify laser is on. Set PHOTO DIODE jumper to NRM. Measure TP16 voltage. If it is >=+0.5V then photodiode A4CR1 is good. If it is approximately -6V then either the photodiode is shorted or U11 is bad. If it is -0.5V to +0.5V go to step **e**.
 - e. Remove PHOTO DIODE jumper and check for diode action between the left hand pin of the jumper and ground. If no diode action is observed, replace A4CR1. Otherwise, not enough light is reaching the photodiode. Remove the A6 Sampler Assembly and inspect the liquid crystal, beam splitters and A4CR1 for dirt, scratches, etc. If OK, see Liquid Crystal Troubleshooting.

8-142. Liquid Crystal Troubleshooting

- 8-143. This procedure assumes the digital circuits and the photodiode and amplifier circuit are functioning properly.
 - a. Set A1S2 to TEST. Verify laser is on. Set all jumpers on A3 to left except LIQ CRYS to PASS. Insert test polarizer (HP Part Number 1000-0616) between laser assembly and sampler assembly. The bottom edge of the polarizer should be parallel to the base of the HP5501B. Measure TP16 voltage. Is it <0.2V? If yes, go to step c. If not, go to step b.</p>
 - b. Rotate polarizer 90 degrees. Is TP16 voltage <0.2V? If yes, go to step **c**. If no, go to step **f**.
 - c. Rotate polarizer 90 degrees. Is TP16 voltage >0.5V? If yes, go to step **d**. If not, go to step **f**.
 - d. Set LIQ CRYS jumper to ACT. Is TP16 voltage <0.2V? If yes, go to step **e**. If not, go to step **f**.
 - e. Rotate polarizer 90 degrees. Is TP16 voltage >0.5V? If yes, the liquid crystal is OK. If no, go to step **f**.
 - f. Liquid crystal may not be working. See paragraph 8-61, Liquid Crystal Test. Check that the elastomeric connectors are connecting A4 and liquid crystal.

NOTE

If contact problems develop, remove elastomeric connectors and clean both sets of contacts at A4 and the liquid crystal with isopropyl alcohol. Reinstall the elastomeric connectors (HP Part Number 8160-0530) in A4 Assembly.

8-144. Subtracting Sample and Hold Troubleshooting

8-145. This procedure assumes the digital circuit and photodiode and amplifier are functioning properly.

- a. Set ~REF ON jumper to LO and HTR OK to HI. Wait for READY LED to remain on. Set HTR OK to NRM. Set PHOTO DIODE jumper to TEST, and LIQ CRYS jumper to ACT. Using a dedicated DC voltmeter, check that the voltage at TP16 is -50 mV to +50 mV? If yes, go to step c. If no, go to step b.
- b. The circuitry connected to Pin 2 or Pin 15 (outputs) of U12 is incorrectly loading photodiode amp when switch U12A or U12D is closed. Check U11, C13, and C14.
- c. Is voltage at TP13 equal to voltage at TP16 within 10 mV? If no, go to step **d**. If yes, go to step **e**.
- d. Verify U12 (Pin 8) is low. Measure voltage from U11B (Pin 5) to TP13.ls it -10 mV to +10 mV? If yes, go to step i. If no, U11 B is defective or its output is incorrectly loaded.
- e. Is voltage at TP14 equal to voltage at TP16 within 10 mV? If yes, go to step **g**. If no, go to step **f**.
- f. Verify U12 (Pin 9) is low. Measure voltage from U11 C (Pin 10) to TP14. Is it -10 mV to +10 mV? If yes, go to step i. If no, U11C is defective or its output is incorrectly loaded.
- g. Set POWER AMP jumper to UP. Is voltage at TP12 between -20 mV and +20 mV? If yes, go to step i.1f no, go to step h.
- h. Verify U11A (Pin 3) voltage is about 1/2that of TP13 voltage. Verify U11A (Pin 2) voltage = U11A (Pin 3) voltage. If not, U11A, R10, R12, R14, or R15 may be bad.

- i. Place LIQ CRYS jumper to NRM. TP16 will alternate between about 0 V to about -5 V. Record these voltages (the 11 V function of the HP 5005A/B is useful here). Measure voltage atTP13. It should be the same 0 V reading as at TP16, within 20 mV. If OK, go to step k. If not, go to step j.
- j. Measure the voltage on C13. During and just after the switch (U12A) is closed (DELAYED ACTIVE signal on Test IC U9 (Pin 3)), the voltage should equal the approximate zero voltage at TP16. If it is not, or if the voltage rapidly goes to zero, then C13 is shorted or the switch U12A does not work. Also check that U12B is open and U11B is not shorting this node.
- k. Is the voltage at TP14 within 20 m V of the approximate -5V voltage at TP16. If yes, go to step **m**. If not, go to step **I**.
- I. Measure the voltage on C14. During and just after the switch (U12D) is closed (DELAYED PASSIVE signal on Test IC U9 (Pin 2)), the voltage should equal the approximate -5V at TP16. If it is not, or the voltage rapidly goes to zero, then C14 is shorted or U12D is faulty. Also check that U12C is open and U11C is not shorting this node.
- m. Set PHOTO DIODE jumper to TEST, LIQ CRYS to PASS, POWER AMP to UP. Verify TP16 voltage is approximately -5V. Measure voltage at TP14 and record as V14.
 Measure voltage at U11A (Pin 3) and record as V3. Measure voltage atTP12. Is it equal to [2 X V3] V14 within 30 mV? If yes, go to step o. If no, go to step n.
- n. Verify U11A (Pin 2) is at the same voltage as U11A pin 3.lf not, U11A or R15 bad. Also check R14, R10, and R11.
- o. This procedure thus far has shown that the Subtracting Sample and Hold circuitry works during optical mode. Next the operation during warmup is checked. *Remove* power from **HP5501B**. Move all A3 jumpers to NRM except ~REF ON to HI. Connect an ohmmeter between Pins 6 and 7 of U12B. Turn **HP5501B** on. Meter should read open-circuit when the DISABLE signal [Test IC U9 (Pin 5)] is low. Meter should read less than 250 Ohms when DISABLE is high. (The HP 5005A/B measures Ohms to ground, therefore Pin 6 or Pin 7 of U12B will have to be grounded for this test). If the result is satisfactory, go to step p. If not, U12B is defective.
- p. Connect an ohmmeter between U12 (Pin 10) and ground. Ohmmeter should read less than 250 Ohms while OPTICAL (U9, pin 12) is low. If it does, go to step q. If not, U12C is faulty.
- q. Set ~REF ON to LO, HTR OK to HI and wait for ready LED to stay on. Ohmmeter should read open. If not, U12C is bad or the node is shorted. If it reads open, the Sample and Hold is OK.

8-146. Power Amplifier Troubleshooting

- 8-147. The heart of the power amplifier is A3U20, a fixed-frequency pulse-width-modulator control unit. The IC operates at a fixed frequency set by A3R63 and C38. The outputs are used to control the amount of ±1SV current supplied to the laser assembly during the warmup and optical modes of operation. To troubleshoot the power amp, theory of operation, schematics diagrams and waveforms, and the following procedure have been provided.
 - a. Set HTR OK jumper to HI, ~REF ON to La and wait for READY LED to stay on. Set POWER AMP jumper to UP. Remove HEATER jumper. Is voltage at U13 (Pin 3) approximately 0.1V? If not, check A3R27, R31, R49, R50, R51, C18, and U13. If so, go to step b.
 - b. Within 1 minute of setting POWER AMP to UP, is voltage at A3TP11 a nonsymmetrical square wave with ±peak voltages >13 Volts? (See *Figure* 8-20.) If yes, go to step d. If not, go to step c.

NOTE

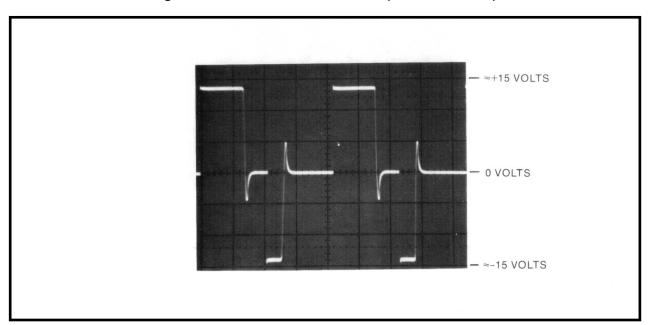
Figure 8-20 oscilloscope settings are as follows:

Time/Division: 10 microseconds/division

Volts/Division: 5 Volts/division

Coupling: DC

Figure 8-20. Test Point 11 Waveform (HEATER SENSE)



- c. Is U13 (Pin 6) > +13 Vdc? If yes, go to step j. If no, check feedback path through R6SB, C20, and R32, or replace U13.
- d. Set POWER AMP jumper to DWN. Is voltage at A3TP11 < 0.6 Vdc within 1 minute? If yes, go to step g. If no, go to step e.

- e. Is U13 (Pin 6) < -10 Vdc (i.e., more negative)? If yes, go to step I. If no, go to step f.
- f. Is U13 (Pin 3) approximately -0.1 Vdc? If yes, check R33 or U13. If no, check R49, R50, R51, and U13.
- While observing voltage at A3TP11, move POWER AMP jumper from DWN to UP. TP11 g. voltage should change from 0 Vdc to waveform of Figure 8-20. If OK, go to step h. If not, check U20 (Pins 11, 12, 13, and 14) for activity (see A3 schematic for waveforms). If waveform activity is not present, check U20 (Pins 3 and 7) for clock activity (see A3 schematic for waveforms). If waveforms and clock activity are OK, check A1 power amp transistors for (A1Q5-9) proper operation. Check E-REF input to U20 (Pin 9). Waveform should be as in Figure 8-21.

NOTE

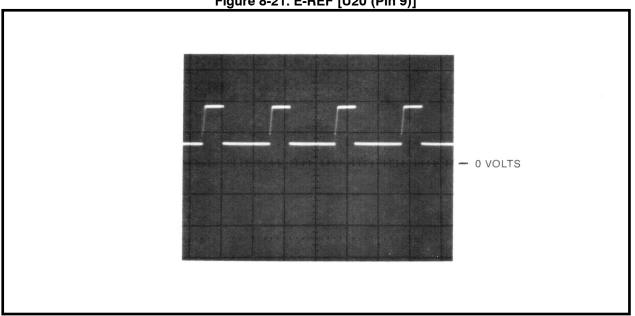
Figure 8-21 oscilloscope settings are as follows:

Time/Division: 20 microseconds/division

Volts/Division: 1 Volt division

Coupling: DC

Figure 8-21. E-REF [U20 (Pin 9)]



- h. Set HEATER jumper to OFF. This applies +5V through A1R62 to U20 (Pin 10), via the DISABLE line, disabling U20. If voltage at U20 (Pin 20) reads between 2 and 3 Vdc, go to step i. If voltage is < 2 Vdc, U20 (Pin 10) could be shorted. If U20 (pin 10) measures approximately +5 Vdc, that input is open.
- Set POWER AMP to UP, HEATER jumper to NRM. U13 (Pin 6) should read> +13 Vdc. i.

8-148. Warm-Up Error Amplifier Troubleshooting

- 8-149. This procedure assumes the power amplifier is functioning properly.
 - a. Set HEATER jumper to OFF. A3TP11 waveform (see Figure 8-20) changes to 0 Vdc. If yes, go to step b. If no, go to power amplifier servicing.
 - b. Is A3TP15 voltage +0.2 to +0.6 Vdc? If yes, go to step c. If no, A3R18, R19 or U14 is faulty.
 - c. Check A3R16 (SET TEMP potentiometer) to see if it is shorted. Short A3TP15 to TP11. Measure U14 (Pin 6). Does the voltage stabilize between -1.5 V and +1.5 Vdc? If yes, go to step d. If no, A3R21, R23 or U14 is faulty. Remove short.
 - d. Short A3TP15 to ground (TP18). Is A3U14 (Pin 6) more negative than -12 V? If yes, go to step e. If no, U14 is faulty. Remove short.
 - e. Is voltage at A3U15 (Pin 3) approximately half of U14 (Pin 6) voltage? If yes, go to step f. If no, A3R25, R26, U12 or U15 is faulty.
 - f. Is voltage at A3U15 (Pin 2) between +1.2 Vdc and +1.3 Vdc? If yes, go to step g. If no, A3R28, R29, R30 or U15 is faulty.
 - g. Is A3U15 (Pin 7) > +3 Vdc? If yes, go to step h. If no, A3R5E, R48D, U8A, or U15 is bad.
 - h. Remove TP15 short and short TP11 to ground. Is A3U14 (Pin 6) voltage> +12 Vdc? If yes, go to step i. If not, U14 is bad.
 - i. Is A3U15 (Pin 7) between 0.05 and 0.15? If yes, the warmup error amplifier is OK. If no, A3R5E, R48D, U8A or U15 is faulty.

8-150. Power Supply Troubleshooting

8-151. If the correct voltage is not observed on A3TP8, 9, or 10, typical power supply troubleshooting should be followed. +15 V, -15V, and +5V test points must meet the limits listed in Table 8-5.

 A3 Test Points
 Voltage Limits

 TP8
 +14V ± 0.3 Vdc

 TP9
 -15V ± 0.3 Vdc

 TP10
 +5V ± 0.25 Vdc

Table 8-5. Voltage Testpoints and Limits

The following are suggested points to check:

- a. External system power source.
- b. A3L 1 and A3L2 are in series with the $\pm 15V$ power supplies.
- c. There should be >200 Ohms from +15V to ground.
- d. If A1F2 blows (-15V line, 1.5A), check for open in A1R11, A1R12, or thermally caused damage to WHT/ORN wire lead to [A1J3 (Pin 2)], or excessive current being drawn by the High Voltage Power Supply. (See High Voltage Power Supply Troubleshooting in paragraph 8-89.)
- e. Power supply components are located on both A1 and A3.

8-152. Reference Receiver Troubleshooting

- a. With power removed from the HP5501B, set the REF ON jumper on A3 to LO and HTR OK to HI. Apply power to 55018. Does the READY LED eventually start blinking then remain on continuously? If no, see HP5501B Trouble Isolation Procedure, paragraph 8-72 and procedures recommended therein.
- b. Are TTL level signals present at A3U16 (Pins 1 and 3) at a frequency between 1.5 and 2.0 MHz? If so the reference receiver may be working properly. If not, trace the signal path from U17 (Pin 16), through A3Q6, to U16 (Pins 5, 6, and 7 (TP22) and check for the following:

U17 (Pin 16): 0.3 to 0.7 Volt square wave at the Reference frequency of 1.5

to 2.0 MHz.

TP22: TTL level square wave at the REFerence frequency of 1.5 to

2.0 MHz.

A5J6 Rear Panel Monitor Pins C and D with an oscilloscope. Waveforms should

Connector: be similar to those in Figure 8-22.

NOTE

Figure 8-22 oscilloscope settings are as follows:

Time/Division: 0.2 microseconds/division

Volts/Division: 2 Volts/division

Coupling: DC

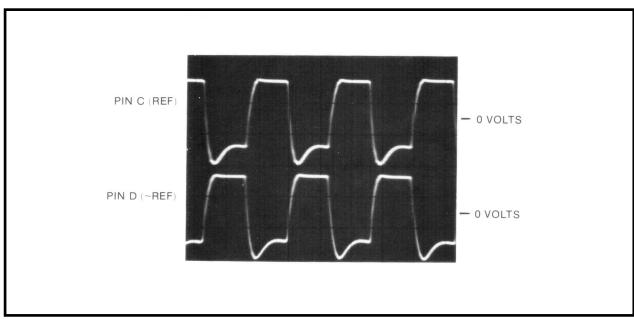


Figure 8-22. REFerence Signal Waveforms

If no activity is found, check U17 (Pin 2). If Pin 2 is at a TTL high level or changing states, then either the laser is not tuned properly, the Reference Receiver is failing or not receiving adequate signal. Verify laser tuning according to step c before continuing with step d. If U17 Pin 2 is at a TTL low level and there is no output activity as described above, then U17 may be bad or its output may be shorted. Go to step d.

- c. Align an **HP10780A** Receiver so that the laser beam is incident on the photodiode lens. If the laser is properly tuned, the LED on top of the **HP10780A** should light and the **HP10780A** should output a square wave at the REFerence frequency. This test can be performed with the laser installed using one of the axes' receivers. In this case, if the axis interferometer is installed, vibration (etc.) will modulate the REFerence frequency but a frequency in the range of 1.5 to 2.0 MHz should still be present. If a steady REFerence frequency signal is not detected by the **HP10780A** Receiver, then a laser tuning failure is indicated which is independent of the Reference Receiver. See **HP5501B** Trouble Isolation Procedure, paragraph 8-72. Otherwise proceed with step d.
- d. Measure and record the DC voltages at A3U17 (Pin 10) and the ACR5-R46 node. With ~REF ON jumper still set to la, place a piece of paper between the laser assembly and the sampler assembly to block the laser beam. The voltage at U17 (Pin 10) should drop by 250 mV or more, indicating adequate signal, and the DC voltages listed in *Table* 8-6 should be measured on the pins of A3U17 with the beam blocked:

POSSIBLE TROUBLE PIN **DC VOLTAGE** 9, 12, 14 +15V External Power Source, +5 Volt Regulator Vcc (+5 Vdc) (A3U7). **GRD** Ground 1, 15 11 TTL HIGH A3U17, A3U1F, A3U3B, or Digital Circuits A3CR5, A3U17, or associated passive components. 8 +0.7 Vdc ±0.1V 7 +4.8 Vdc ±0.1V A3C22 or A3U17 6 A3U17 or associated passive components (A3R43, +0.7 Vdc ±0.1V A3R44, A3C23 etc.). [2 mVp-p noise (nominal)] +2.3 Vdc ±0.2V A3C24 or A3U17 5 +0.8 Vdc ±0.1V 4 A3C23 or A3U17 10 +1.6 Vdc ±0.2V A3C28 or A3U17 Vcc + 0/-0.1VA3U17 3 2 V cc + 0/ -0.1VA3U17 13 <80 mVdc A3U17 +0.7 Vdc ±0.1V A3Q6 or A3U17

Table 8-6. A3U17 Reference Receiver Test Voltages

If any voltage is incorrect, check or replace the part listed.

If the voltage at Pin 10 does not drop according to the above, measure the DC voltage at the CR5-R46 node with the beam blocked. It should be approximately 15 Volts and should have increased at least 6 mV above the value measured and recorded previously when the laser beam was unblocked. If not, check R46, C27, or CR5. CR5 can be checked by removing power from the **HP5501B** and checking for diode action of CR5 using a DC ohmmeter. Resistance measured in the reverse direction should be much larger than the resistance measured in the forward direction. If CR5 is OK replace U17.

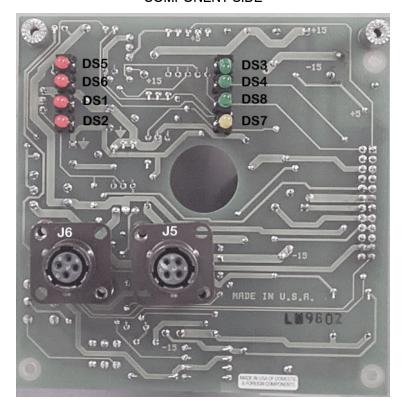
- e. In cases of marginal signal strength, the following factors should be checked:
 - Laser assembly output power
 - Sampler assembly function

The laser assembly output power should be checked according to Laser Power Output Test, paragraph 4-12.

The sampler assembly can be checked as follows:

- 1. Remove power from the **HP5501B**.
- 2. Remove A4.
- 3. Rest the test polarizer, HP Part Number 1000-0616 (supplied with the **HP5501B**), against the exposed Reference Receiver exit port of the sampler. The test polarizer will serve as a viewing screen in order to examine the laser beam which is normally incident on the Reference Receiver photodiode. Apply power to the **HP5501B**. Examine the laser beam cross section illuminating the polarizer. It should be circular and centered within a few millimeters with respect to the exit port. Slight eclipsing is normal. If any intensity variations are visible across the beam diameter they should be straight, regularly spaced lines of high and low intensity, not spots or irregular shapes. Rotate the polarizer 90 degrees and repeat the above observations. The sampler can be removed and the internal beam splitters and polarizer's examined for scratches dirt or cloudiness. Check the A3CR5 lens for scratches, dirt, or cloudiness. Also, see Liquid Crystal Troubleshooting, step **f**.

COMPONENT SIDE



CIRCUIT SIDE SERIES 2632, REV A

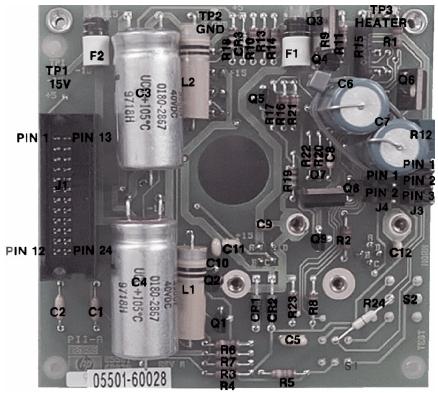


Figure 8-23. A1 Connector Board Component Locator

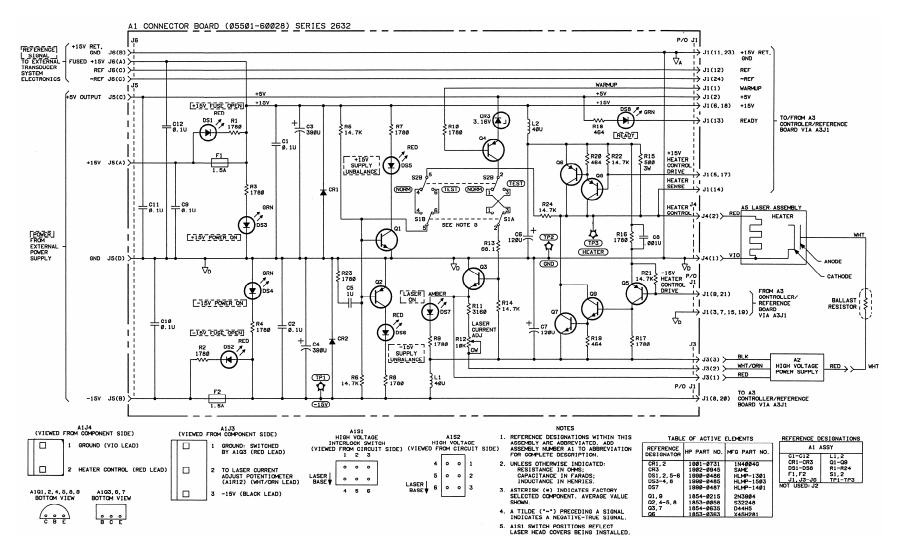
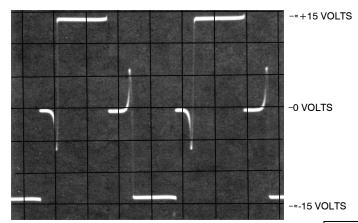


Figure 8-23. A1 Connector Board Component Schematic Diagram

A1 ↔ A3 Connections

A1J1 PIN	A3J1 PIN	DESCRIPTION	то	FROM	вьоск
1	13	Warmup	Through A1R10 to A1Q4	A3U3B(6)	Ē
2	14	+5V	Through A1R18 to A1CR3, and A1J5(C)	A3U7(3)	©
3	15	Digital Ground	5501B Circuitry	A1J5(D)	©
4	16		_		_
5	17	+15V Heater Control Drive	A1Q8	A3U20(12)	①
6	18	+15V	5501B Circuitry	A1J5(A)	©
7	19	Digital Ground	5501B Circuitry	A1J5(D)	©
8	20	-15V	5501B Circuitry	A1J5(B)	©
9	21	-15V Heater Control Drive	A1Q5	A3U20(13)	
10	22		_	<u></u>	_
11	23	+15V Signal Return Ground (Analog)	A5 Cathode, Line Driver Analog Ground	A1J6(B)	(K)
12	24	REF	Through A3C34, A3L5, to A3U16(1,2)	A1J6(C)	(K)
13	1	READY	READY LED A1DS8 and A3DS1	Flashing: A3U19(6) On Steady: A3U19(10)	Ē
14	2	HEATER SENSE	Through A3R21 to A3U14(2)	A5 Heater Control (A1TP3 or A3TP11)	J
15	3	Digital Ground	5501B Circuitry	A1J5(D)	©
16	4		_		
17	5	+15V Heater Control Drive	A1Q8	A3U20(12)	①
18	6	+15V	5501B Circuitry	A1J5(A)	©
19	7	Digital Ground	5501B Circuitry	A1J5(D)	©
20	8	-15V	5501B Circuitry	A1J5(B)	©
21	9	-15V Heater Control Drive	A1Q5	A3U20(13)	
22 23	10 11	+15V Signal Return Ground (Analog)	— A5 Cathode, Line Driver Analog Ground	A1J6(B)	<u> </u>
24	12	~REF	Through A3C32, A3L4 to A3U16(3,4)	A1J6(D)	(K)

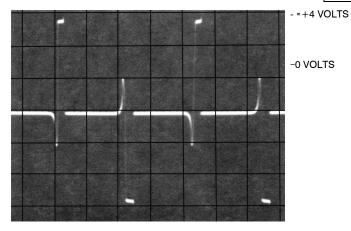
Figure 8-23. A1 ↔ A3 Connector Pin Table



① A3TP11 or A1TP3. HEATER SENSE During Warmup Mode

Oscilloscope Settings:

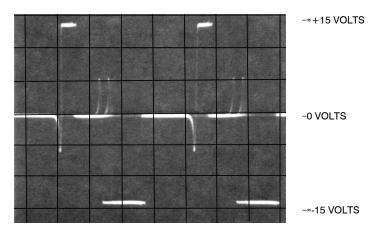
Vertical Input: 5 Volts/Division Horizontal Input: 10 µsec/Division Waveform photographs taken with all test jumpers in the NRM (leftmost) position.
10:1 Probe Attenuation not considered when establishing vertical channel input settings.



3 A3TP11 or A1TP3. HEATER SENSE During Optical (Locked) Mode

Oscilloscope Settings:

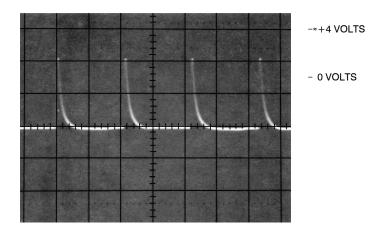
Vertical Input: 5 Volts/Division Horizontal Input: 10 µsec/Division



② A3TP11 or A1TP3. HEATER SENSE During Optical (Locking) Mode

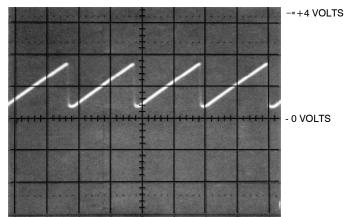
Oscilloscope Settings:

Vertical Input: 5 Volts/Division Horizontal Input: 10 µsec/Division



(4) A3U20 (Pin 3). U20's Internal Oscillator Output Waveform (~50 kHz) Oscilloscope Settings:

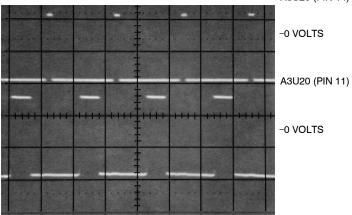
Vertical Input: 2 Volts/Division Horizontal Input: 10 µsec/Division



(5) A3U20 (Pin 7).RC Input Waveform to U20's Internal Oscillator/Logic Circuitry (~50 kHz)

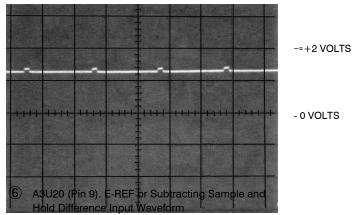
Oscilloscope Settings:

Vertical Input: 2 Volts/Division Horizontal Input: 10 µsec/Division Waveform photographs taken with all test jumpers in the NRM (leftmost) position.
10:1 Probe Attenuation not considered when establishing vertical channel input settings.



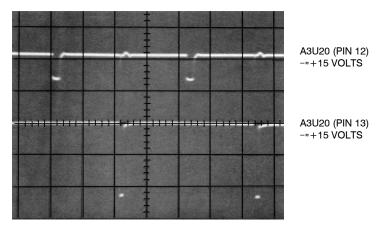
A3U20 (Pins 14 and 11). E-REF Drive Output Waveform (~25 kHz) Oscilloscope Settings:

> Vertical Input: 5 Volts/Division Horizontal Input: 20 µsec/Division



Oscilloscope Settings:

Vertical Input: 1 Volts/Division Horizontal Input: 20 µsec/Division



 A3U20 (Pins 12 and 13). ±15 Volt Heater Control Drive Output Waveform (~25 kHz) Oscilloscope Settings:

Vertical Input: 2 Volts/Division
Horizontal Input: 10 μsec/Division

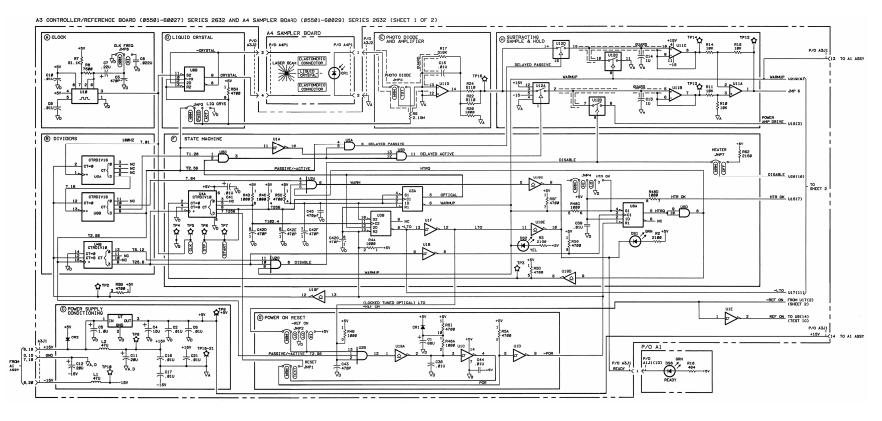
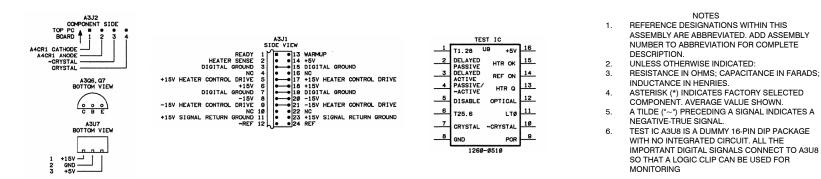


Figure 8-24. A3 Controller/Reference Board (05501-60027) and A4 Sampler Board (05501-60029) Schematic Diagram (Sheet 1 of 2)



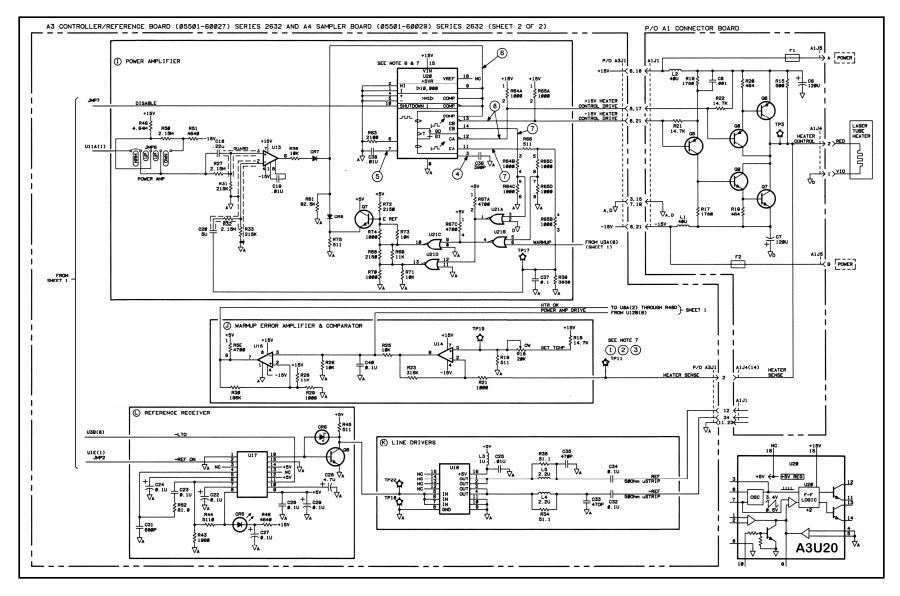


Figure 8-24. A3 Controller/Reference Board (05501-60027) and A4 Sampler Board (05501-60029) Schematic Diagram (Sheet 2 of 2)

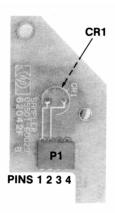


TABLE OF ACTIVE ELEMENTS

TABLE OF ACTIVE ELEMENTS				
REFERENCE DESIGNATOR	HP PART NO.	MFG PART NO.		
CR1,7-8	1901-0050	1N4150		
CR2	1901-0731	1N4004G		
CR5	1980-0770	OP913(SELECTED)		
CR6	1901-0518	SAME		
DS1	1990-0485	HLMP-1503		
DS2	1990-0487	HLMP-1401		
Q6-7	1854-0215	2N3904		
U1	1820-1416	SN74LS14N		
U2	1820-2889	SN74ALS11N		
U3,8	1820-2488	SN74ALS74AN		
U4	1820-2078	SN74LS490N		
U5	1820-2635	SN74ALS08N		
U6	1820-2096	SN74LS383N		
U7	1820-0122	7805UC		
U8	1260-0510	SAME		
U10	1820-2466	1CM7555IPA		
U11	1826-0753	MC34004BL		
U12	1826-0416	LF13331D		
U13	1826-0493	MLM308AP1		
U14	1826-0519	TL071CP		
U15	1826-0065	LM311N		
U16	1826-2668	SN75114N		
U17	1826-0775	IDA7Q		
U18	1826-3562	SN74ALS1005N		
U20	1826-0428	SG3524J		
U21	1826-1272	SN74LS33N		

Reference Designations

Holoronoc Designations			
A3 ASSY			
CI-C45	R2-8,10,11,		
CR1,2,5-8	14-36, 39,43-		
DS1,2	46,		
J1,2	48-52, 61-85		
JMP1-8	TPI-22,		
L1-5	U1-17, 19-21		
Q6,7			

NOT USED: CR3, CR4, Q1-Q5, R1, 9, 12, 13, 37, 38, 40, 41, R42, 47, 53-60, U18

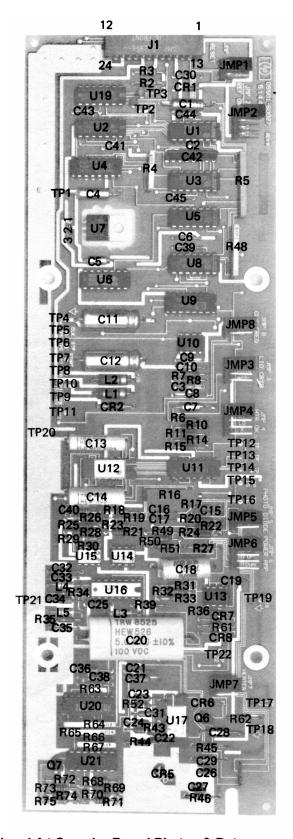


Figure 8-24 A3 Controller/Reference Board and A4 Sampler Board Photos & Data

9 SERVICE NOTES

9-1. Service Note 5501-02A July 2001

SUPERSEDES: 5501 B-02

5501B Laser Heads

Serial Numbers: OOOOAOOOO / 9999A99999

USOOOOOO / US99999999

To Be Performed By: Agilent-Qualified Personnel Situation:

In many incidences, the temperature adjustment process for the laser heads had been found being adjusted incorrectly. The result of in-correct adjustment might shorten the life of the laser tube and some other un-predictable laser head performance. This service note is important addition to the manual instructions when replacing the laser tube or the control board.

Solution / Action:

- 1. After the Laser Tube or the control board has been replaced, the heater voltage must be correctly readjusted! The adjustment is done with the pot (R16) to the right of U11 on the control board.
- 2. The adjustment must be performed when the laser tube is at room temperature, 21 to 25 degrees C (approx. 70 to 77 degrees F). If the laser High Voltage Power Supply or heater has been on, allow at least two hours with ±15 Vs off before performing this adjustment.

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION:			
MODIFICATION RECOMMENDED			
ACTION CATEGORY:	■ IMMEDIATELY■ ON SPECIFIED FAILURE■ AGREEABLE TIME	STANDARDS: LABOR 1.0 Hours	
LOCATION CATEGORY:	☐ CUSTOMER INSTALLABLE☐ ON-SITE☐ SERVICE CENTER	SERVICE RETURN USED RETURN PARTS: SCRAP SEE TEXT	
AVAILABILITY:	PRODUCT'S SUPPORT LIFE	AGILENT RESPONSIBLE UNTIL: July 2002	
AUTHOR: EL	ENTITY: 0200	ADDITIONAL INFORMATION:	

- 3. To make sure that the tube does not begin heating perform the following with the laser head "OFF":
 - a. On A3, the control board, change the HEATER jumper, JMP7, from NRM to OFF.
 - b. ON A1, connector board, UNPLUG J3, the Hi Voltage Power Supply.
- 4. Turn "ON" the laser head and measure the Voltage on Test Pin 11 (A3TP11). It should be between .2 and .3 volts.

NOTE:

The measurement should be done immediately after the head is turned on

- 5. Calculate the heater adjust set point using the following equation: Vset = 1.285 X V(A3TP11) + 0.005 Volts
- 6. Measure A3TP15 and adjust A3R16 until it equals Vset to \pm 1 millivolt.
- 7. Turn off the laser head. Move the HEATER jumper from OFF to NRM and PLUG J3, the HV Power Supply back onto it's connector on A1.
- 8. Turn on the laser head again and wait until it locks.

NOTE:

If the laser does not lock, wait for two hours and repeat Step 1 - 5 using following equation: Vset = 1.285 X V(A3TP11) + 0.01 Volts then repeat Step 6 - 8.

Measure A3TP11. It should be between 5 and 7.5 Volts! Leave the head on for another half an hour and measure A3TP11 again. The voltage will have decreased, but it should still be between 5 and 7.5 Volts!